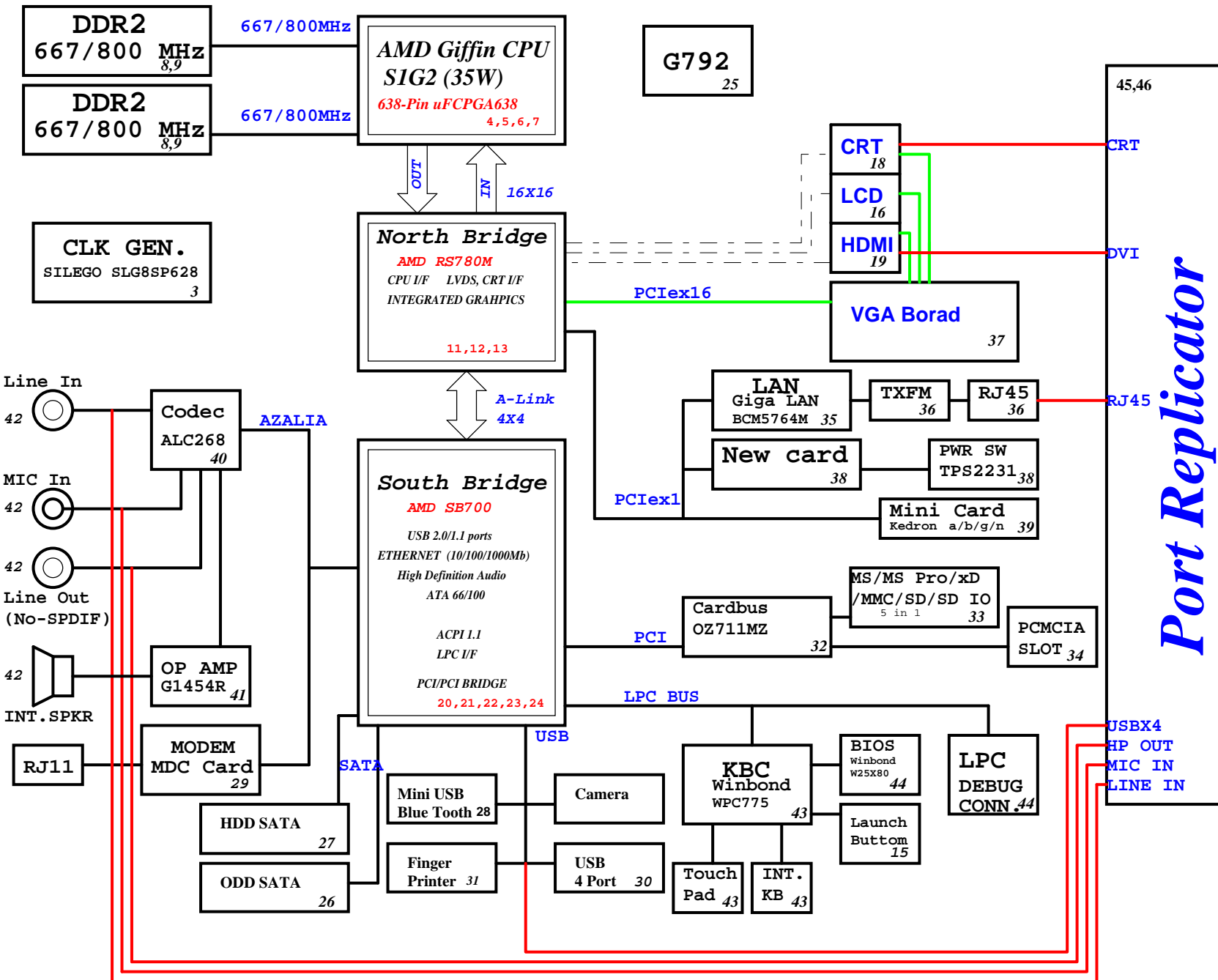


# Olan (TM15") Block Diagram

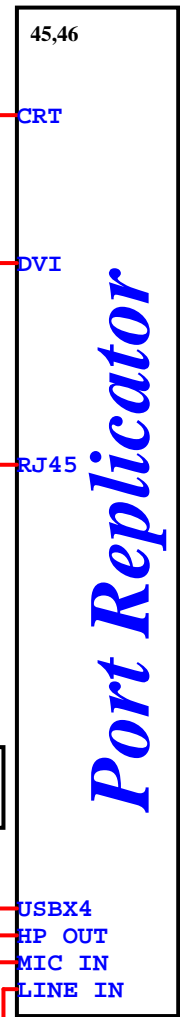
Project code: 91.4Z701.001  
 PCB P/N : 48.4Z701.001  
 REVISION : 07249-1



PCB STACKUP

TOP	---
VCC	---
S	---
S	---
GND	---
BOTTOM	---

<b>SYSTEM DC/DC TPS51125 51</b>	
INPUTS	OUTPUTS
DCBATOUT	5V_S5(7A) 3D3V_S5(7A)
<b>SYSTEM DC/DC TPS51124 52</b>	
INPUTS	OUTPUTS
DCBATOUT	1D1V_S0(9A) 1D2V_S0(5A)
<b>SYSTEM DC/DC TPS51117 53</b>	
INPUTS	OUTPUTS
DCBATOUT	1D8V_S3(10A)
<b>RT9026PFP 54</b>	
5V_S5	DDR_VREF_S3 0D9V_S3
<b>RT9166 54</b>	
3D3V_S0	2D5V_S0 (300mA)
<b>G957 54</b>	
3D3V_S0	1D5V_S0 (1A)
<b>G9161 54</b>	
3D3V_S5	1D2V_S5 (400mA)
<b>CHARGER BQ24745 55</b>	
INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V 6.0A UP+5V 5V 100mA
<b>CPU DC/DC ISL6265HR 50</b>	
INPUTS	OUTPUTS
DCBATOUT	VCC_CORE_S0_0 0~1.55V 18A
	VCC_CORE_S0_1 0~1.55V 18A
	VDDNB 0~1.55V 18A
	VDDNB 0~1.55V 18A



6. Page 18: 'F3' change to 'FUSE\_IAGV-2-GP'  
7. Page 30: 'USBCN1' change to '20.F0765.020'  
8. Page 26: ODD connector 'SKT1' change to '62.10065.291'  
9. Page 40: Add analog MIC schematic.  
10. Page 46: Add 'RN65' for NO duck LAN LED  
11. Page All: Close PWR GP  
12. Page 03: Update 'D18' foot print  
13. Page 57: Add test point under Dimm Door  
14. Page 55: 'R32' pull hi from '3D3V\_AUX\_S5' to 'BQ24745\_VREF'  
15. Page 41: Change audio AMP to G1454R41  
16. Page 55: Change C34 size from 0402 to 0603  
17. Page 57: Add EMI capacitor follow EMI recommend  
18. Page 22: Add E-SATA schematic  
=====

2007/12/20  
1. Page 12: 'R109' change to '768R2F-1-GP'  
2. Page 46: Remove 'R119' 'R21' 'R22' 'RN53' 'RN54' 'RN55' 'RN56'  
3. Page 46: connect U12 HDMI switch to PEG\_TX  
4. Page 51: Modify 5V & 3D3V 51125\_ENTPI1 & 51125\_ENTPI2 schematic.  
5. Page 06: PH 300 ohm on 'CPU\_DBREQ#'; PL 300 ohm on 'CPU\_TEST1' & 'CPU\_TEST24'  
6. Page 12: PH 'SUS\_STAT#' 10K ohm to 3D3V\_S0  
7. Page 45: Add 'DOCK1' PIN 51 'CRT\_DBREQ'  
8. Page 46: Modify HDMI switch to 'PS8122QFN48G-GP'  
=====

2007/12/25  
1. Page 46: Connect '3D3V\_S0' to U12 remove '3D3V\_S0\_PI'  
2. Page 45: Add 'R497' 'R498' 'R499' for D18 CRT switch  
3. Page 46: Add Pi filter before dock & C818 C819 for VSYNC\_5 and HSYNC\_5  
4. Page 37: Add 'R618' PU for 'AC/BAT\_DET'  
=====

2007/12/26  
1. Page 21: Swap USB port 8 and Port 10.  
2. Page 45: Follow net swap report.  
3. Page 41: Add 'R633' DY PL '1451\_SD'  
4. Page 46: RN19-RN23, RN42-RN45 & RN65 change to SRN0J-10-GP  
5. Page 43: Add R634 ,U17 pin120 connect 'SPI\_WP\_R#'  
6. Page 30: Follow Homa modify 'USBCN1'  
=====

2007/12/27  
1. Page 11: NEW CARD PCIE channel change to channel 3.  
2. Page 21: 'DOCK\_DT1#' change to 'GEVENT7#' and DY 0 ohm resistor  
3. Page 37: Add 'R618' PU for 'AC/BAT\_DET' on MXM pin 157, Connect MXM SMB with 'RN53'  
4. Page 45: Add Pi filter before dock  
5. Page 18: change R113, R114, R106 and R99 to 33ohm. change C471, C468 and C466 to 2.2pf.  
6. Page 43: Change R186 to 150ohm for FLT\_RST1#\_1 (KBC U20A)  
7. Page 35: Change C86 to 150pf LAN\_RST (LAN U8 )  
8. Page 32: Change C631 to 150pf P1T\_RST1#\_MMX (U58 OZ711)  
9. Page 37: Change C510 to 330pf for P1T\_RST1#\_MMX (MMX)  
10. Page 33: Add C650 to 220pf for PCIRST1# (CR U67)  
11. Page 38: Add C639 to 220pf for NEW\_RST# (NEW U66)  
12. Page 43: R181 change to 30KF for BOM integrate  
13. Page 39: Change R226 to 470ohm for MINI\_RST# (MINI MINIC1)  
14. Page 12: Add 330pf C551 between R313 and ground for SYSREST# (NB U43C).  
15. Page 40: Change C379 to 56pf for RSSE# (AUDIO U24)  
16. Page 06: Change R298 to 330hm for LDT\_RST#\_CPU  
17. Page 45: Change RN4 connect to 'CRT\_R\_S' 'CRT\_G\_S' 'CRT\_B\_S'  
18. Page 24: Change R89 to 10R2J-2-GP for BOM integrate  
19. Page 46: Follow net swap report.  
20. Page 57: Add Spring 'GND1' 'GND2'.  
=====

2007/12/28  
1. Page 57: Add EMI capacitor follow EMI recommend.  
2. Page 45: Add EC191 EC192 EC193 follow EMI recommend.  
=====

2007/12/28a  
1. Page 40: Codec IC change to ALC268.  
2. Page 41: Add U69 G1412 AMP for Line out.  
3. Page 33: Add EMI capacitor Follow EMI recommend  
=====

2007/12/31  
1. Page 22: Change PlanarID to SB and ADD CLK\_ID to identify Clock Gen.  
2. Page 42: Modify 'INTMIC1' to MONO MIC  
3. Page 40: Modify ALC\_268 to MONO MIC schematic, Add 'DOCK\_DT1#' on 'GPI01'  
=====

2008/01/02  
1. Page 40: Change Speaker and Line-out channel.  
2. Page 40: Change 'DOCK\_DT1#' connect to GPIO3 U24 pin 3.  
3. Page 40: Modify 'MIC' and 'Line\_in' schematic.  
4. Page 30: Modify 'USBCN1' schematic follow Homa.  
5. Page 43: Add 'R654' 10K PU 3D3V\_S0 for 'FP\_DETECT#'.  
6. Page 21: Add 'R200' 10K PU 3D3V\_S0 for 'FP\_ID'  
7. Page 51: Add 'R549' 0 ohm for 'MXM\_THER#'.  
8. Page 40: Change R196 to 64.39225.6DL 39.2K.  
9. Page 21: Remove 'R397' 'R489' 'R490' 'R491', add 'RN56' for component count.  
=====

2008/01/03  
1. Page 50: Change C4 to SC1U10V3XK-3GP for BOM integrate  
2. Page 55: Change C296 form SC1U25V0KX-1GP (P/N 78.10522.21L) to SC1U25V0KX-GP (P/N 78.10522.5BL)  
3. Page 43: Remove 'R188' 'R177' 'R185' 'R189', add 'RN56' for component count.  
4. Page 46: Swap IL2 Pin 29 & Pin 28; add C394, C395 D01u.  
5. Page 22: Add U41 E-STAT solution  
6. Page 21: Add R326 for NB\_PWRGD  
7. Page 48: Add R498 for NB\_PWRGD  
=====

2008/01/03a  
1. Page 46: Modify SM BUS PH resistor  
2. Page 40: Add 'R119' and 'R177' for ALC268 GPI01  
=====

2008/01/04  
1. Page 22: Swap RN68 net  
=====

2008/01/04a  
1. Page 57: Remove H23; H24.  
2. Page 06: Remove R300, R301, change to 'RN71'  
=====

2008/01/07  
1. Page All: Follow Net swap report.  
=====

2008/01/07a  
1. Page 22: Swap U41 Pin 3, 4 & Pin 17, 18.  
=====

2008/01/07b  
1. Page 57: Add H23 screw holl.  
=====

2008/01/07c  
1. Page All: Follow Net swap report.  
=====

2008/02/01  
1. Page 45: Change 'DOCK1' to 20.F1257.001.  
=====

2008/02/04  
1. Page 40: Add R327, R328, EC200, EC201 for EMI solution.  
=====

2008/02/05  
1. Page 22: Add R397 follow caystall FAE recommend.  
2. Page All: Short 0 ohm resistor with PAD.  
3. Page 18: Remove 'D2' 'D3' 'D4' for ME & Layout  
=====

2008/02/13  
1. Page 41 & 42: Modify Line-out jack connection.  
=====

2008/02/13a  
1. Page 06: Follow AMD recommend Add & Dummy 'R503' to PU 'CPU\_LDT\_REQ#'.  
=====

2008/02/13b  
1. Page 06: Change 'R503' to 'R304' to PU 'ALLOW\_LDTSTOP'.  
2. Page 06 & 12: Remove net 'CPU\_LDT\_REQ#' Replace with 'ALLOW\_LDTSTOP'  
3. Page 21: Add 'R134' & 'R185' for 'HDMI' on SB700 'GP200'.  
4. Page 42: Change 'C400' 'C401' to 'R301' & 'R218'  
=====

2008/03/03  
page3, remove RN31 (control by SW)  
page12,merge R105,R107 to RN29  
merge R309,R310,R311 to RN72 (R309 can use 3K)  
page14 merge R477,R476 to RN73  
page16 RMI change to 2 pos 0ohm PAD 'R476' 'R477'  
merge R29,R30 to RN53  
1. Page 28: Merge R106,R99 to RN75  
merge R113,R114 to RN74  
merge R283,R284 to RN30  
merge R275,R276 to RN32  
merge R319,R38 to RN31  
page20 change R165,R164,R404,R403 to 0 ohm PAD (only use for strap,don't need 22 ohm)  
page21 merge R170,R159 to RN34  
merge R162,R160 to RN33  
R185 for Dock(input can't floating)  
page22 Short R14,R13  
C672,C671,C673,C674 for E-SATA use,need add DIS  
check with SW to remove CLK\_ID setting(use SMBUS)  
dummy all E-SATA re-driver  
change RN67,RN68 to PAD  
page24 Merge R319,R311 to RN35  
merge R344,R355 to RN36  
del R360,R366,merge R361,R365 to RN37  
page35 change R265,R263,R67,R87,R72,R269,R270,R79,R260,R58,R54,R56,R38,R44,R42,R46,R74,R83 To 0ohm PAD  
page37 change r456 to PAD  
page39 check R224/R225,R222/R229, need confirm spec  
=====

page40 check R327,R328 with EMI  
change RN55,R325 to PAD  
Modify schematic for current leakage on 'DOCK\_DT1#'  
R119 for Dock (input can't floating)  
page42 merge R217,R220 to RN55  
merge R214,R215 to RN67  
merge R475,R479 to RN76 (need change to 48 ohm)  
page44 change ER1, ER2,ER4 to PAD  
dummy EC69  
change ER3 to 33 ohm  
page47 change R316 to PAD  
page48 level shift for NB\_PWRGD  
page50 change R12,R13,R14,R3,R4,R7 to PAD  
page53 change R261 to PAD  
page54 change R317,R18 to PAD  
page55 change R148,R147,R132,R131 to PAD  
merge R28,R32,R31,R37 to RN77 (please take care R32 power)  
=====

2008/03/04  
1. Page 26: Modify 'SKT1' ODD connector.  
2. Page 45: Merge 'R292' 'R293' to 'RN68'.  
3. Page 51: change R416,R441 to PAD for noise issue.  
4. Page 16: 'F2' change to '69.50007.A31'.  
=====

2008/03/04b  
1. Page 51: change R416,R442 to PAD and DY 'R441' for noise issue.  
2. Page 17: 'LED3' change to '3D3V\_S5' 'LED2' change to '3D3V\_AUX\_S5'.  
3. Page 30: Modify 'USBCN1' pin define.  
4. Page 40: Remove 'C377' 'C379' short them  
5. Page 40: Remove 'R177' for new INTMIC connector  
6. Page 42: Modify 'INTMIC' schematic.  
7. Page 45: Merge R497, R498, R499 to RN68; R287, R286, R289 to RN78.  
8. Page 16: Add RN79 for ESD.  
9. Page 45: 'DOCK1' 'PIN S51' change to 'CRT\_IN#\_R' for ESD.  
10. Page 45: Add 'RN80' for ESD  
11. Page 56: Add 'D30' on 'BAT\_IN#' for ESD, Change 'RN59' to 8P4R for 'BAT\_IN#' ESD  
=====

2008/03/05  
1. Page 32: Add 'R220' and Dummy for 'PME' issue.  
2. Page 39: Change '3D3V\_S5\_MINI1' to '3D3V\_S5' and Change '3D3V\_S0\_MINI' to '3D3V\_S5'.  
3. Page 17: Merge 'R485' 'R486' to 'RN81'; Merge 'R487' 'R488' to 'RN82'.  
4. Page 17: Change 'R473' to '453R2F-1-GP'; Change 'R480' to '150R2F-1-GP'.  
5. Page 14: Merge 'R179' 'R180' to 'RN83'.  
6. Page All: Follow Swap report.  
=====

2008/03/06  
1. Page 30: 'USBCN1' pin 15 change to GND.  
2. Page 22: Remove 'U41' relative schematic.  
3. Page 40: 'RN41' change to 4P2R  
4. Page 42: Merge 'R474' 'R475' to 'RN84'.  
5. Page 42: Change 'EC6' 'EC7' 'EC8' 'E29' to 0603  
6. Page 40: Change 'EC200' 'EC201' to 0603  
7. Page 38: 'U66' change to 74.00577.A73  
8. Page 57: ADD EMI capacitor 'EC203' ~ 'EC220'.  
9. Page 40: Merge 'R329' 'R330' 'R325' to 'RN85' for ESD.  
10. Page 42: Short 'RN67' with PAD  
=====

2008/03/06a  
1. Page 51: Change 'TC17' 'TC10' to 77.21561.00L & mount.  
2. Page 50: Change 'C7' 'C8' to 77.21561.00L & mount.  
3. Page 52: Change 'TC19' to 79.1010.105.  
4. Page 55: Add 'C826' for Vendor suggest add decoupling capacitor in CSSN to ground.  
=====

2008/03/07  
1. Page 55: Change 'D9' to 83.R0203.08F & mount.  
2. Page 57: Add Spring 'GND5 and EMI capacitor 'EC221' ~ 'EC229'.  
=====

2008/03/10  
1. Page 57: Add 'GND11' for EMI, 'GND8' 'GND9' 'GND10' change to '34.15F09.001'.  
2. Page 52: Change 'TC21' to SE100U25VM-L1-GP.  
3. Page All: Follow Swap net.  
=====

2008/03/10a  
1. Page 55: Change 'TC21' to SE100U25VM-L1-GP.  
2. Page 57: Remove 'GND6' 'GND7'.  
=====

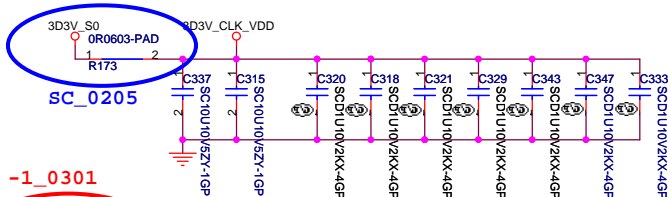
2008/03/11  
1. Page 57: Remove 'EC204' 'EC205'.  
=====

2008/03/11a  
1. Page 40: 'R194' change to '51R2J-2-GP'.  
2. Page 29: 'R235' change to '15R2J-GP' & DY 'C424'.  
3. Page 21: Change 'RN33' to 'R655' & 'R656' with '27R2J-1-GP'; Change 'RN34' to 'SRN470-7-GP'; UNdummy 'EC61'  
4. Page 48: Add 'U70' for 'NB\_PWRGD' level shift.  
=====

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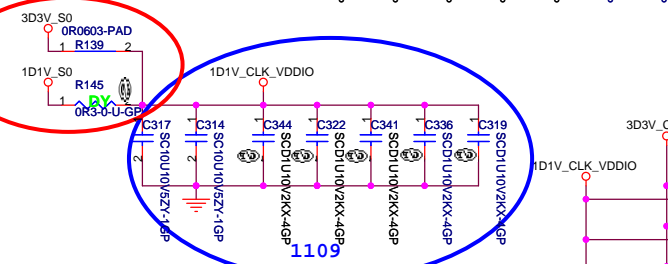
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Date	Friday, April 18, 2008	Sheet 2 of 58

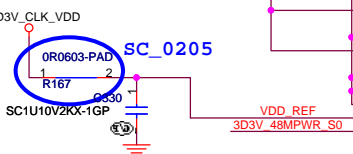


SC\_0205

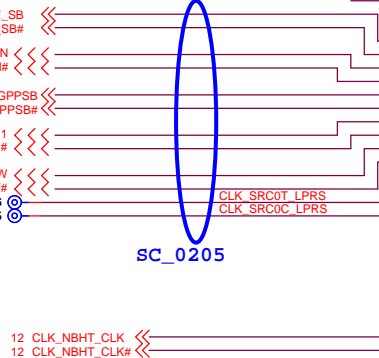
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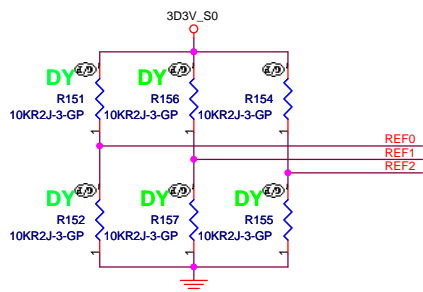
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SC\_0205



SC\_0205



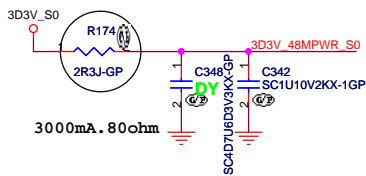
SEL_SATA	1	100 MHz non-spreading differential SRC clock
REF1	0*	100 MHz spreading differential SRC clock
SEL_HTT66	1	66 MHz 3.3V single ended HTT clock
REF0	0*	100 MHz differential HTT clock

\* default

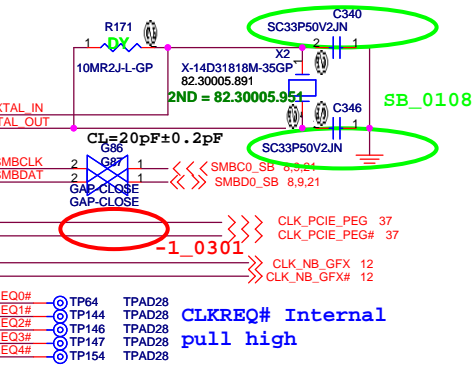
CPU\_CLK (200MHz)



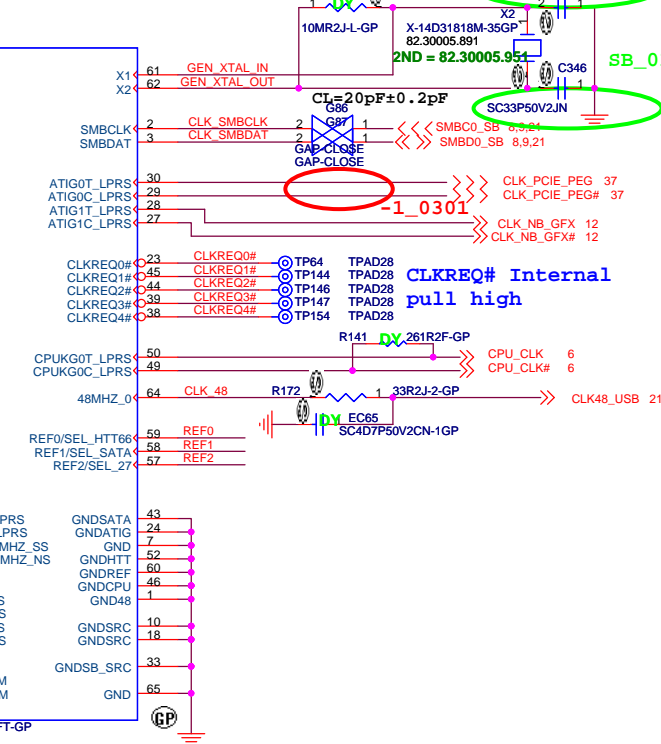
OSC\_14M\_NB  
RS780M 1.1V 158R/90.9F



3000mA.80ohm



SB\_0108



ICS9LPRS480BKLFT-GP  
71.09480.A03  
2nd = SLG:71.08628.003  
-1\_0310 change to 71.09480.A03

Due to PLL issue on current clock chip, the SBlink clock need to come from SRC clocks for RS740 and RS780. Future clock chip revision will fix this.

Clock chip has internal serial terminations for differential pairs, external resistors are reserved for debug purpose.

NB CLOCK INPUT TABLE

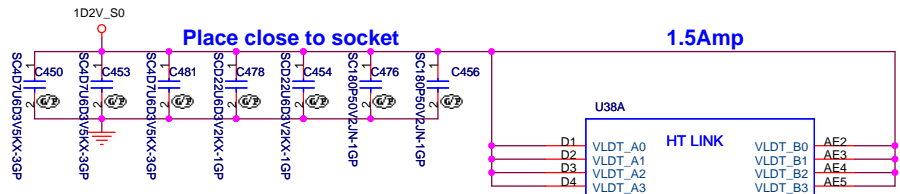
NB CLOCKS	RS740	RX780	RS780
HT_REFCLKP	66M SE(SINGLE END)	100M DIFF	100M DIFF
HT_REFCLKN	NC	100M DIFF	100M DIFF
REFCLK_P	14M SE (3.3V)	14M SE (1.8V)	14M SE (1.1V)
REFCLK_N	NC	NC	vref
GFX_REFCLK	100M DIFF	100M DIFF	100M DIFF(IN/OUT)*
GPP_REFCLK	NC	100M DIFF	NC or 100M DIFF OUTPUT
GPPSB_REFCLK	100M DIFF	100M DIFF	100M DIFF

\* RS780 can be used as clock buffer to output two PCIe reference clocks. By default, chip will configured as input mode, BIOS can program it to output mode.

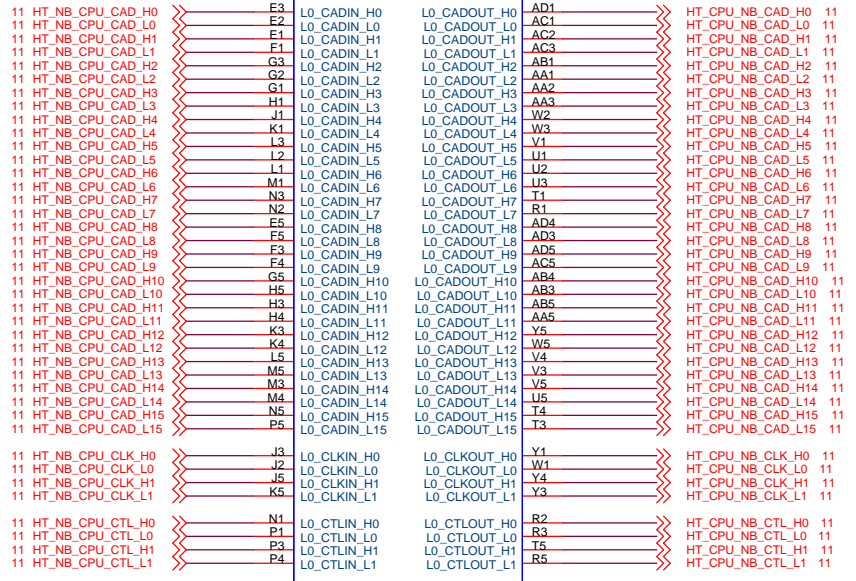
<Core Design>

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Title <b>CLKGEN_ICS9LPRS480</b>		
Size <b>A3</b>	Document Number <b>Olan</b>	Rev <b>-1</b>
Date Friday, April 18, 2008	Sheet 3	of 58



State	Specification	Notes	ZM200100M2303
S0.C0.Px	Tcase Max	3	TBD
	NB COF	1	400 MHz
	VID_VDDNB Min	2	0.950 V
	VID_VDDNB Max	2	0.950 V
	Startup P-state		S0.C0.P7
S0.C0.P0	CPU COF	1	2000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	IDD Max	3	TBD
S0.C0.P1	CPU COF	1	1800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1500 MHz
S0.C0.P2	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1300 MHz
	TDP	3	TBD
S0.C0.P3	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
S0.C0.P4	VID_VDD Max	2	1.125 V
	CPU COF	1	800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
S0.C0.P5	CPU COF	1	500 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
S0.C0.P6	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
	TDP	3	TBD
S0.C0.P7	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V



SKT-CPU638P-GP-U1  
 62.10055.111  
 ZND = 62.10040.471  
**SKT-BGA638H176**

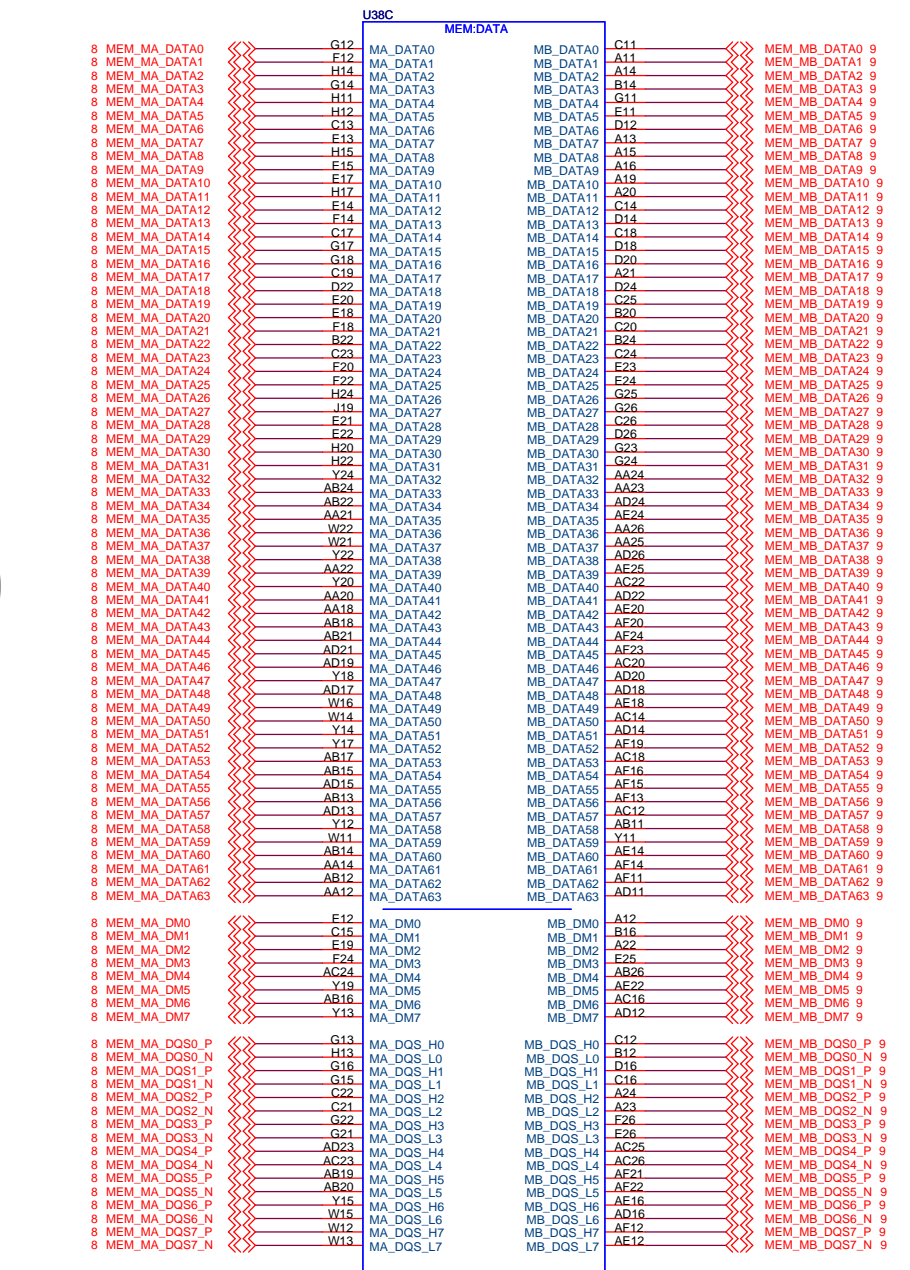
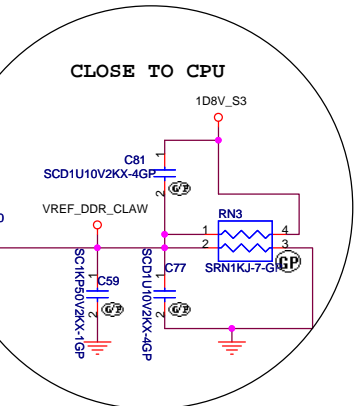
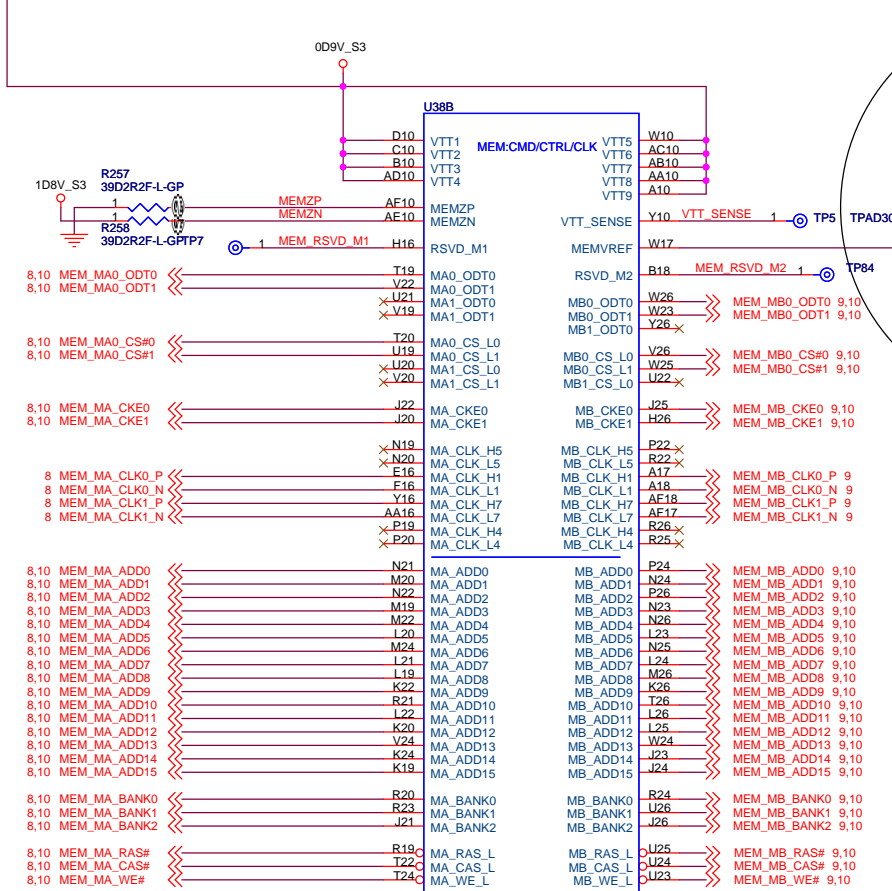
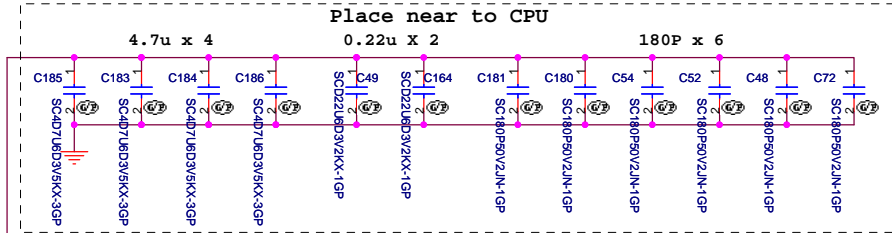
<Core Design>

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Title: **CPU\_HT\_LINK I/F (1/4)**

Size: **A3** Document Number: **Olan** Rev: **-1**

Date: **Friday, April 18, 2008** Sheet **4** of **58**



<Core Design>

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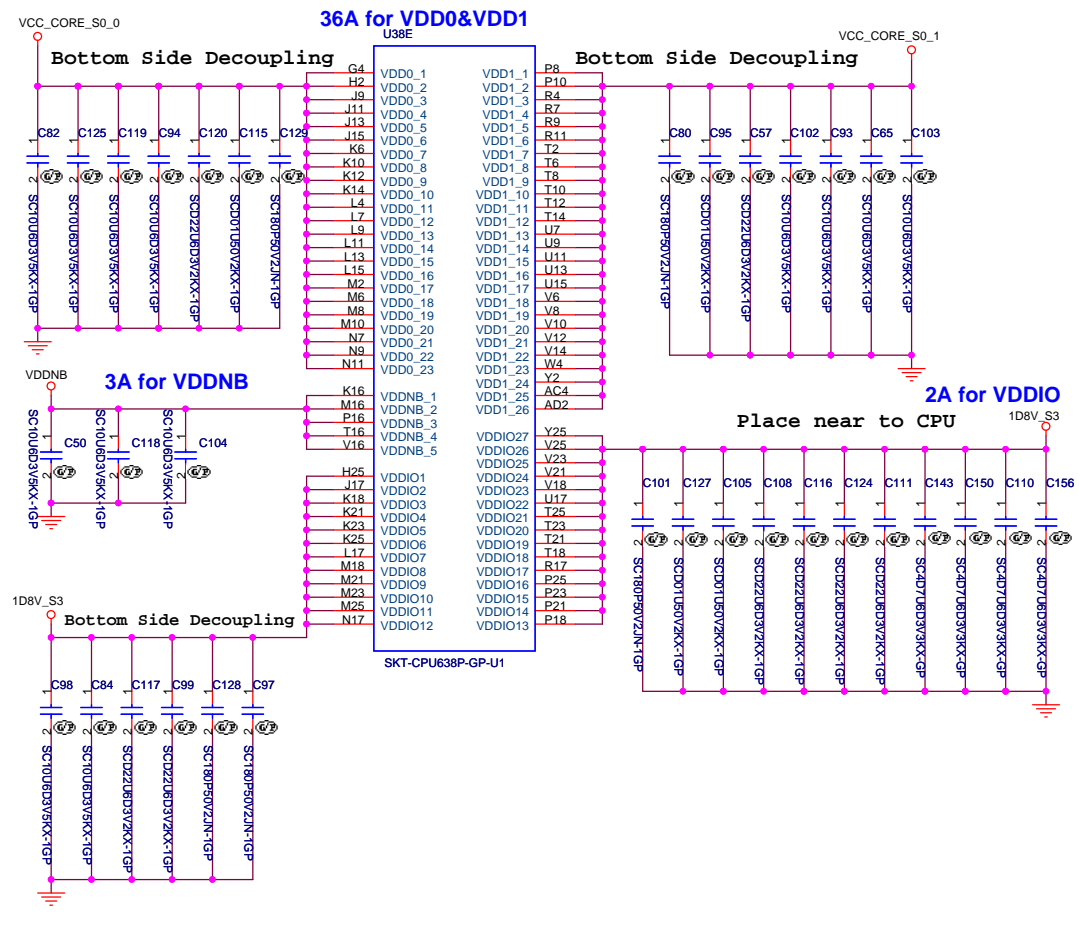
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Size: **A3** Document Number: **Olan** Rev: **-1**

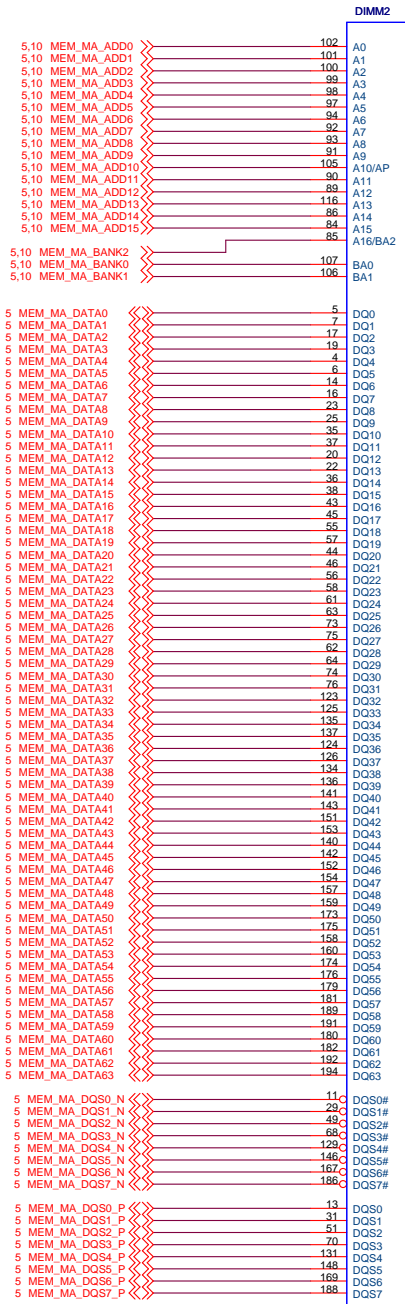
Date: **Friday, April 18, 2008** Sheet: **5** of **58**



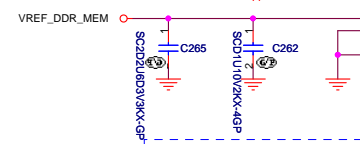
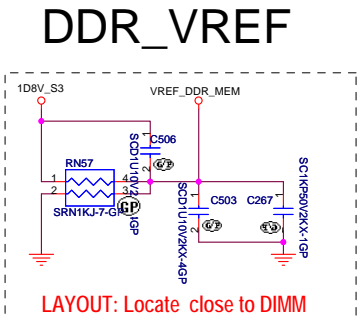
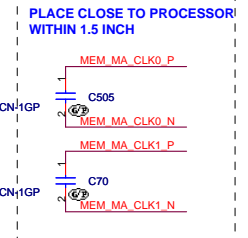
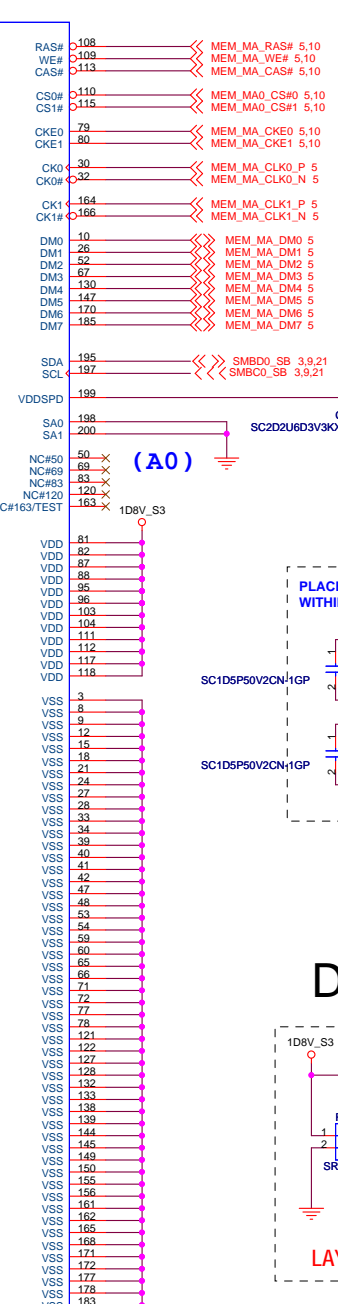
U38F		
AA4	VSS1	VSS66
AA11	VSS2	VSS67
AA13	VSS3	VSS68
AA15	VSS4	VSS69
AA17	VSS5	VSS70
AA19	VSS6	VSS71
AB2	VSS7	VSS72
AB7	VSS8	VSS73
AB9	VSS9	VSS74
AB23	VSS10	VSS75
AB25	VSS11	VSS76
AC11	VSS12	VSS77
AC13	VSS13	VSS78
AC15	VSS14	VSS79
AC17	VSS15	VSS80
AC19	VSS16	VSS81
AC21	VSS17	VSS82
AD6	VSS18	VSS83
AD8	VSS19	VSS84
AD25	VSS20	VSS85
AE11	VSS21	VSS86
AE13	VSS22	VSS87
AE15	VSS23	VSS88
AE17	VSS24	VSS89
AE19	VSS25	VSS90
AE21	VSS26	VSS91
AE23	VSS27	VSS92
B4	VSS28	VSS93
B6	VSS29	VSS94
B8	VSS30	VSS95
B9	VSS31	VSS96
B11	VSS32	VSS97
B13	VSS33	VSS98
B15	VSS34	VSS99
B17	VSS35	VSS100
B19	VSS36	VSS101
B21	VSS37	VSS102
B23	VSS38	VSS103
B25	VSS39	VSS104
D6	VSS40	VSS105
D9	VSS41	VSS106
D11	VSS42	VSS107
D13	VSS43	VSS108
D15	VSS44	VSS109
D17	VSS45	VSS110
D19	VSS46	VSS111
D21	VSS47	VSS112
D23	VSS48	VSS113
D25	VSS49	VSS114
E4	VSS50	VSS115
F1	VSS51	VSS116
F2	VSS52	VSS117
F11	VSS53	VSS118
F13	VSS54	VSS119
F15	VSS55	VSS120
F17	VSS56	VSS121
F19	VSS57	VSS122
F21	VSS58	VSS123
F23	VSS59	VSS124
F25	VSS60	VSS125
H7	VSS61	VSS126
H9	VSS62	VSS127
H21	VSS63	VSS128
H23	VSS64	VSS129
J4	VSS65	







**NORMAL TYPE**



Place C2.2uF and 0.1uF < 500mils from DDR connector

DDR2-200P-22-GP-U2  
62.10017.A61  
2ND = 62.10017.A51  
HI 9.2mm

Main Source:

<Core Design>

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Title: **DDR\_SO-DIMM SKT\_1**

Size	Document Number	Rev
Custom	Olan	-1

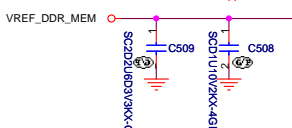
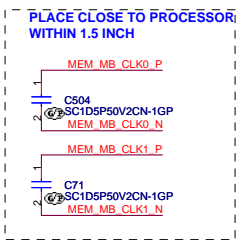
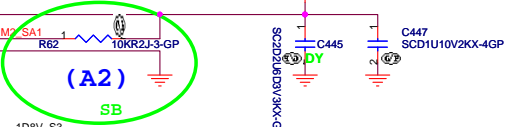
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5,10 MEM_MB_ADD0	102	A0
5,10 MEM_MB_ADD1	101	A1
5,10 MEM_MB_ADD2	100	A2
5,10 MEM_MB_ADD3	99	A3
5,10 MEM_MB_ADD4	98	A4
5,10 MEM_MB_ADD5	97	A5
5,10 MEM_MB_ADD6	94	A6
5,10 MEM_MB_ADD7	92	A7
5,10 MEM_MB_ADD8	93	A8
5,10 MEM_MB_ADD9	91	A9
5,10 MEM_MB_ADD10	105	A10/AP
5,10 MEM_MB_ADD11	90	A11
5,10 MEM_MB_ADD12	89	A12
5,10 MEM_MB_ADD13	116	A13
5,10 MEM_MB_ADD14	86	A14
5,10 MEM_MB_ADD15	84	A15
5,10 MEM_MB_ADD15	85	A16/BA2
5,10 MEM_MB_BANK2	107	BA0
5,10 MEM_MB_BANK0	106	BA1
5,10 MEM_MB_BANK1	106	BA1
5 MEM_MB_DATA0	7	DO0
5 MEM_MB_DATA1	7	DO1
5 MEM_MB_DATA2	17	DO2
5 MEM_MB_DATA3	19	DO3
5 MEM_MB_DATA4	4	DO4
5 MEM_MB_DATA5	6	DO5
5 MEM_MB_DATA6	14	DO6
5 MEM_MB_DATA7	16	DO7
5 MEM_MB_DATA8	23	DO8
5 MEM_MB_DATA9	25	DO9
5 MEM_MB_DATA10	35	DO10
5 MEM_MB_DATA11	37	DO11
5 MEM_MB_DATA12	20	DO12
5 MEM_MB_DATA13	22	DO13
5 MEM_MB_DATA14	36	DO14
5 MEM_MB_DATA15	38	DO15
5 MEM_MB_DATA16	43	DO16
5 MEM_MB_DATA17	45	DO17
5 MEM_MB_DATA18	55	DO18
5 MEM_MB_DATA19	57	DO19
5 MEM_MB_DATA20	44	DO20
5 MEM_MB_DATA21	46	DO21
5 MEM_MB_DATA22	56	DO22
5 MEM_MB_DATA23	58	DO23
5 MEM_MB_DATA24	61	DO24
5 MEM_MB_DATA25	63	DO25
5 MEM_MB_DATA26	73	DO26
5 MEM_MB_DATA27	75	DO27
5 MEM_MB_DATA28	62	DO28
5 MEM_MB_DATA29	64	DO29
5 MEM_MB_DATA30	74	DO30
5 MEM_MB_DATA31	76	DO31
5 MEM_MB_DATA32	123	DO32
5 MEM_MB_DATA33	125	DO33
5 MEM_MB_DATA34	135	DO34
5 MEM_MB_DATA35	137	DO35
5 MEM_MB_DATA36	124	DO36
5 MEM_MB_DATA37	126	DO37
5 MEM_MB_DATA38	134	DO38
5 MEM_MB_DATA39	136	DO39
5 MEM_MB_DATA40	141	DO40
5 MEM_MB_DATA41	143	DO41
5 MEM_MB_DATA42	151	DO42
5 MEM_MB_DATA43	153	DO43
5 MEM_MB_DATA44	140	DO44
5 MEM_MB_DATA45	142	DO45
5 MEM_MB_DATA46	152	DO46
5 MEM_MB_DATA47	154	DO47
5 MEM_MB_DATA48	157	DO48
5 MEM_MB_DATA49	159	DO49
5 MEM_MB_DATA50	173	DO50
5 MEM_MB_DATA51	175	DO51
5 MEM_MB_DATA52	158	DO52
5 MEM_MB_DATA53	160	DO53
5 MEM_MB_DATA54	174	DO54
5 MEM_MB_DATA55	176	DO55
5 MEM_MB_DATA56	179	DO56
5 MEM_MB_DATA57	181	DO57
5 MEM_MB_DATA58	189	DO58
5 MEM_MB_DATA59	191	DO59
5 MEM_MB_DATA60	180	DO60
5 MEM_MB_DATA61	182	DO61
5 MEM_MB_DATA62	192	DO62
5 MEM_MB_DATA63	194	DO63
5 MEM_MB_DQS0_N	110	DQS0#
5 MEM_MB_DQS1_N	290	DQS1#
5 MEM_MB_DQS2_N	490	DQS2#
5 MEM_MB_DQS3_N	690	DQS3#
5 MEM_MB_DQS4_N	1290	DQS4#
5 MEM_MB_DQS5_N	1490	DQS5#
5 MEM_MB_DQS6_N	1690	DQS6#
5 MEM_MB_DQS7_N	1890	DQS7#
5 MEM_MB_DQS0_P	13	DQS0
5 MEM_MB_DQS1_P	31	DQS1
5 MEM_MB_DQS2_P	51	DQS2
5 MEM_MB_DQS3_P	70	DQS3
5 MEM_MB_DQS4_P	131	DQS4
5 MEM_MB_DQS5_P	148	DQS5
5 MEM_MB_DQS6_P	169	DQS6
5 MEM_MB_DQS7_P	188	DQS7
5,10 MEM_MB_ODT0	114	ODT0
5,10 MEM_MB_ODT1	119	ODT1

REVERSE TYPE

RAS#	108	MEM_MB_RAS# 5,10
WE#	109	MEM_MB_WE# 5,10
CAS#	113	MEM_MB_CAS# 5,10
CS0#	110	MEM_MB_CS#0 5,10
CS1#	115	MEM_MB_CS#1 5,10
CKE0	79	MEM_MB_CKE0 5,10
CKE1	80	MEM_MB_CKE1 5,10
CK0	30	MEM_MB_CLK0_P 5
CK0#	32	MEM_MB_CLK0_N 5
CK1	164	MEM_MB_CLK1_P 5
CK1#	166	MEM_MB_CLK1_N 5
DM0	10	MEM_MB_DM0 5
DM1	26	MEM_MB_DM1 5
DM2	52	MEM_MB_DM2 5
DM3	67	MEM_MB_DM3 5
DM4	130	MEM_MB_DM4 5
DM5	147	MEM_MB_DM5 5
DM6	170	MEM_MB_DM6 5
DM7	185	MEM_MB_DM7 5
SDA	195	SMBD0_SB 3,8,21
SCL	197	SMBC0_SB 3,8,21
VDDSPD	199	
SA0	198	
SA1	200	
NC#50	50	X
NC#69	69	X
NC#83	83	X
NC#120	120	X
NC#163/TEST	163	X
VDD	81	
VDD	82	
VDD	87	
VDD	88	
VDD	95	
VDD	96	
VDD	103	
VDD	104	
VDD	111	
VDD	112	
VDD	117	
VDD	118	
VSS	3	
VSS	8	
VSS	9	
VSS	15	
VSS	18	
VSS	21	
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VSS	27	
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VSS	33	
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VSS	161	
VSS	162	
VSS	165	
VSS	70	
VSS	171	
VSS	172	
VSS	173	
VSS	177	
VSS	178	
VSS	183	
VSS	184	
VSS	187	
VSS	190	
VSS	193	
VSS	196	
GND	201	
MH2	GP	



SKT-SODIMM20020U3GP  
62.10017.661  
2ND = 62.10017.A41

LOW 5.2mm  
Main Source:

Place C2.2uF and 0.1uF < 500mils from DDR connector

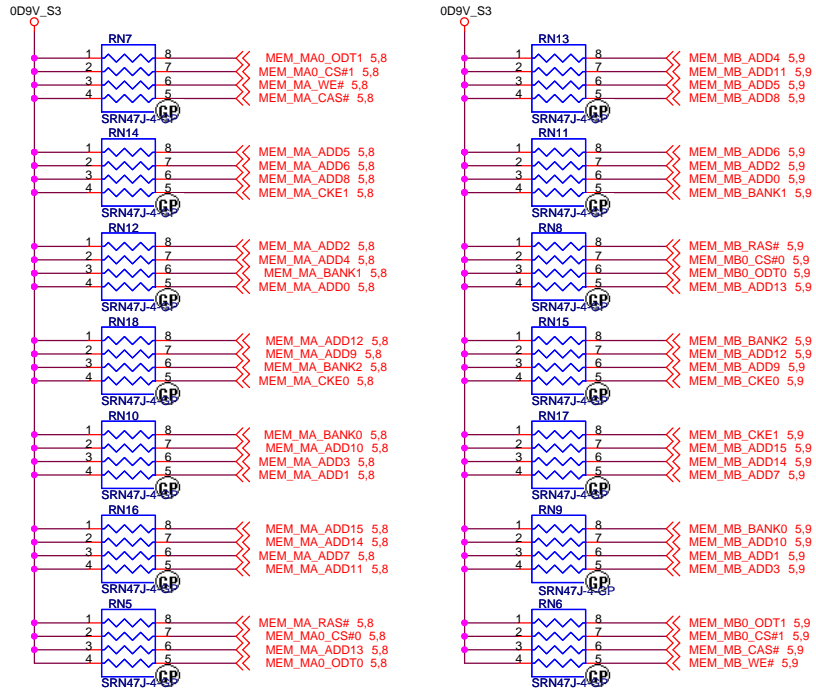
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Title	DDR_SO-DIMM SKT_2	
Size	Document Number	Rev
Custom	Olan	-1
Date: Friday, April 16, 2008	Sheet 9	of 58

# PARALLEL TERMINATION

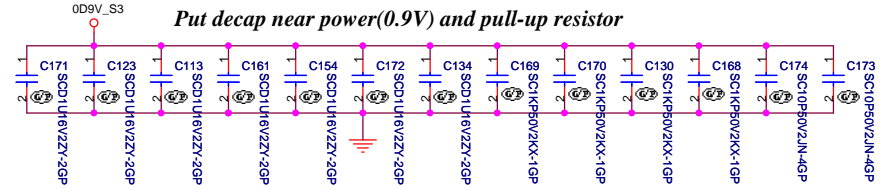
Put decap near power(0.9V) and pull-up resistor



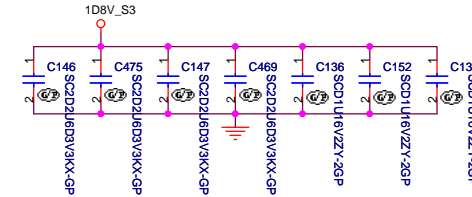
Do not share the Term resistor between the DDR address and Control Signals.

# Decoupling Capacitor

Put decap near power(0.9V) and pull-up resistor

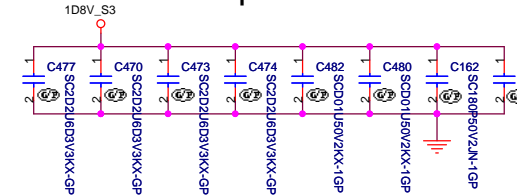


## Place these Caps near DM1



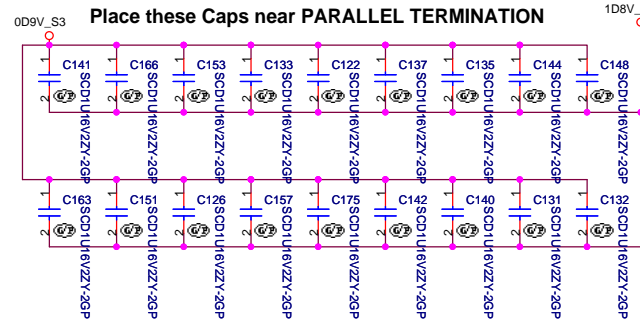
Layout Note:  
Place one cap close to every 2 pullup resistors terminated to 0D9V\_S3

## Place these Caps near DM2



Layout Note:  
Place one cap close to every 2 pullup resistors terminated to 0D9V\_S3

Place these Caps near PARALLEL TERMINATION

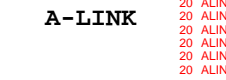
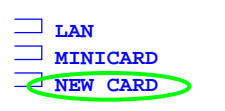
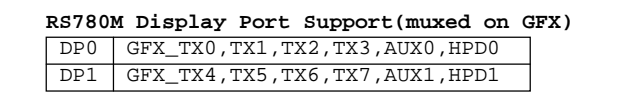
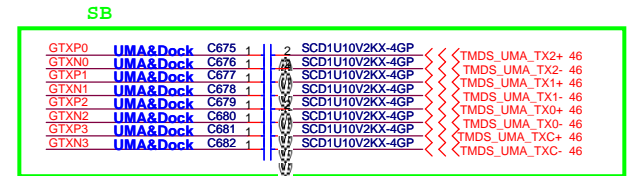
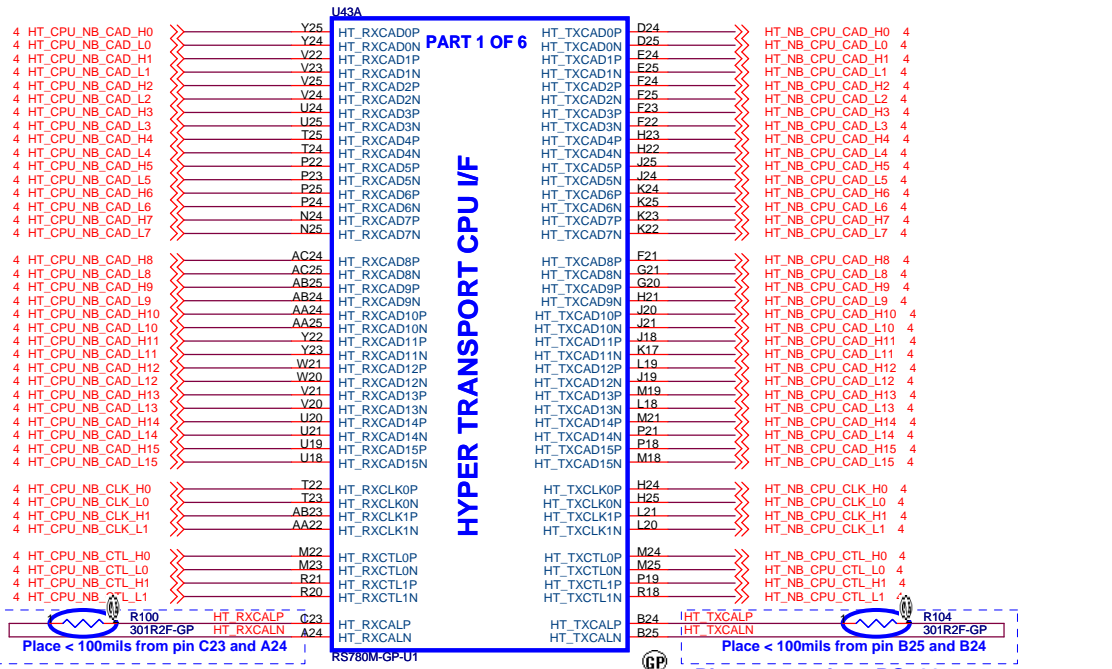


<Core Design>

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Title: **DDR DAMPING & TERMINATION**

Size: A3 Document Number: **Olan** Rev: -1  
Date: Friday, April 18, 2008 Sheet 10 of 58



**Wistron Corporation**

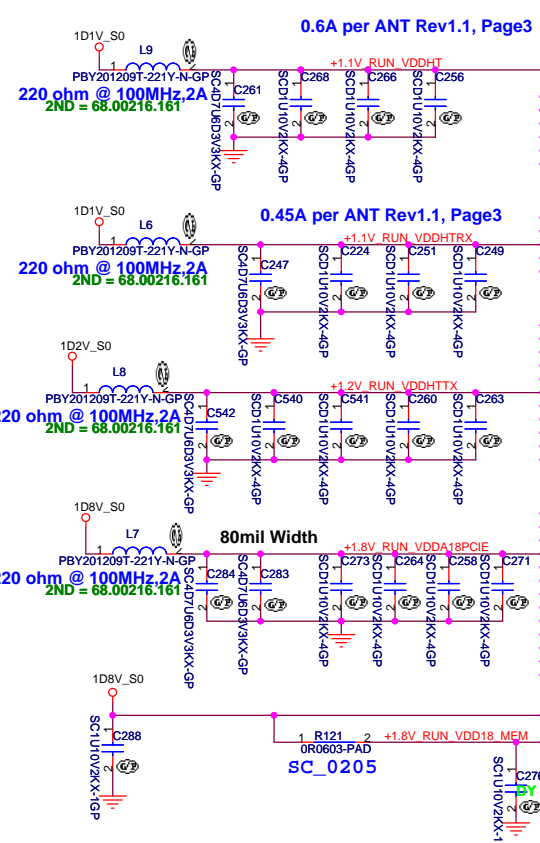
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

**ATI-RS780M\_HT LINK&PCIE(1/3)**

Size A3 Document Number **Olan** Rev -1

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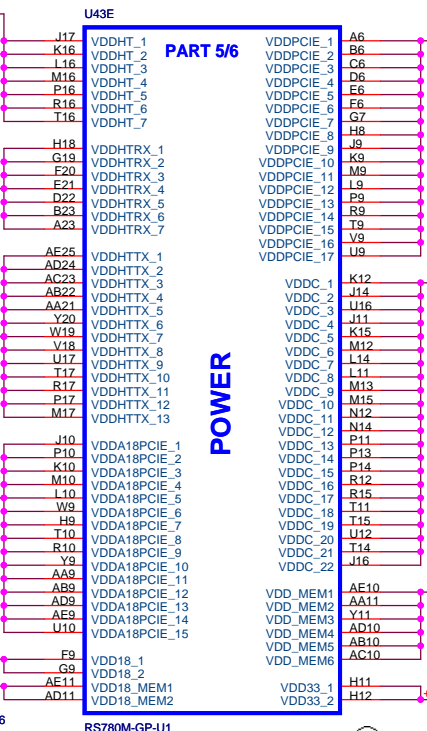




0.6A per ANT Rev1.1, Page3

0.45A per ANT Rev1.1, Page3

80mil Width

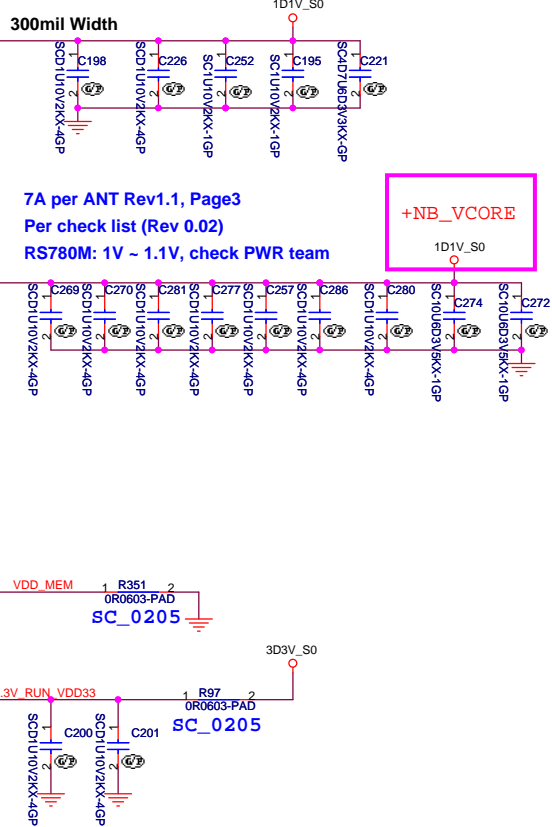


PART 5/6

PAR 4 OF 6

POWER

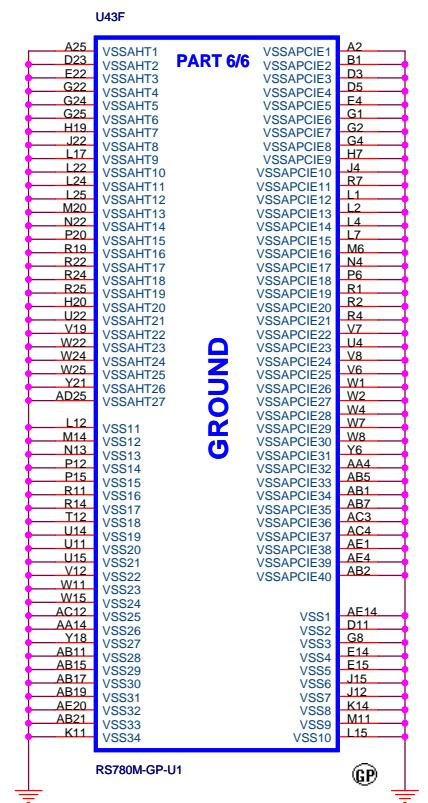
MEM\_COMP\_P and MEM\_COMP\_N trace width >=10mils and 10mils spacing from other Signals in X,Y,Z directions



7A per ANT Rev1.1, Page3 Per check list (Rev 0.02) RS780M: 1V ~ 1.1V, check PWR team

VDD MEM

+3.3V RUN VDD33



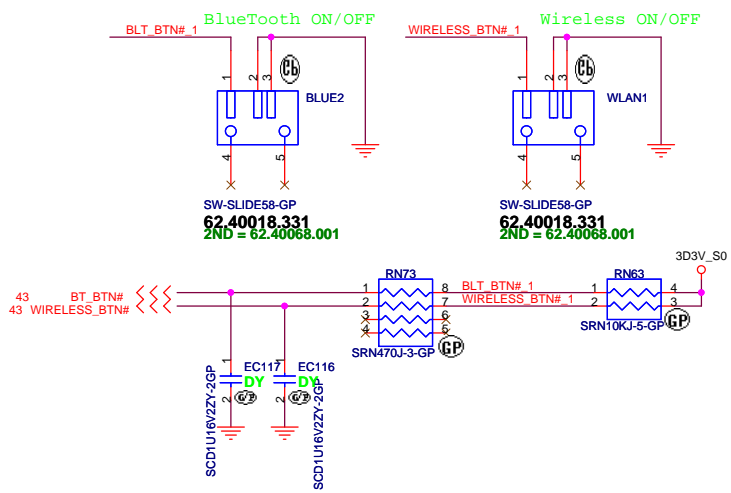
PART 6/6

GROUND

<Core Design>

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Title		
ATI-RS780M_Side Port&PWR&GND(3/3)		
Size	Document Number	Rev
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Date:	Friday, April 18, 2008	Sheet 13 of 58

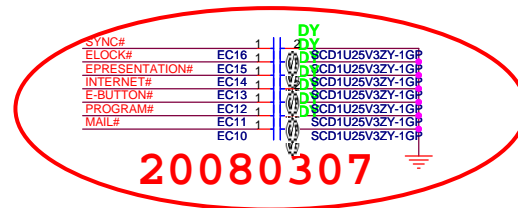
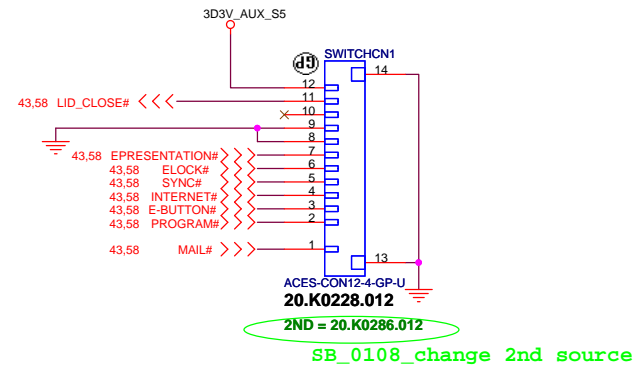
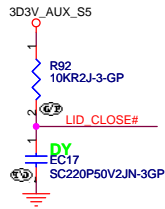
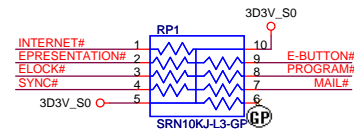


<Core Design>

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 Taipei Hsien 221, Taiwan, R.O.C.

Title		
<b>SWITCH</b>		
Size	Document Number	Rev
A3	<b>Olan</b>	-1
Date:	Friday, April 18, 2008	Sheet 14 of 58

# LAUNCH



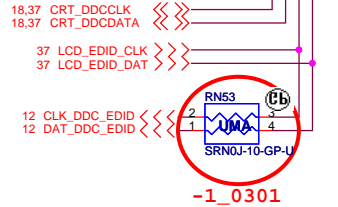
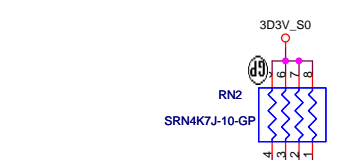
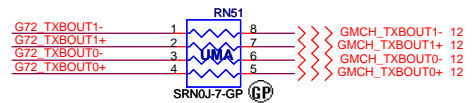
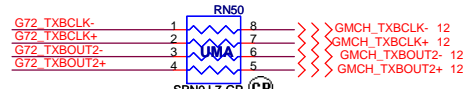
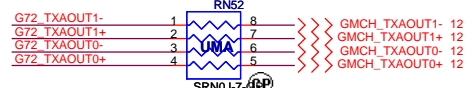
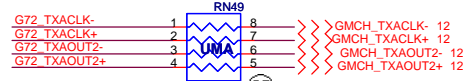
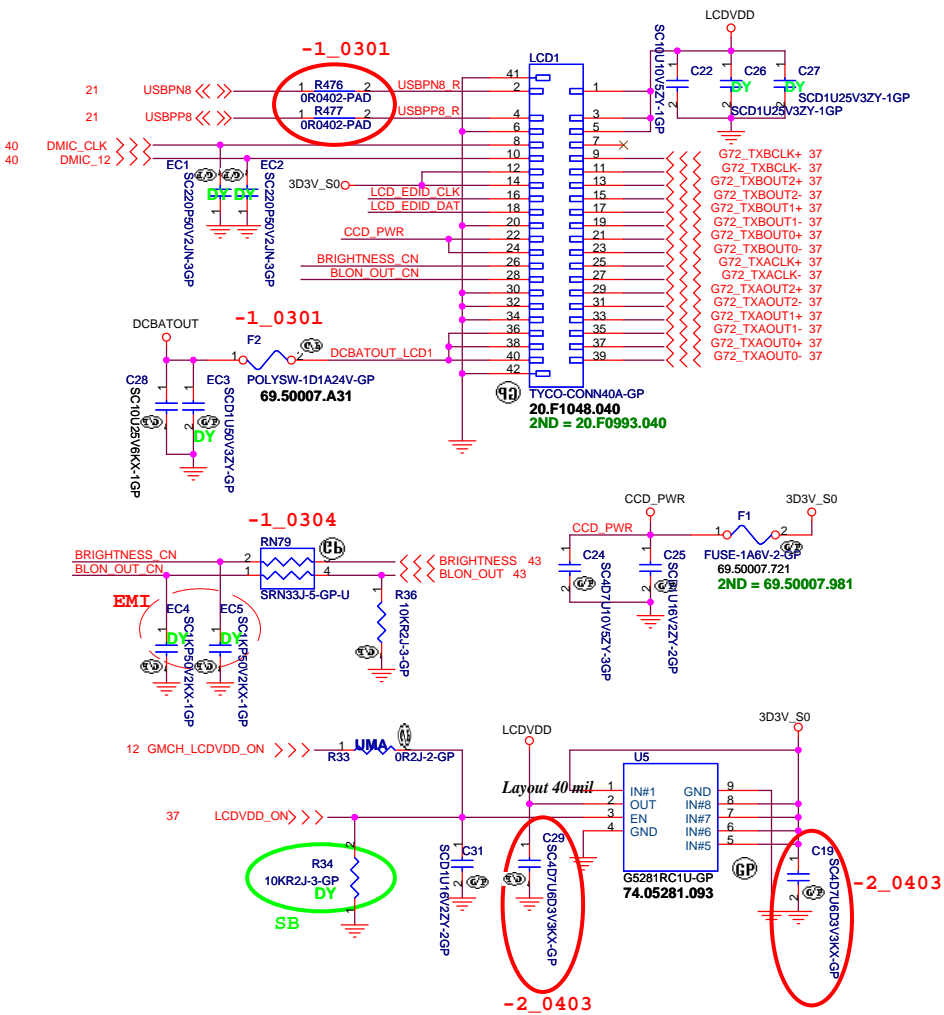
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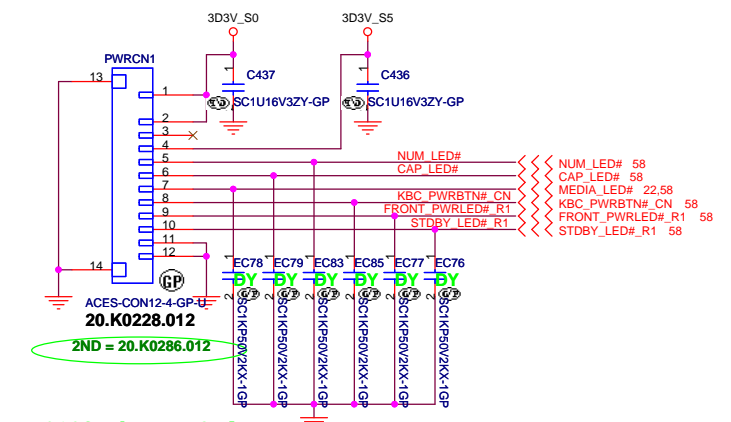
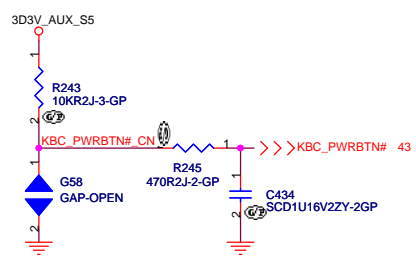
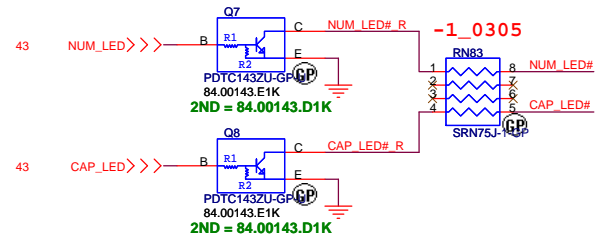
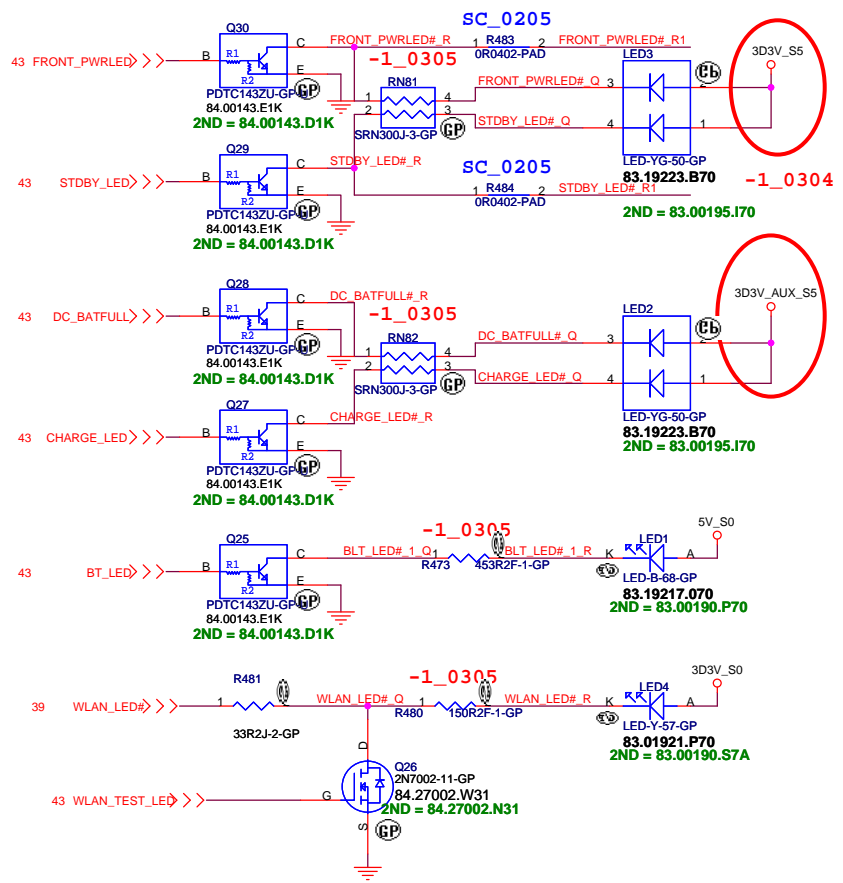
Title			<b>LAUNCH</b>		
Size	Document Number		Rev		
A3	Olan		-1		
Date:	Friday, April 18, 2008	Sheet	15	of	58



# LCD/INVERTER/CCD CONN



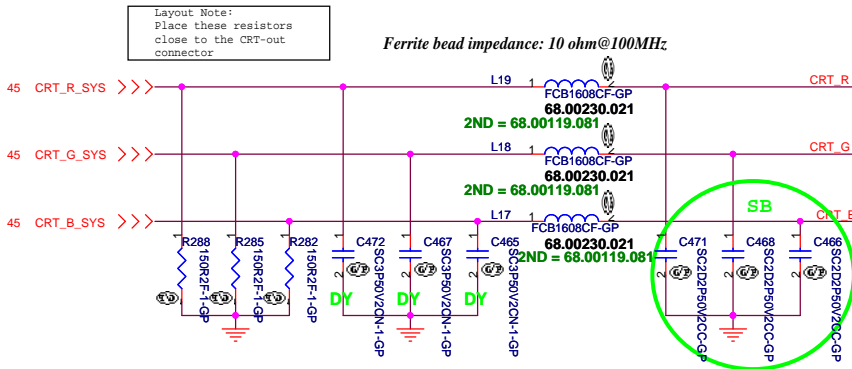
# LED



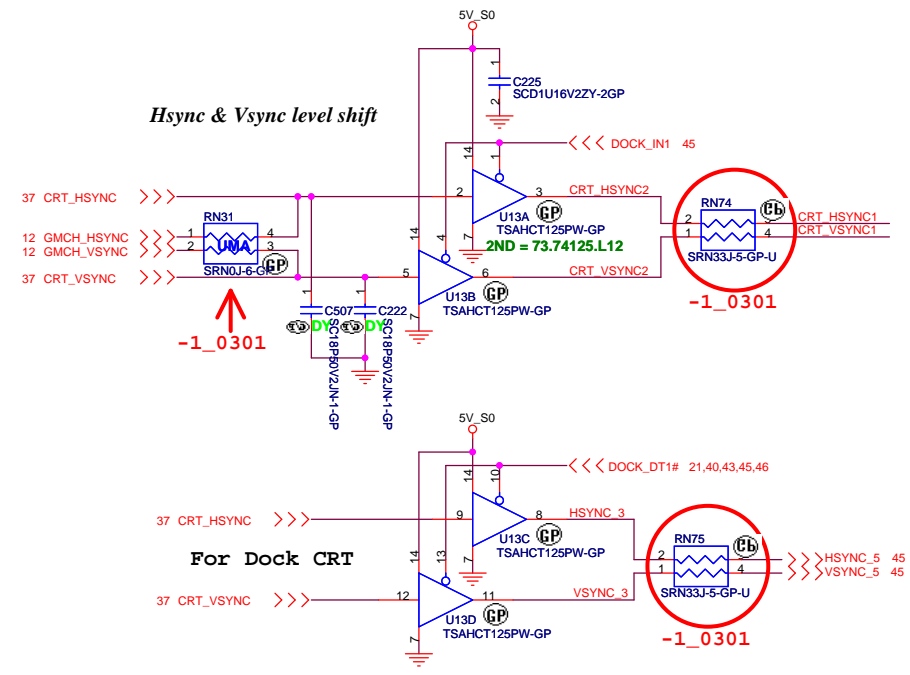
SB\_0108\_change 2nd source

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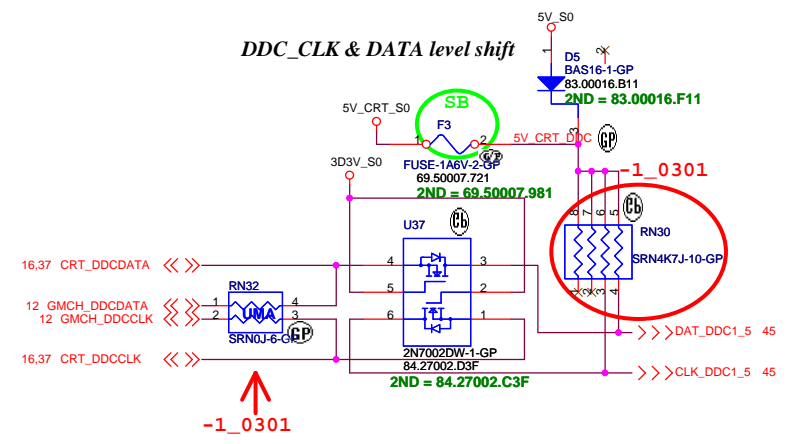
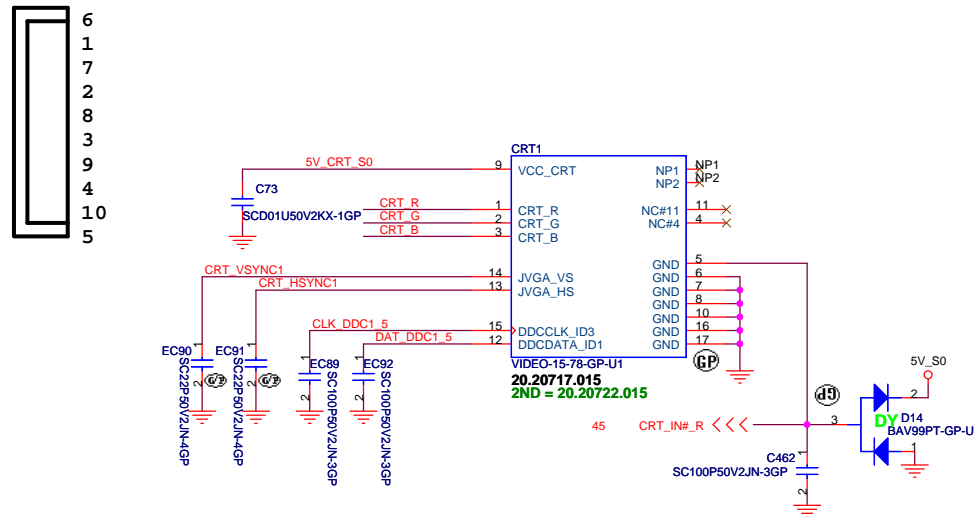
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<b>LED &amp; LAUNCH</b>		
Size	Document Number	Rev
A3	<b>Olan</b>	-1
Date:	Friday, April 18, 2008	Sheet 17 of 58

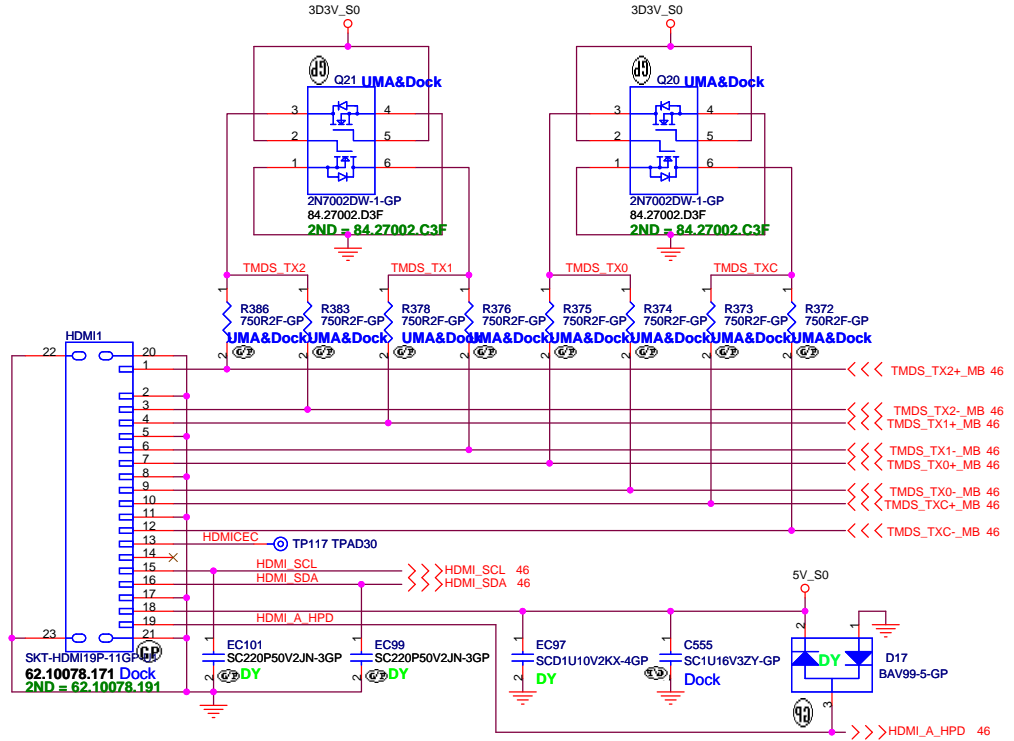


Layout Note:  
\* Must be a ground return path between this ground and the ground on the VGA connector.  
Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.




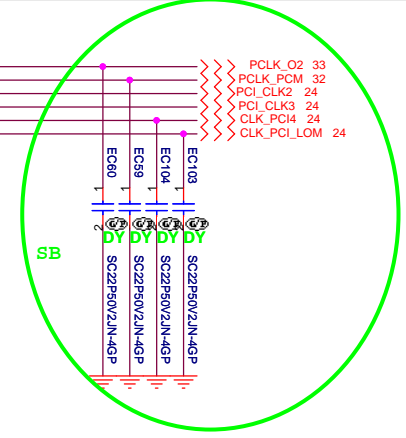
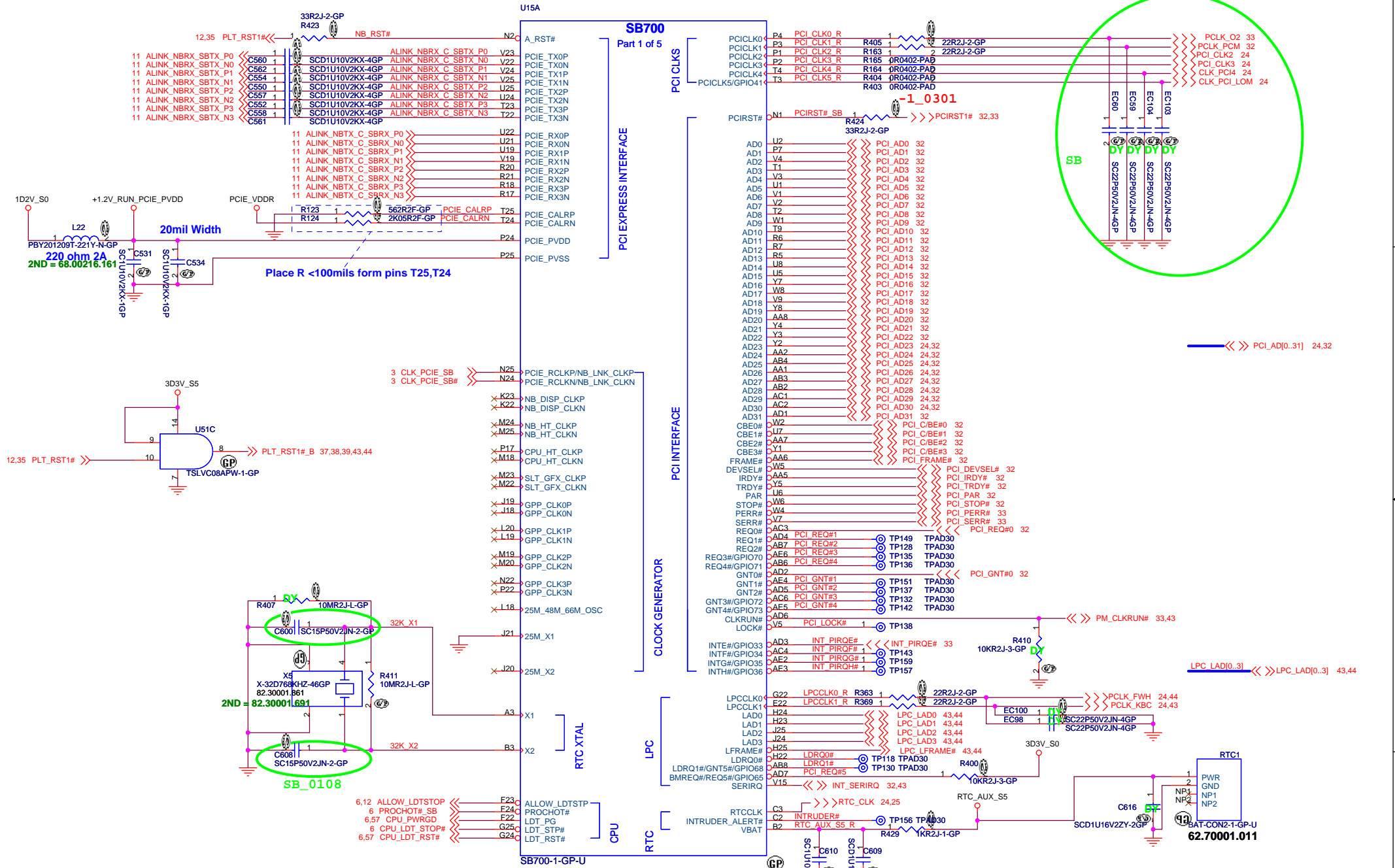
### CRT I/F & CONNECTOR





<Core Design>

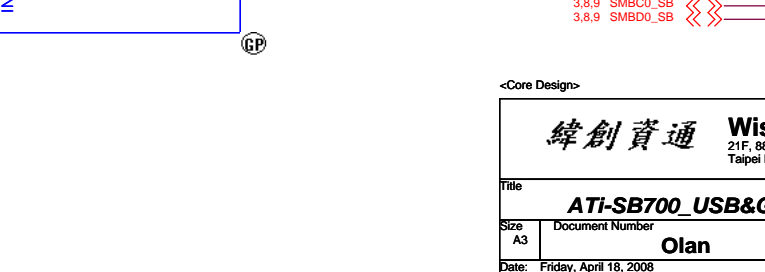
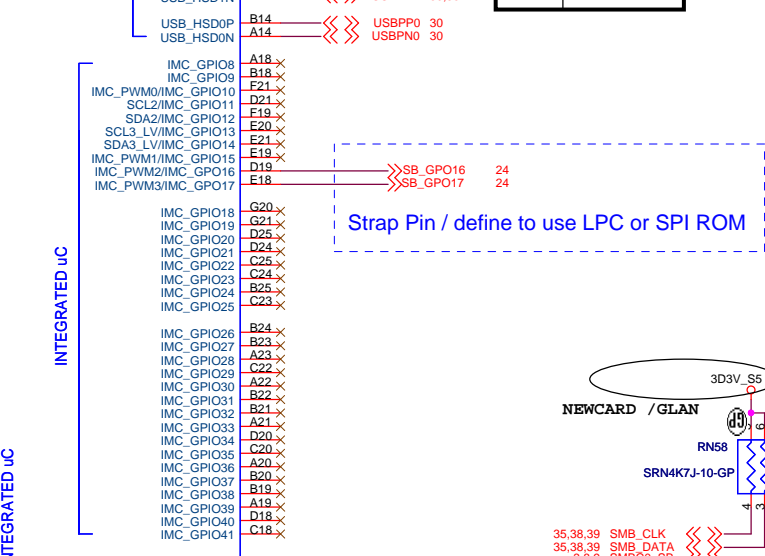
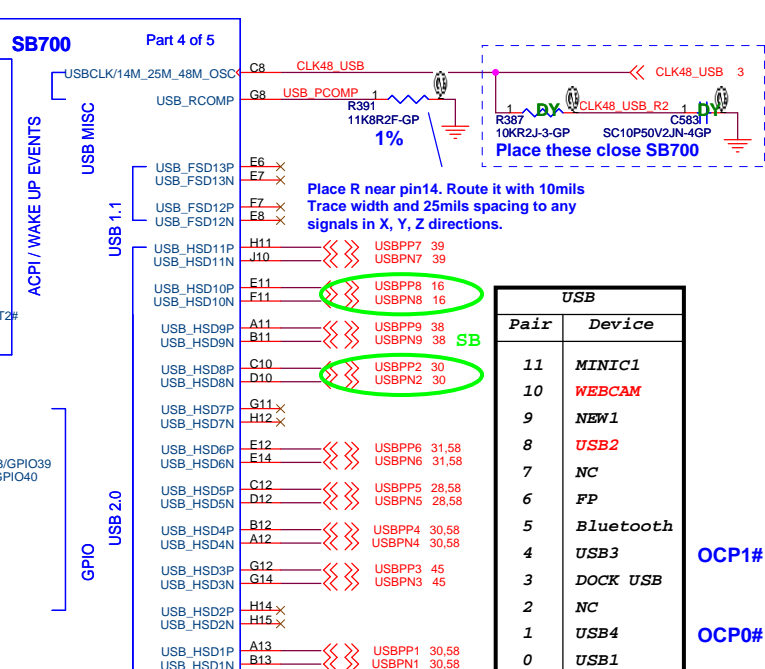
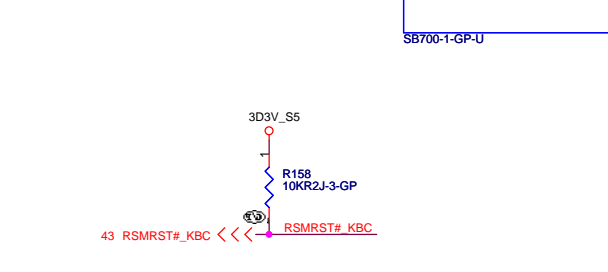
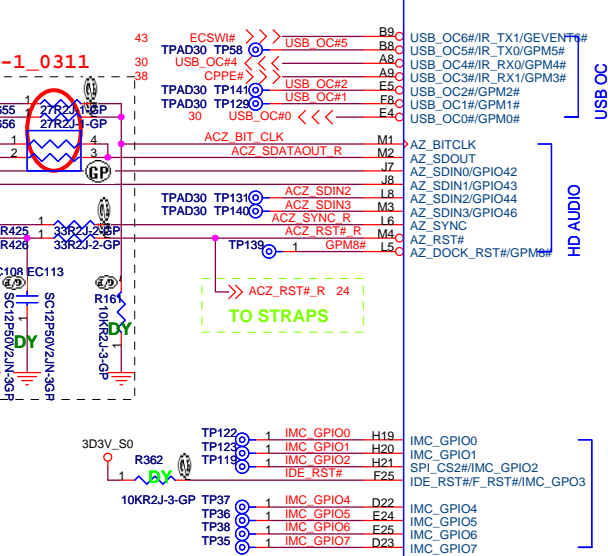
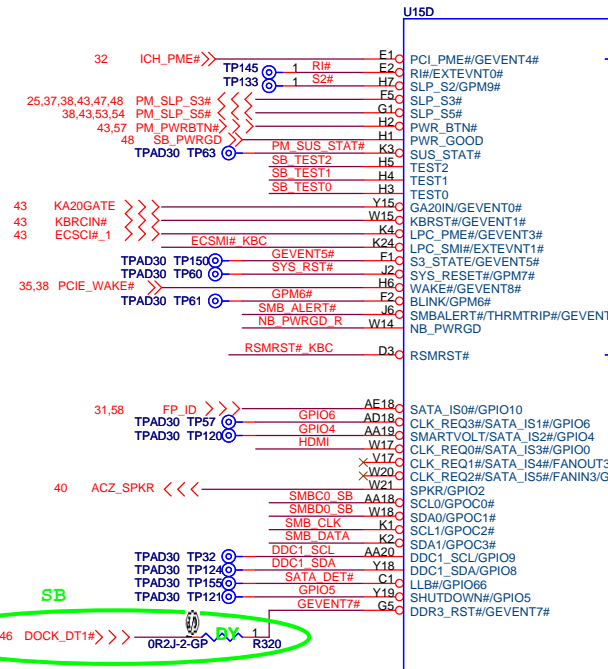
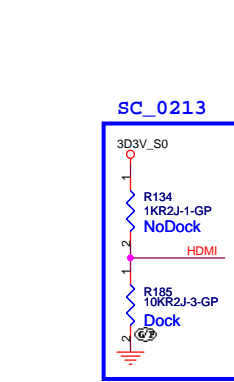
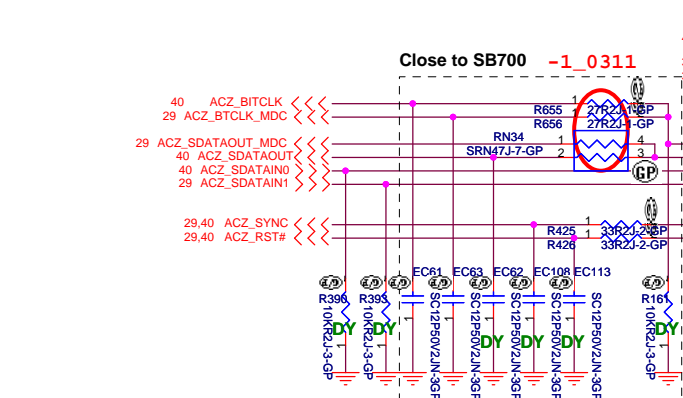
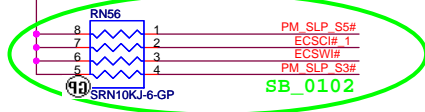
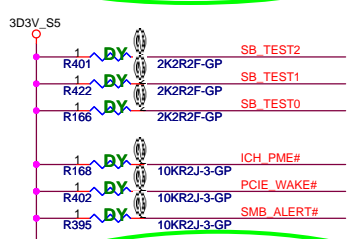
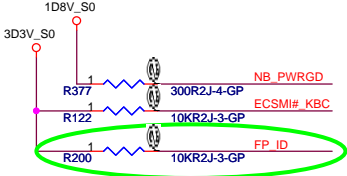
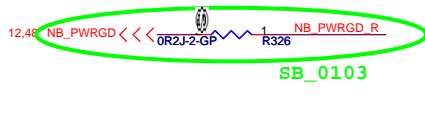
 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>HDMI CONNECTOR</b>		
Size	Document Number	Rev
A3	Olan	-1
Date:	Friday, April 18, 2008	Sheet 19 of 58



<Core Design>

緯創資通 Wistron Corporation  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title		
ATI-SB700_PCIE&PCI (1/5)		
Size	Document Number	Rev
A3	Olan	-1
Date:	Friday, April 18, 2008	Sheet 20 of 58



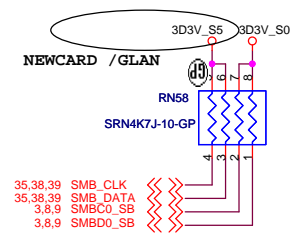
Place R near pin14. Route it with 10mils Trace width and 25mils spacing to any signals in X, Y, Z directions.

Pair	Device
11	MINIC1
10	WEBCAM
9	NEW1
8	USB2
7	NC
6	FP
5	Bluetooth
4	USB3
3	DOCK USB
2	NC
1	USB4
0	USB1

OCP1#

OCP0#

Strap Pin / define to use LPC or SPI ROM



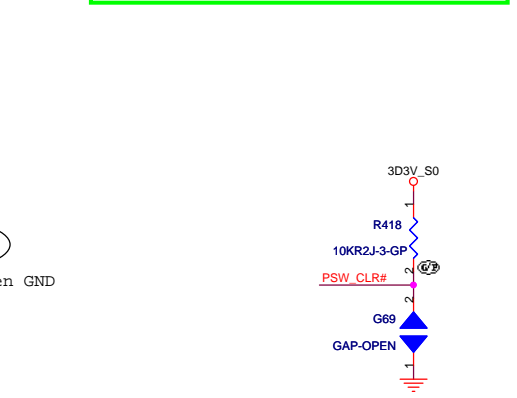
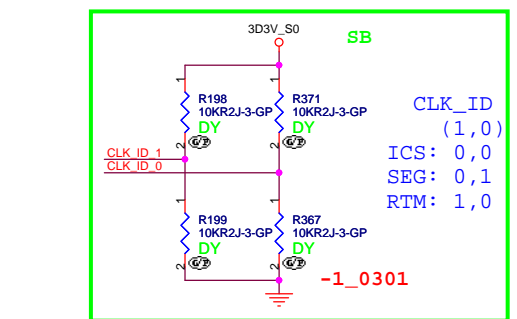
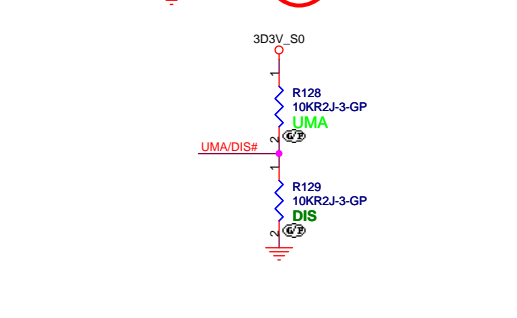
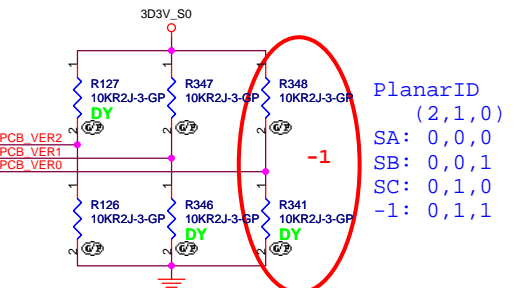
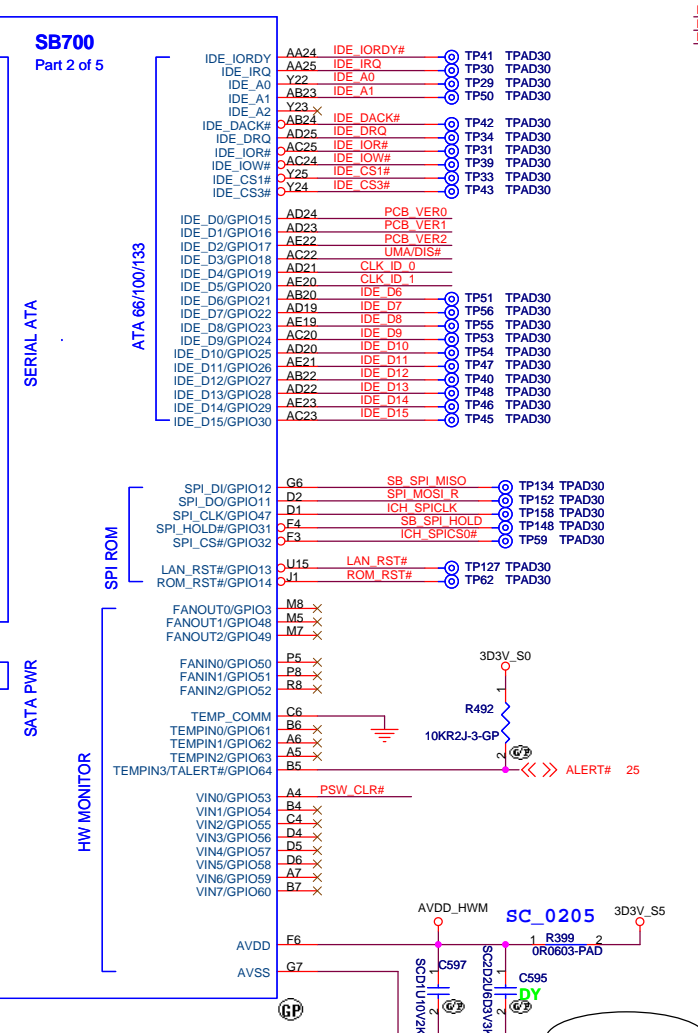
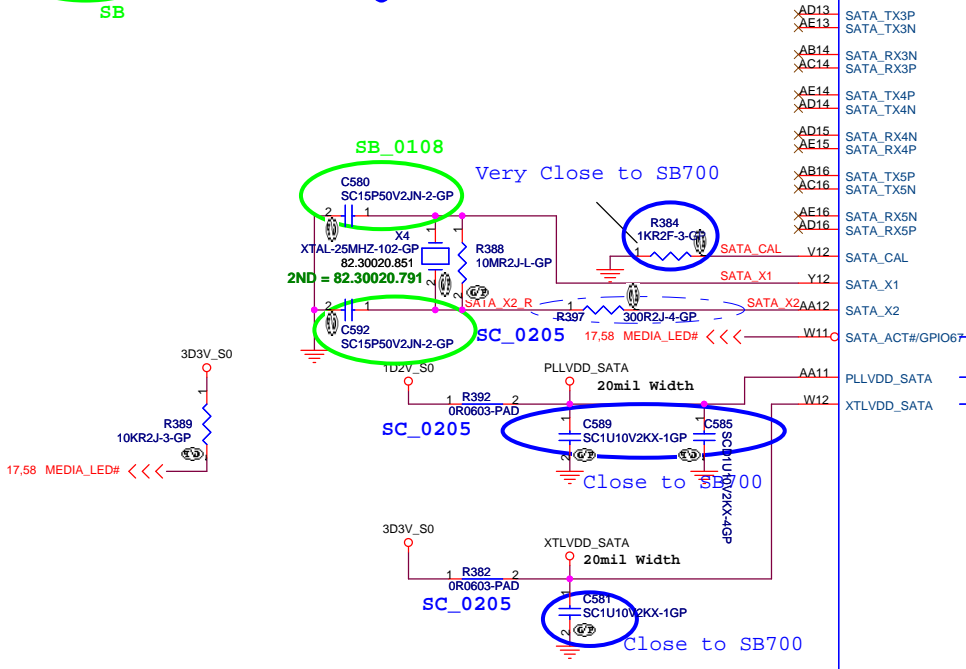
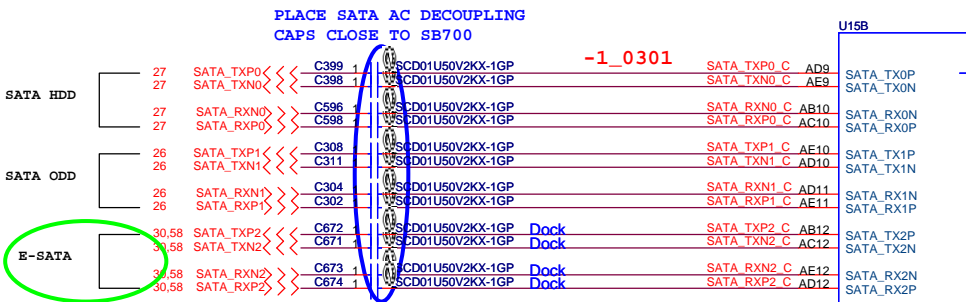
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**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **ATI-SB700\_USB&GPIO\_(2/5)**

Size: A3 Document Number: **Olan** Rev: -1

Date: Friday, April 18, 2008 Sheet 21 of 58



<Core Design>

**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **ATI-SB700 SATA-IDE (3/5)**

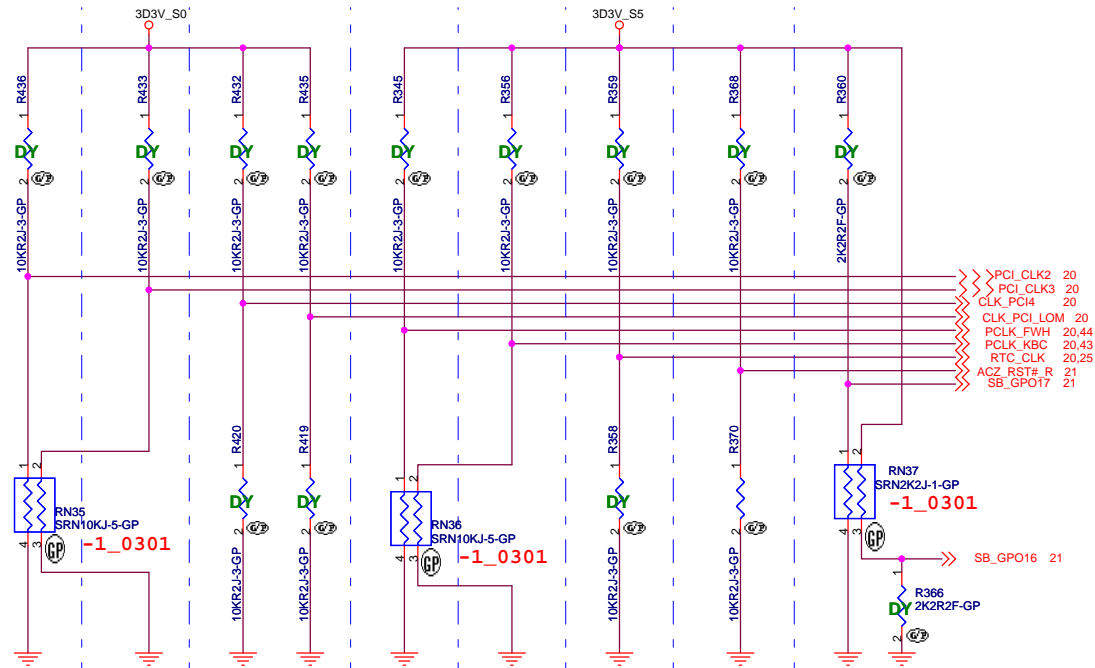
Size: <b>A3</b>	Document Number:	Rev: <b>-1</b>
Date: <b>Friday, April 18, 2008</b>	<b>Olan</b>	Sheet 22 of 58





## REQUIRED STRAPS

### REQUIRED SYSTEM STRAPS



- PCI\_CLK2 20
- PCI\_CLK3 20
- CLK\_PCI4 20
- CLK\_PCI\_LOM 20
- PCLK\_FWH 20,44
- PCLK\_KBC 20,43
- RTC\_CLK 20,25
- ACZ\_RST#\_R 21
- SB\_GPO17 21

## DEBUG STRAPS

- TPAD30 TP160 PCI\_AD23 20,32
- TPAD30 TP163 PCI\_AD24 20,32
- TPAD30 TP161 PCI\_AD25 20,32
- TPAD30 TP162 PCI\_AD26 20,32
- TPAD30 TP164 PCI\_AD27 20,32
- TPAD30 TP165 PCI\_AD28 20,32
- TPAD30 TP166 PCI\_AD29 20,32
- TPAD30 TP153 PCI\_AD30 20,32

	PCI_CLK2	PCI_CLK3	CLK_PCI_LOM CLK_PCI4	PCLK_FWH	PCLK_KBC	RTCCLK	AZ_RST#	SB_GPO17, SB_GPO16
<b>PULL HIGH</b>	WatchDOG (NB_PWRGD) ENABLED	USE DEBUG STRAPS	RESERVED	IMC ENABLED	CLKGEN ENABLED (Use Internal)	INTERNAL RTC DEFAULT	ENABLE PCI ROM BOOT	ROM TYPE: H, H = Reserved H, L = SPI ROM DEFAULT
<b>PULL LOW</b>	WatchDog (NB_PWRGD) DISABLED DEFAULT	IGNORE DEBUG STRAPS DEFAULT		IMC DISABLED DEFAULT	CLKGEN DISABLED (Use External) DEFAULT	EXT. RTC (PD on X1, apply 32KHz to RTC_CLK)	DISABLE PCI ROM BOOT DEFAULT	L, H = LPC ROM L, L = FWH ROM

NOTE: SB700 HAS INTERNAL 15K PULL UP RESISTOR FOR RTCCLK

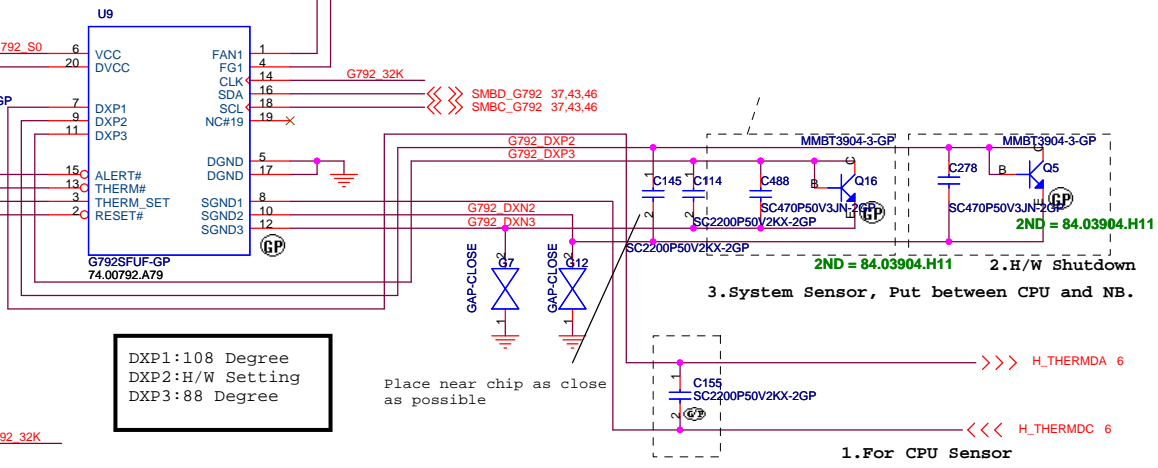
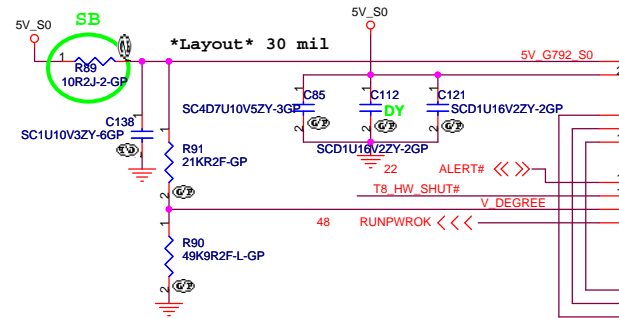
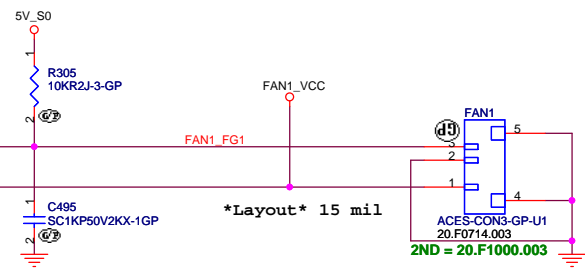
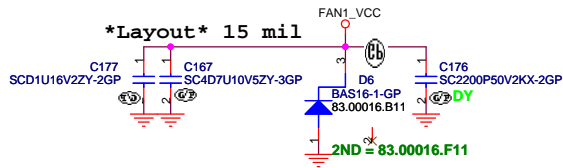
	PCI_AD28	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23	PCI_AD30 PCI_AD29
<b>PULL HIGH</b>	USE LONG RESET (DEFAULT)	USE PCI PLL (DEFAULT)	USE ACPI BCLK (DEFAULT)	USE IDE PLL (DEFAULT)	USE DEFAULT PCIE STRAPS (DEFAULT)	Reserved (DEFAULT)	Reserved
<b>PULL LOW</b>	USE SHORT RESET	BYPASS PCI PLL	BYPASS ACPI BCLK	BYPASS IDE PLL	USE EEPROM PCIE STRAPS	Reserved	Reserved

Note: SB700 has 15K internal PU FOR PCI\_AD[30:23]

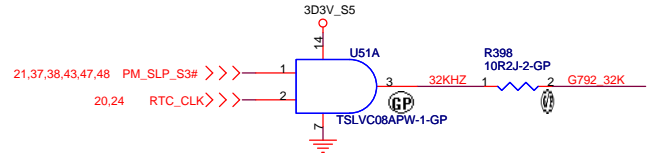
<Core Design>

**Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

<b>ATI-SB700 STRAPPING (5/5)</b>		
Size <b>A3</b>	Document Number <b>Olan</b>	Rev <b>-1</b>
Date: Friday, April 18, 2008		
Sheet		58



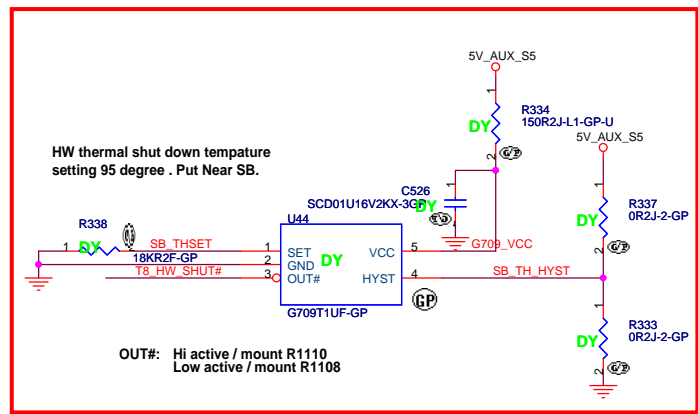
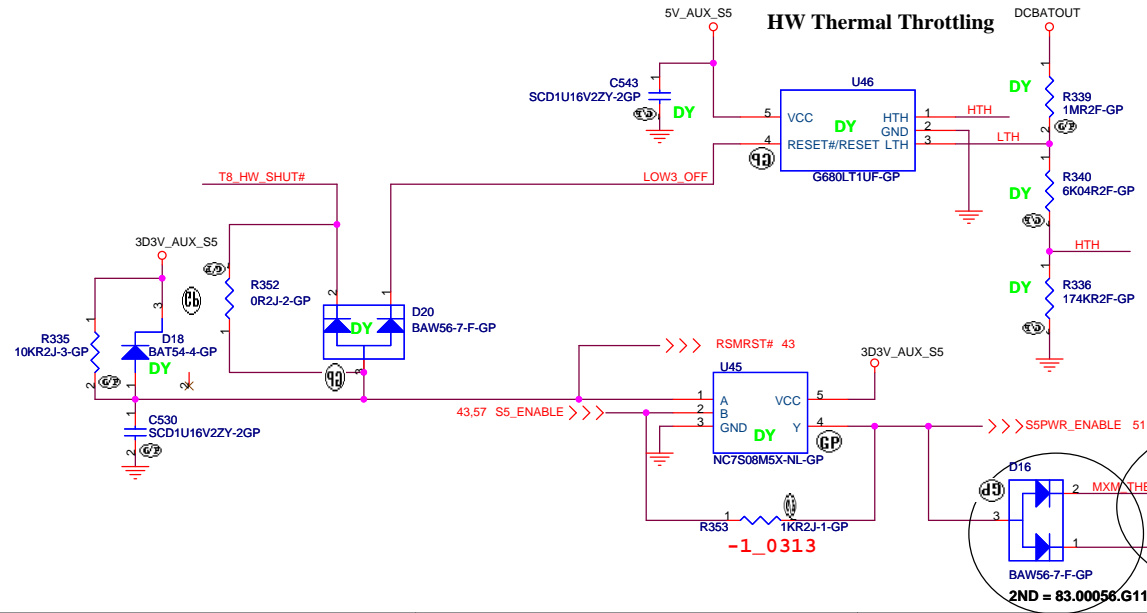
DXP1:108 Degree  
DXP2:H/W Setting  
DXP3:88 Degree



32K suspend clock output

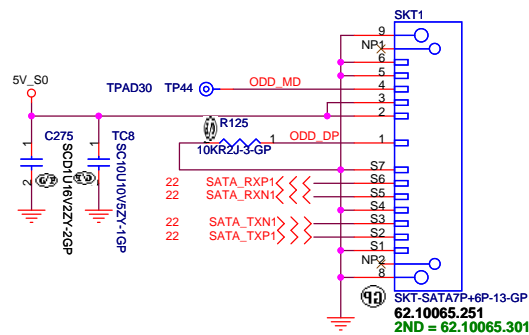
**BL3#**

**HW Thermal Throttling**



<Core Design>

# ODD Connector

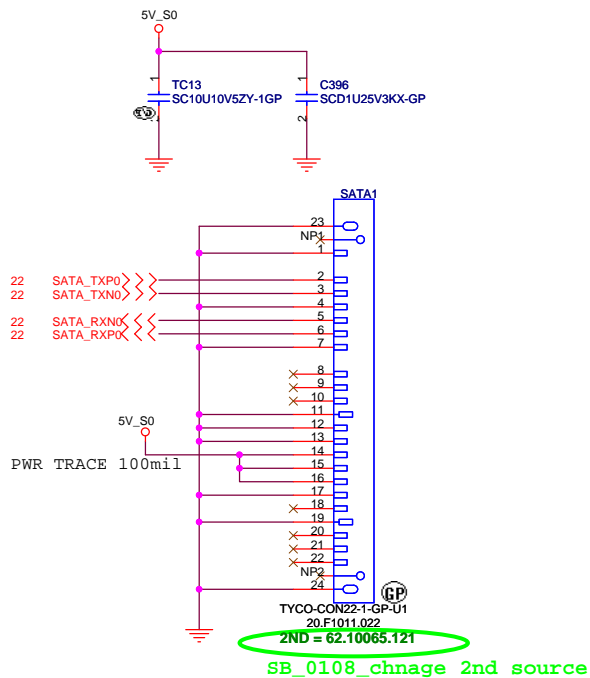


-1\_0305

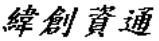
<Core Design>

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>CDROM</b>	
<b>Olan</b>	
Size	Document Number
Date: Friday, April 18, 2008	Sheet 26 of 58
Rev -1	

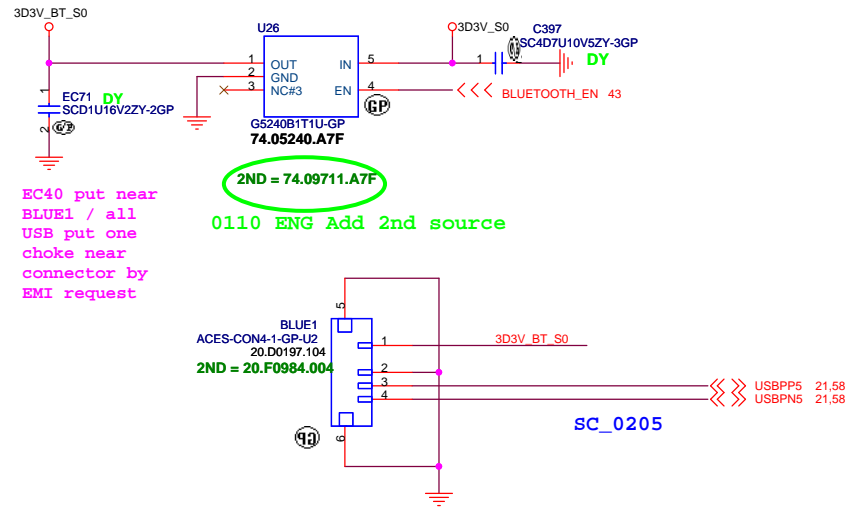
# SATA HDD Connector



<Core Design>

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>Title</b> <b>HDD</b>	
Size	Document Number
<b>Olan</b>	
Date: Friday, April 18, 2008	Sheet 27 of 58

# BLUETOOTH MODULE



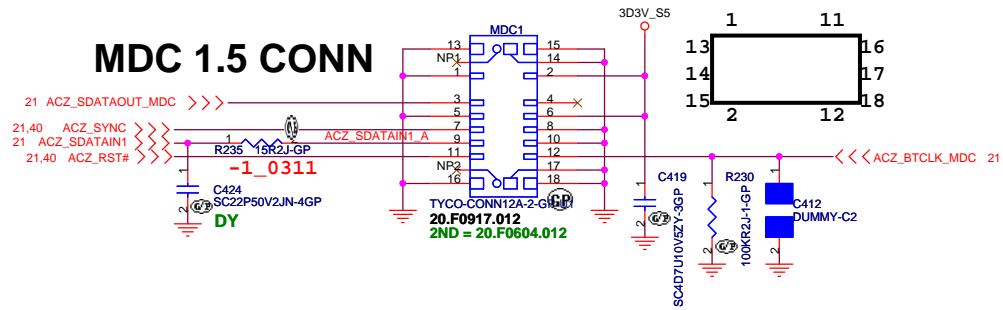
EC40 put near  
BLUE1 / all  
USB put one  
choke near  
connector by  
EMI request

<Core Design>

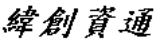
緯創資通 **Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

Title			<b>BLUETOOTH</b>
Size	Document Number	Rev	
		-1	
Date:	Friday, April 18, 2008	Sheet	28 of 58

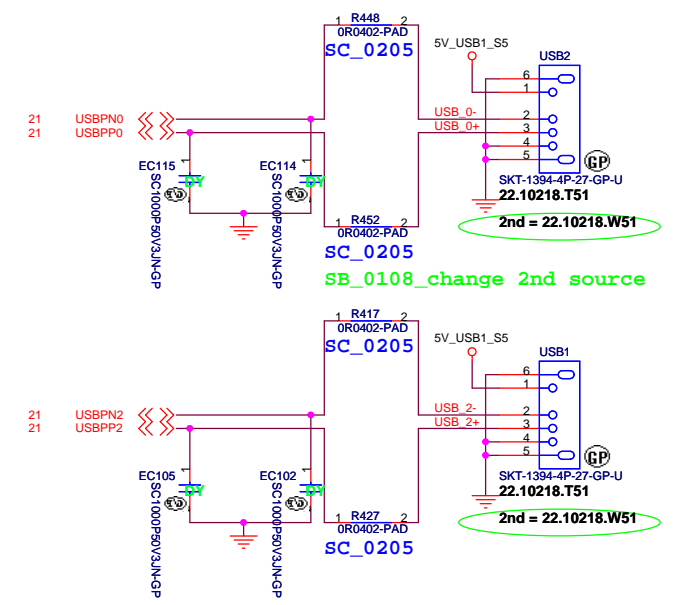
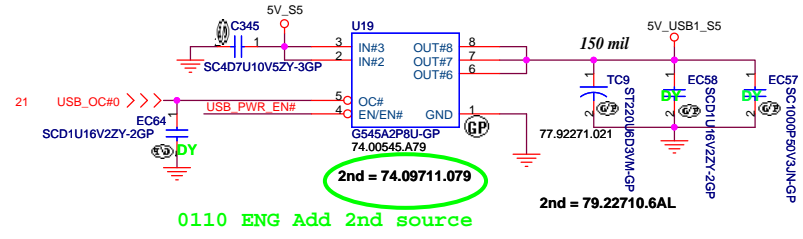
# MDC 1.5 CONN



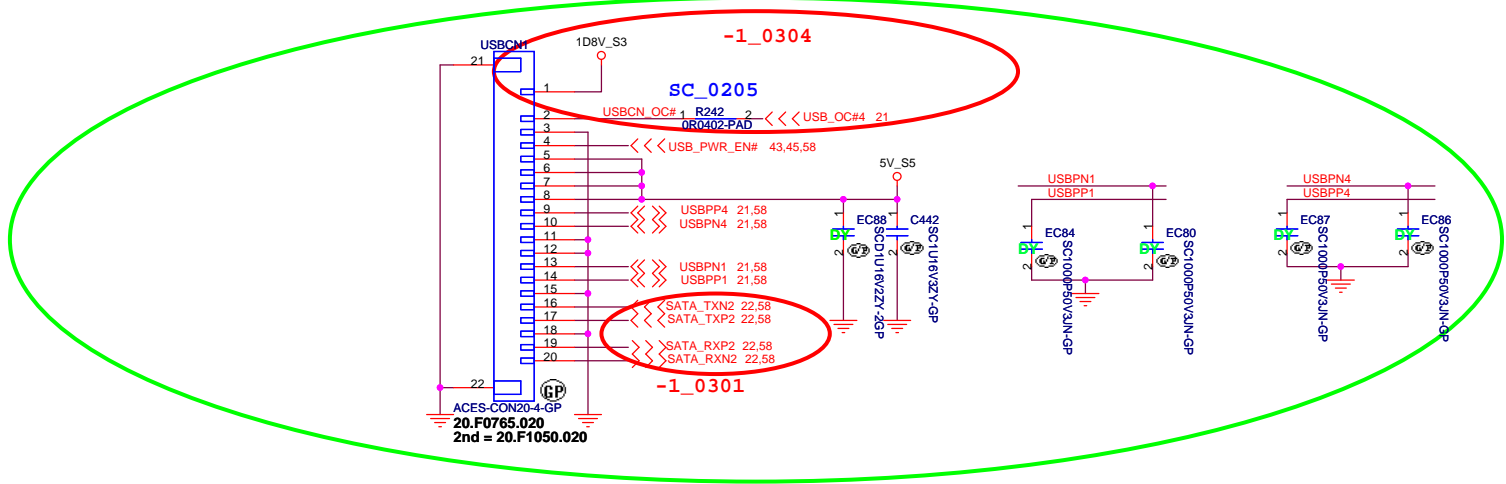
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 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
<b>Title</b> <b>MDC</b>		
Size	Document Number	Rev
	<b>Olan</b>	-1
Date:	Friday, April 18, 2008	Sheet 29 of 58





SB\_0102

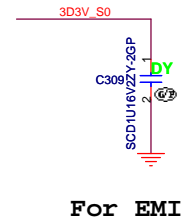
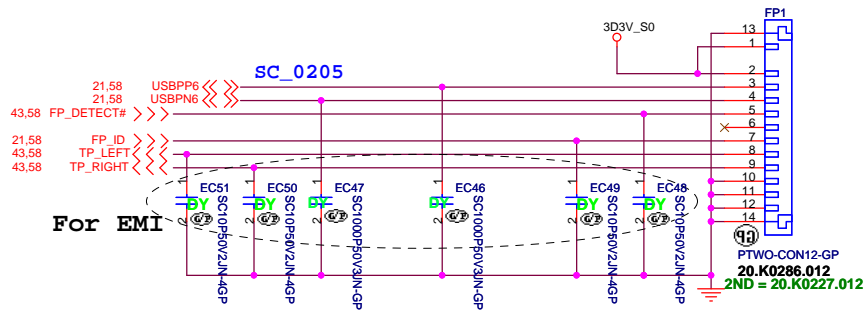


58 USBCN\_OC# <<< USBCN\_OC#


<Core Design>

<b>緯創資通</b>		<b>Wistron Corporation</b>	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title <b>USB</b>			
Size	Document Number		Rev
	<b>Olan</b>		-1
Date:	Friday, April 18, 2008	Sheet 30	of 58

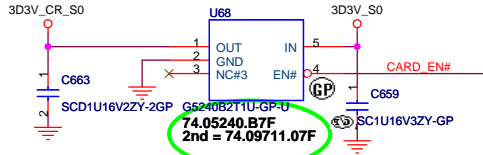
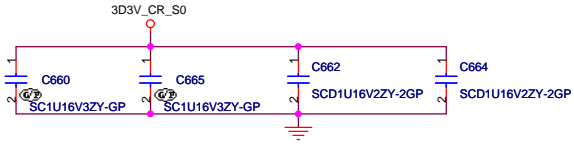
# Finger printer



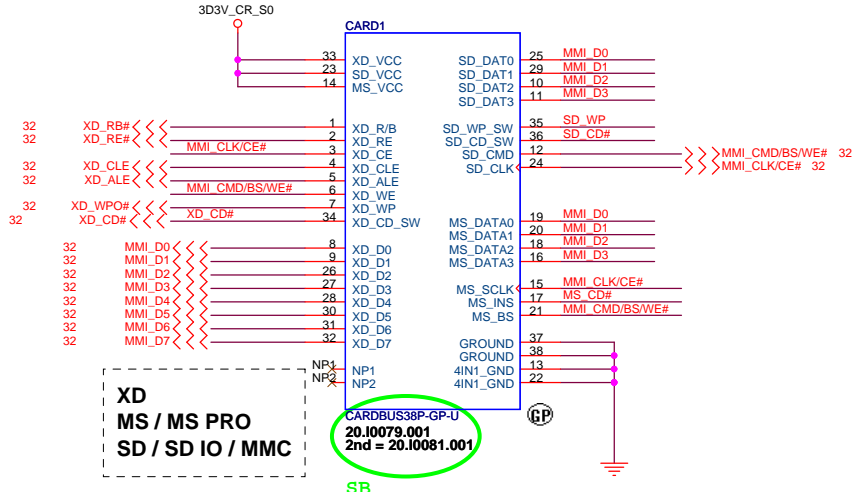
<Core Design>

 <b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title <b>Finger Printer</b>		
Size	Document Number	Rev
	<b>Olan</b>	-1
Date: Friday, April 18, 2008	Sheet 31 of 58	



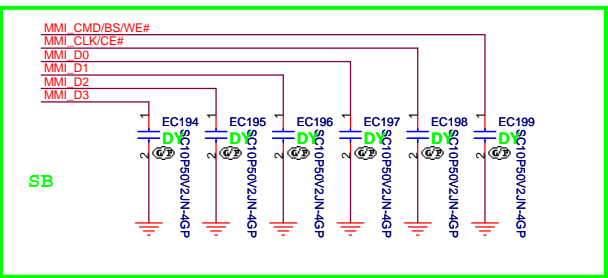


ENG Add 2nd source

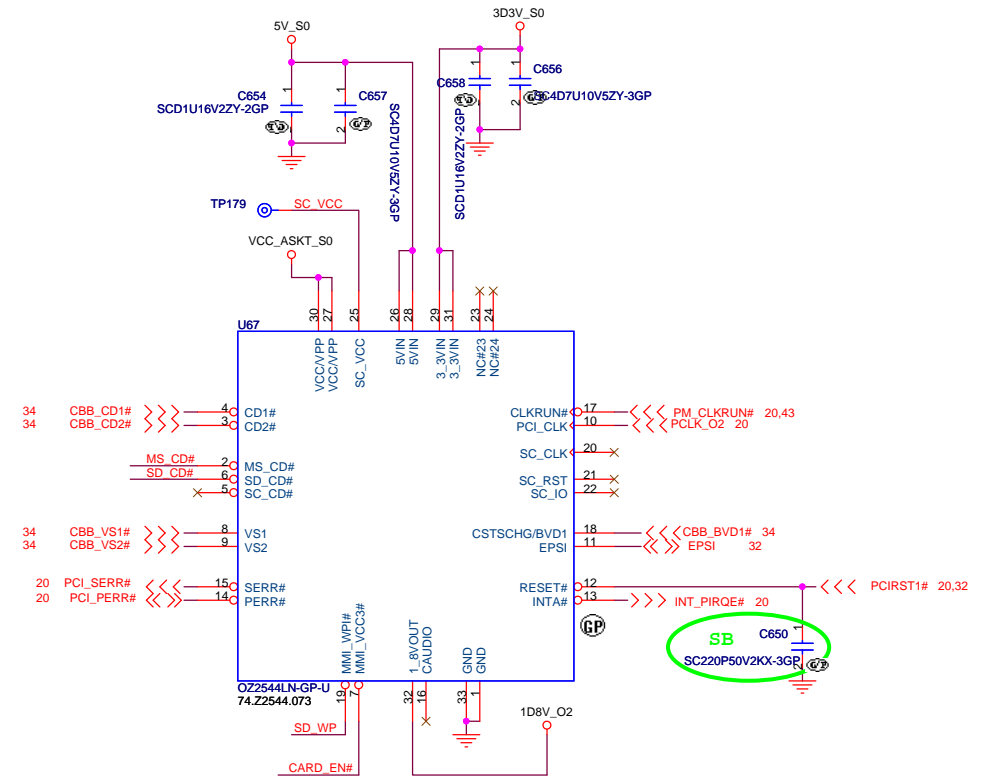


**XD**  
MS / MS PRO  
SD / SD IO / MMC

SB



SB



**SB**  
C650  
SC220P50V2KX-3GR

<Core Design>

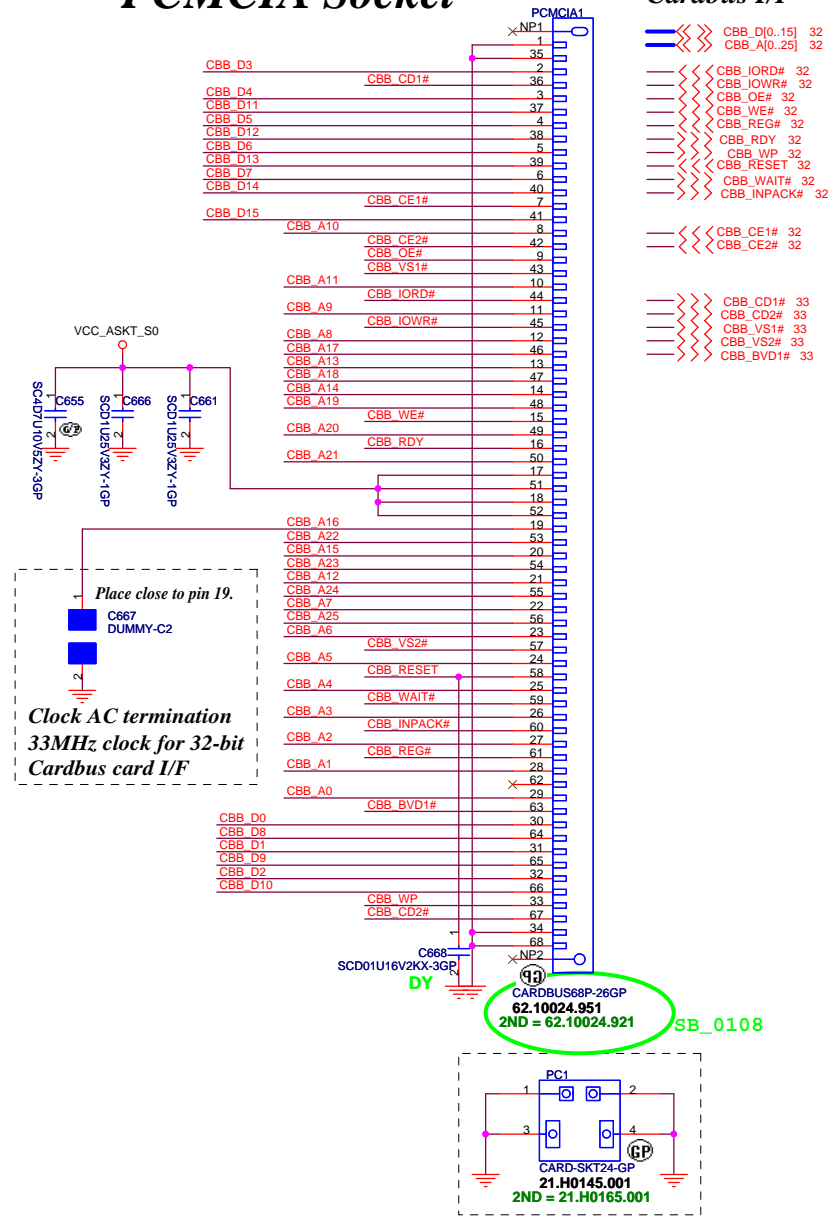
**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **Card Reader Connector**

Size: <b>A3</b>	Document Number:	Rev: <b>-1</b>
Date: <b>Friday, April 18, 2008</b>	Sheet: <b>33</b> of <b>58</b>	

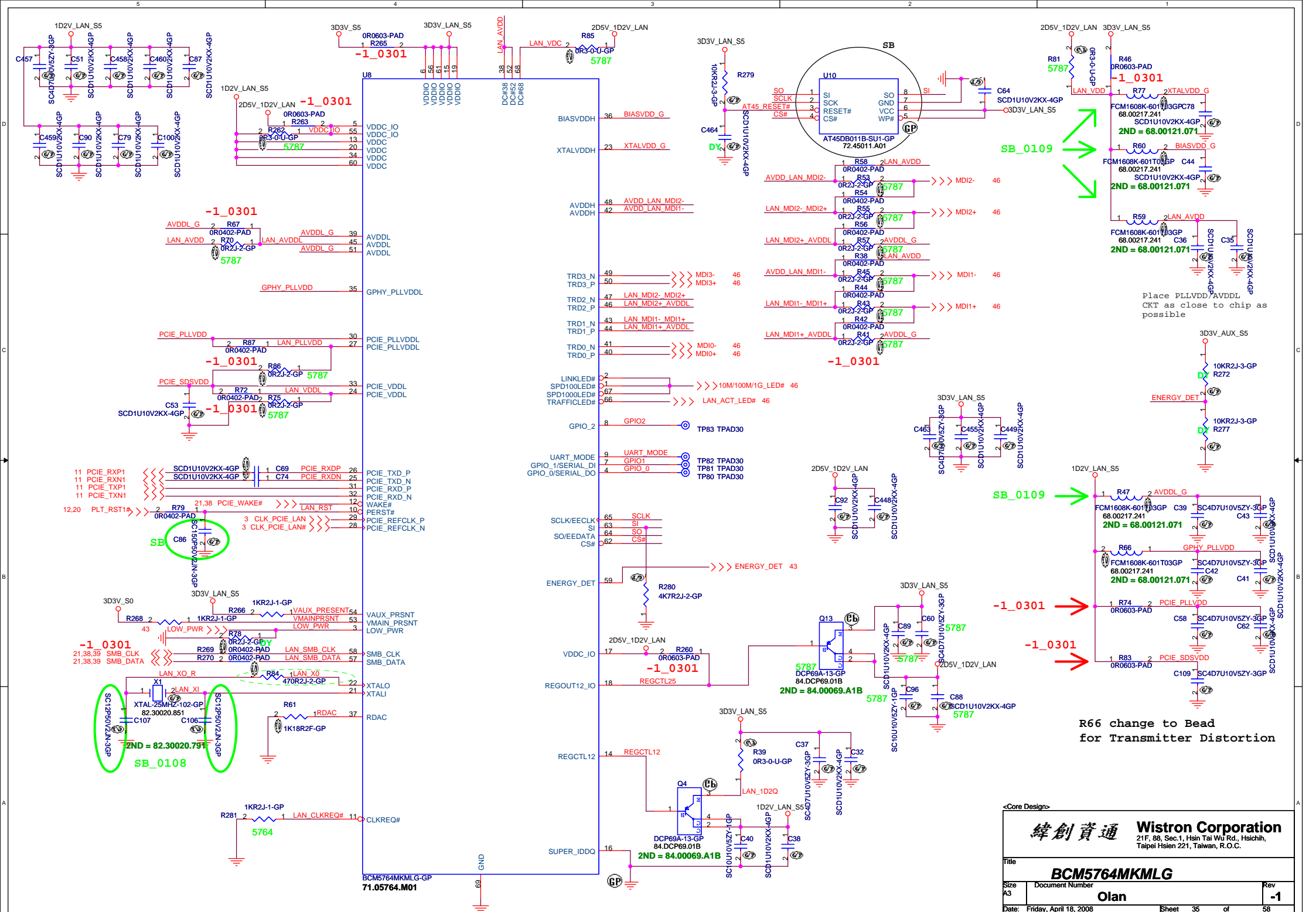
# PCMCIA Socket

# Cardbus I/F



<Core Design>

		<b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
PCMCIA			
Size	Document Number	Rev	
A3	Olan	-1	
Date:	Friday, April 18, 2008	Sheet	34 of 58



Place PLLVDD/AVDDL CKT as close to chip as possible

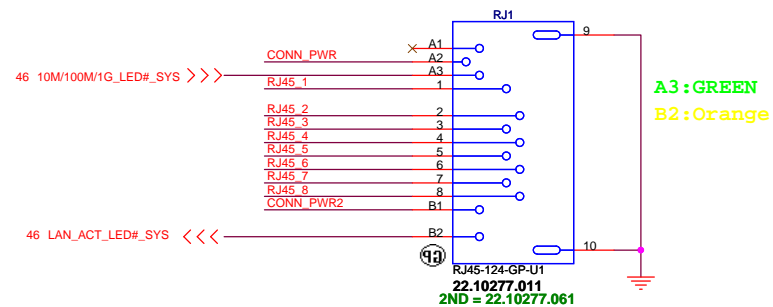
R66 change to Bead for Transmitter Distortion

<Core Design>

**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

File	<b>BCM5764MKMLG</b>	
Size	Document Number	Rev
A3	<b>Olan</b>	<b>-1</b>
Date:	Friday, April 18, 2008	Sheet 35 of 58

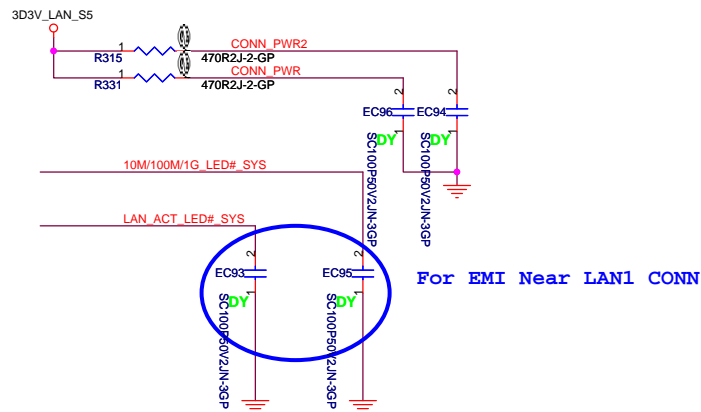
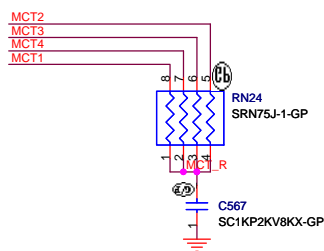
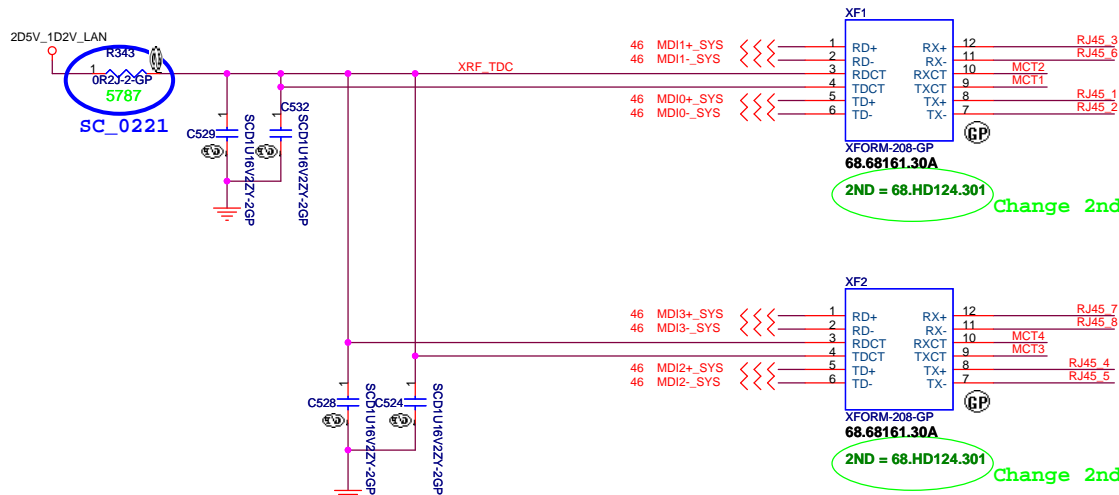
# LAN Connector



LAN Link: Green(A3), behavior is the same for 10/100/1000 bits

LAN Data: Yellow(B2), when LAN is transferring data.

## GIGA Lan Transformer



<Core Design>

緯創資通 Wistron Corporation  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

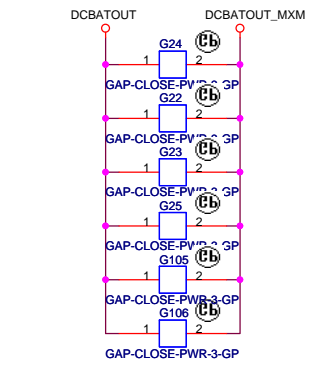
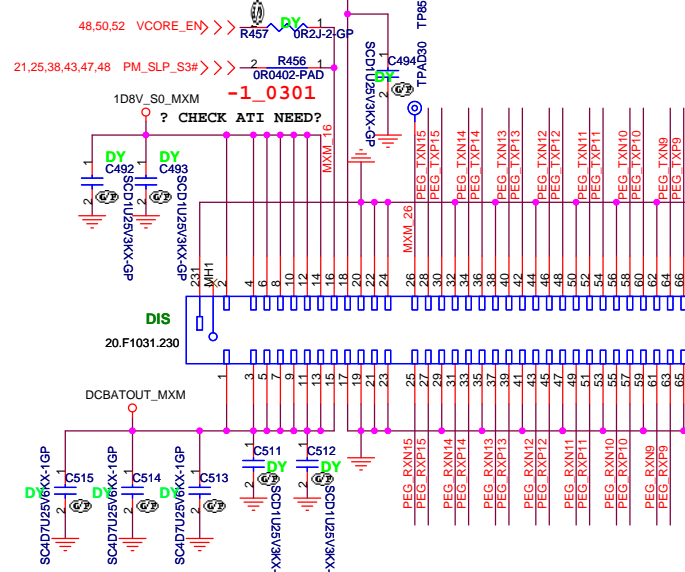
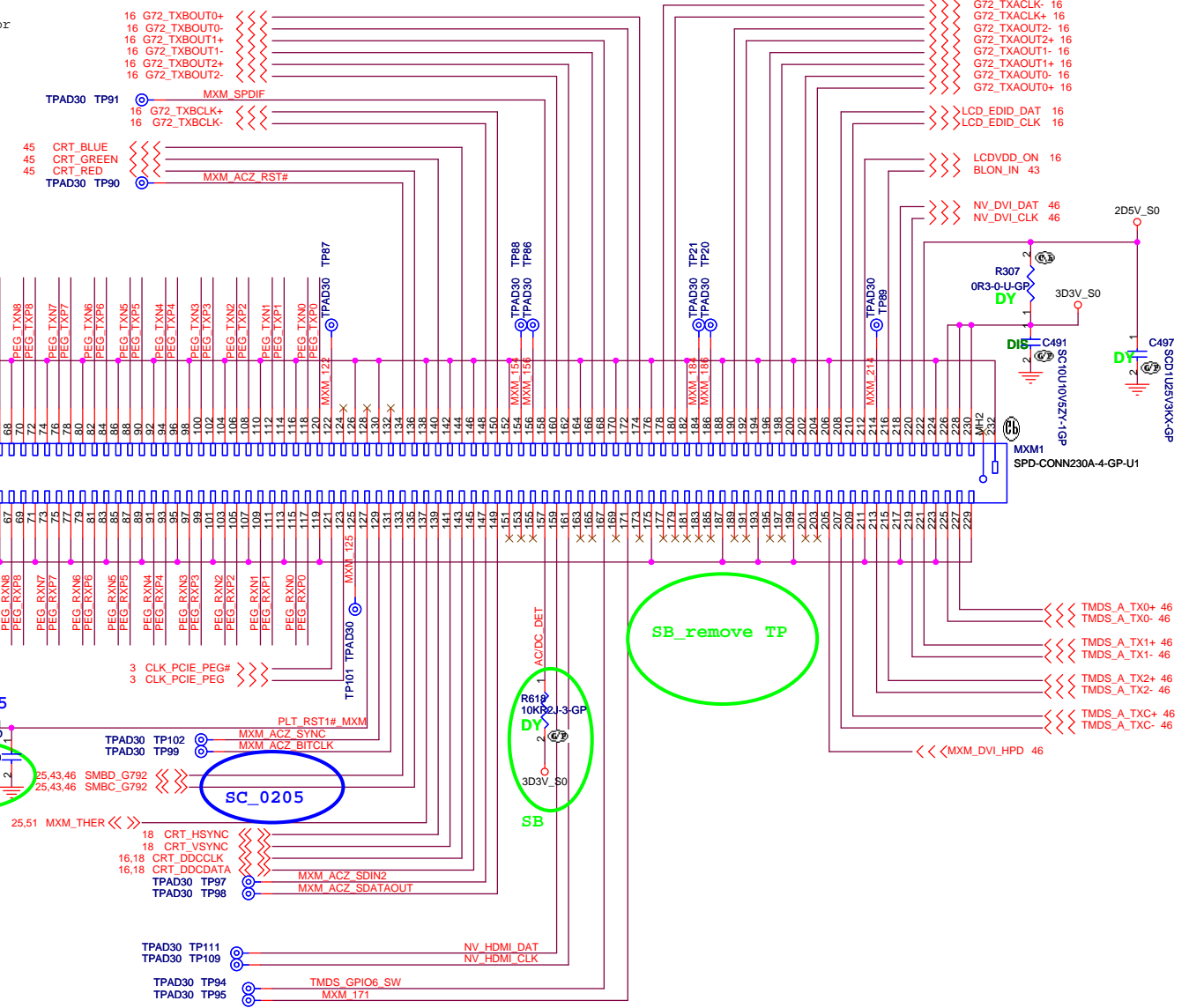
Title <b>LAN CONN</b>		
Size <b>A3</b>	Document Number <b>Olan</b>	Rev <b>-1</b>
Date Friday, April 18, 2008	Sheet 36	of 58



NV SMBus  
 A(pin143&145) : VGA(CRT) / DOCK  
 B(pin218&220) : DVI  
 C(pin208&210) : HDMI / TPI / LVDS

Put near graphic connector

11 PEG\_TXP[15.0] <<>>  
 11 PEG\_TXN[15.0] <<>>  
 11 PEG\_RXP[15.0] <<>>  
 11 PEG\_RXN[15.0] <<>>



<Core Design>

**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

Title: **Graphic MXM CONN**

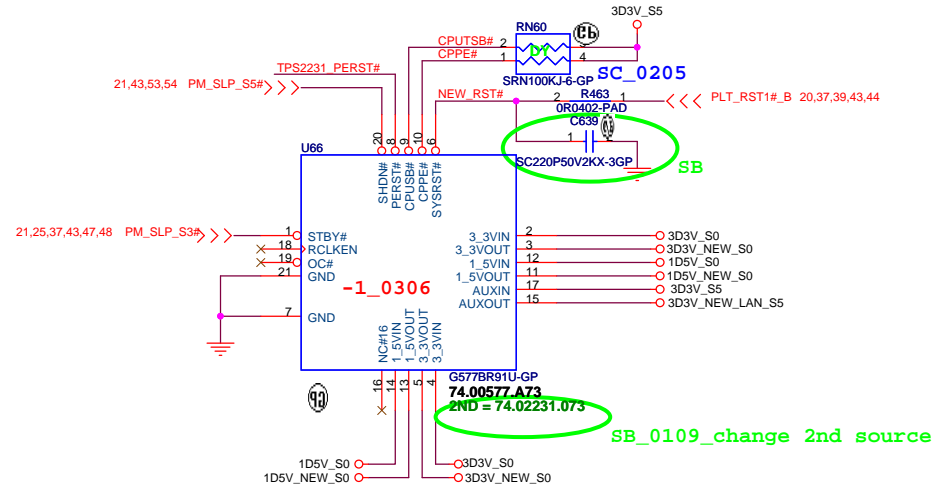
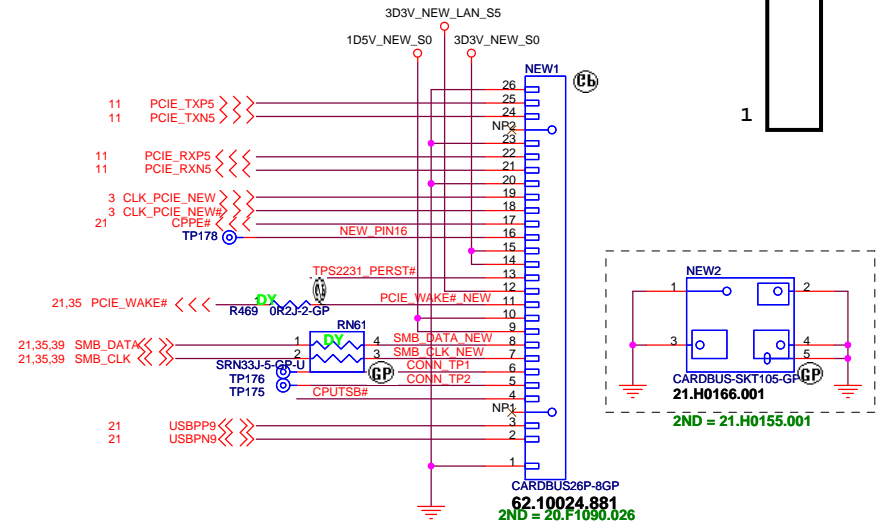
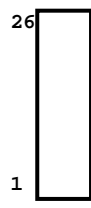
Size: A3 Document Number: **Olan** Rev: -1

Date: Friday, April 18, 2008 Sheet 37 of 58

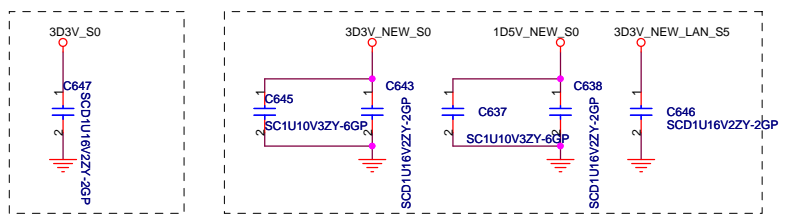
# NEWCARD Connector

Reserve the symbol for bottom side connector

## TOP VIEW



Place them Near to Chip Place them Near to Connector



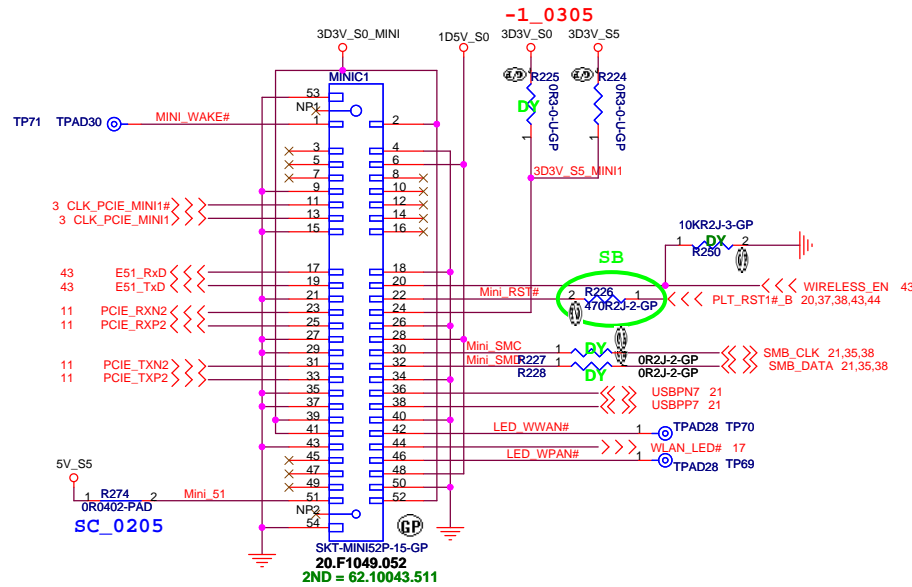
<Core Design>

**緯創資通 Wistron Corporation**  
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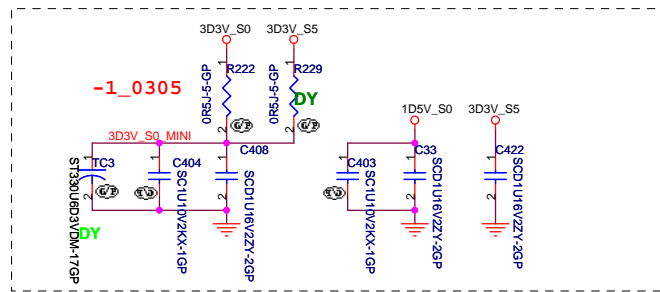
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Size: <b>A3</b>	Document Number: <b>Olan</b>	Rev: <b>-1</b>
Date: <b>Friday, April 18, 2008</b>	Sheet: <b>38</b> of <b>58</b>	

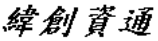
# Mini Card Connector(WLAN)

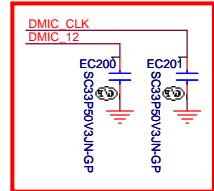
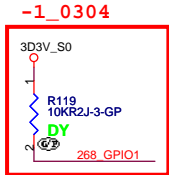
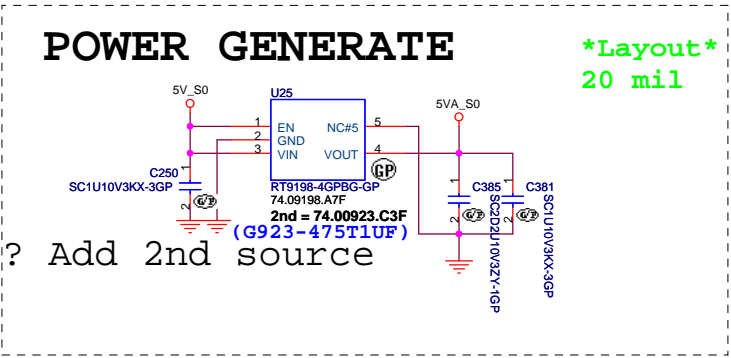
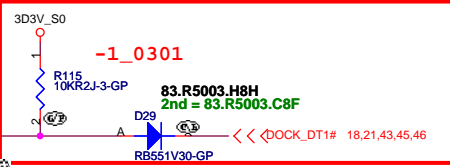
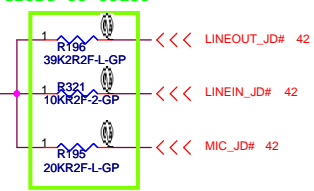
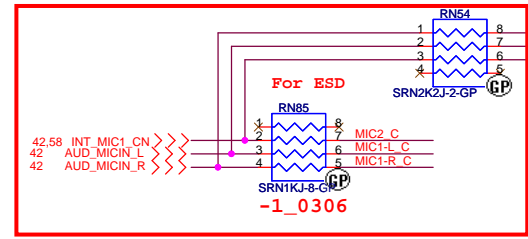
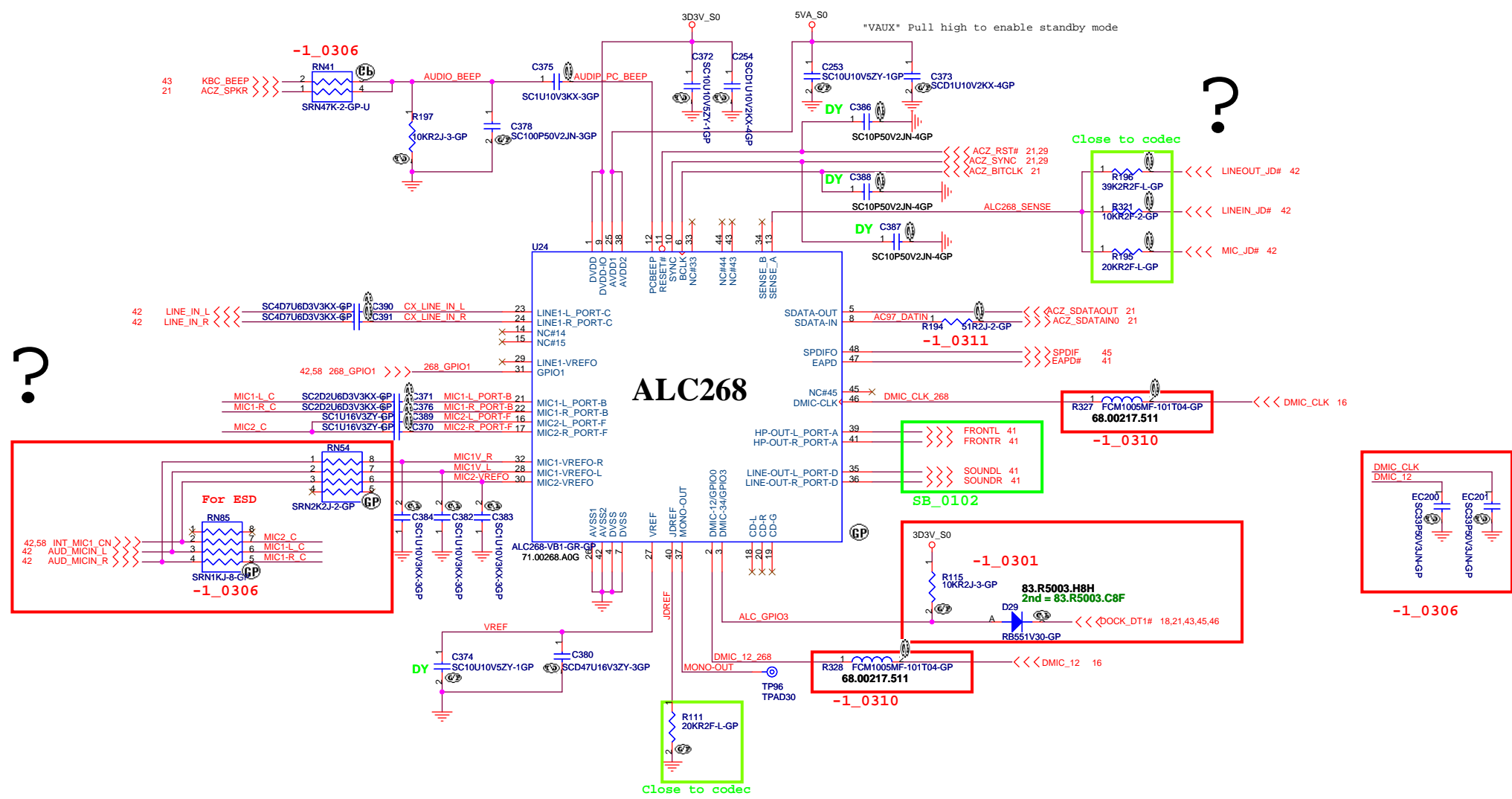


Place near MINIC1

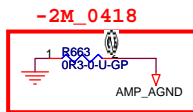
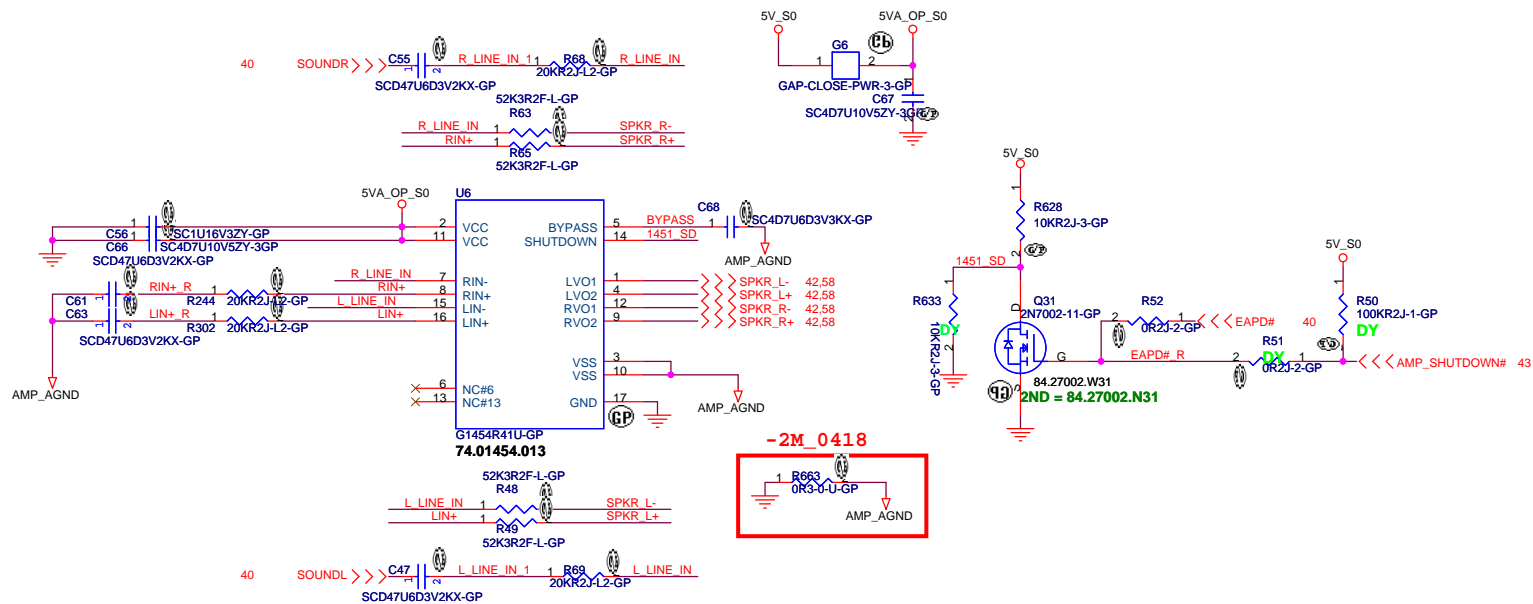


<Core Design>

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Title		
<b>Mini Card</b>		
Size	Document Number	Rev
<b>A3</b>	<b>Olan</b>	<b>-1</b>
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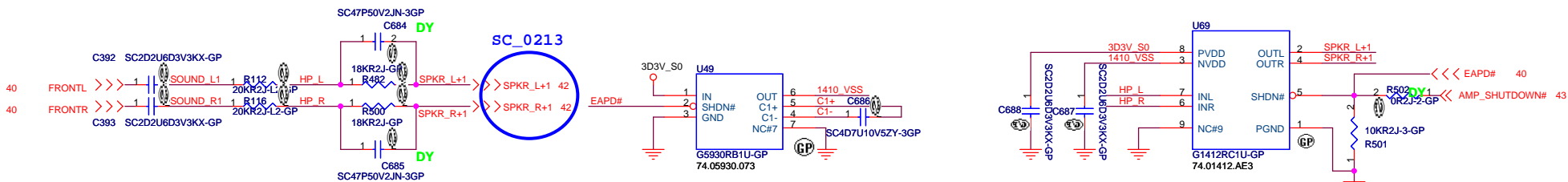


# AUDIO OP AMPLIFIER



SB

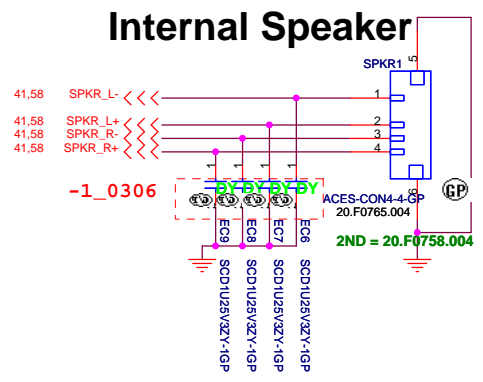
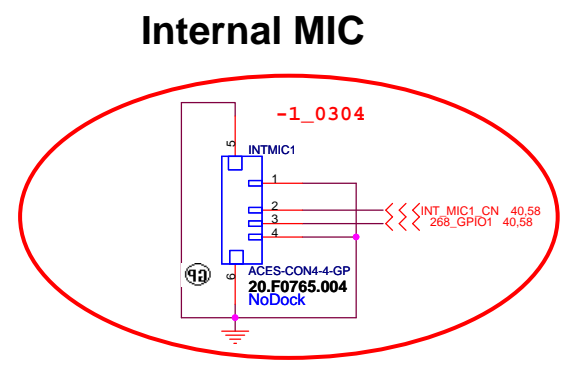
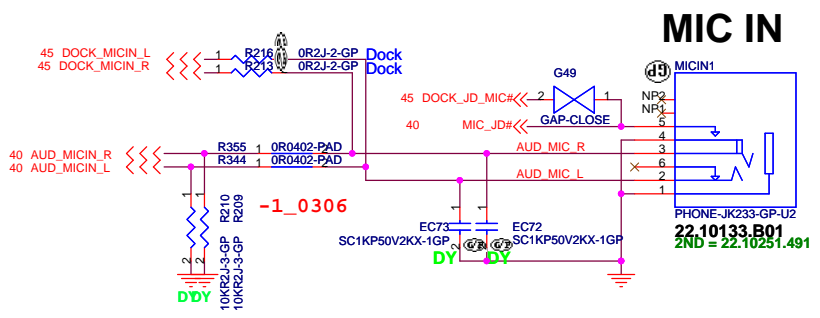
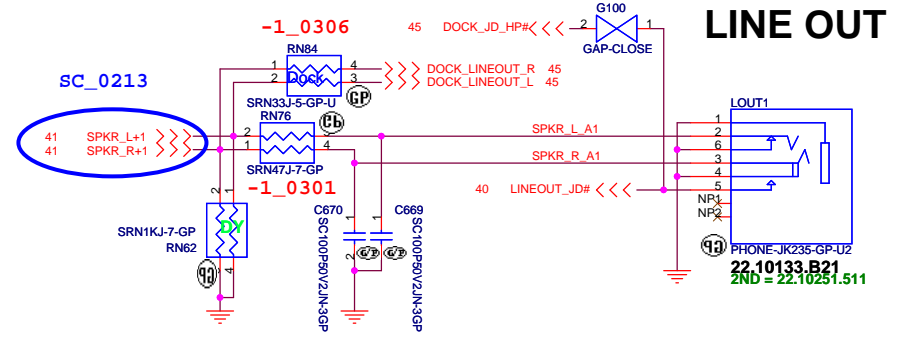
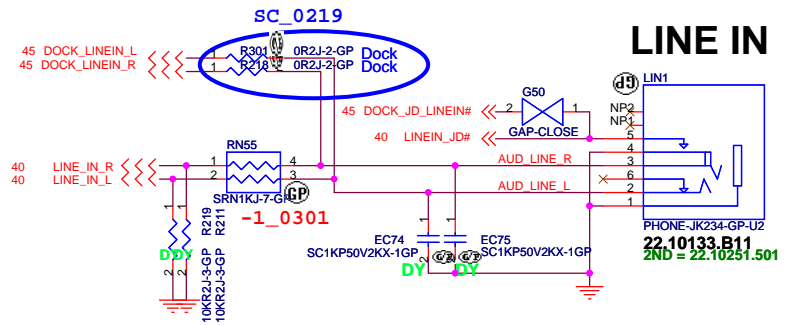
## KBC\_MUTE\_GPIO8

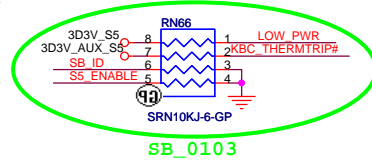
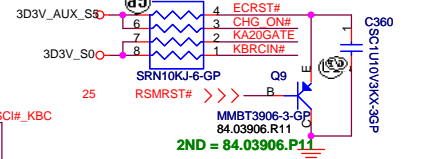
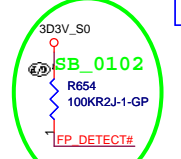
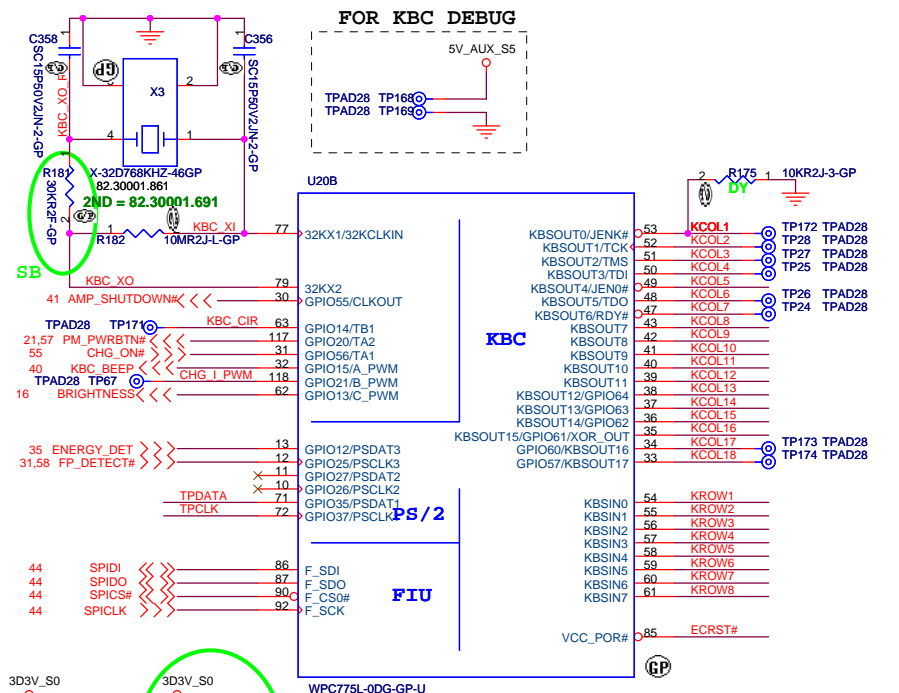
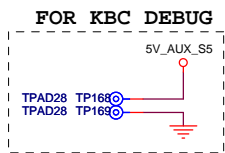
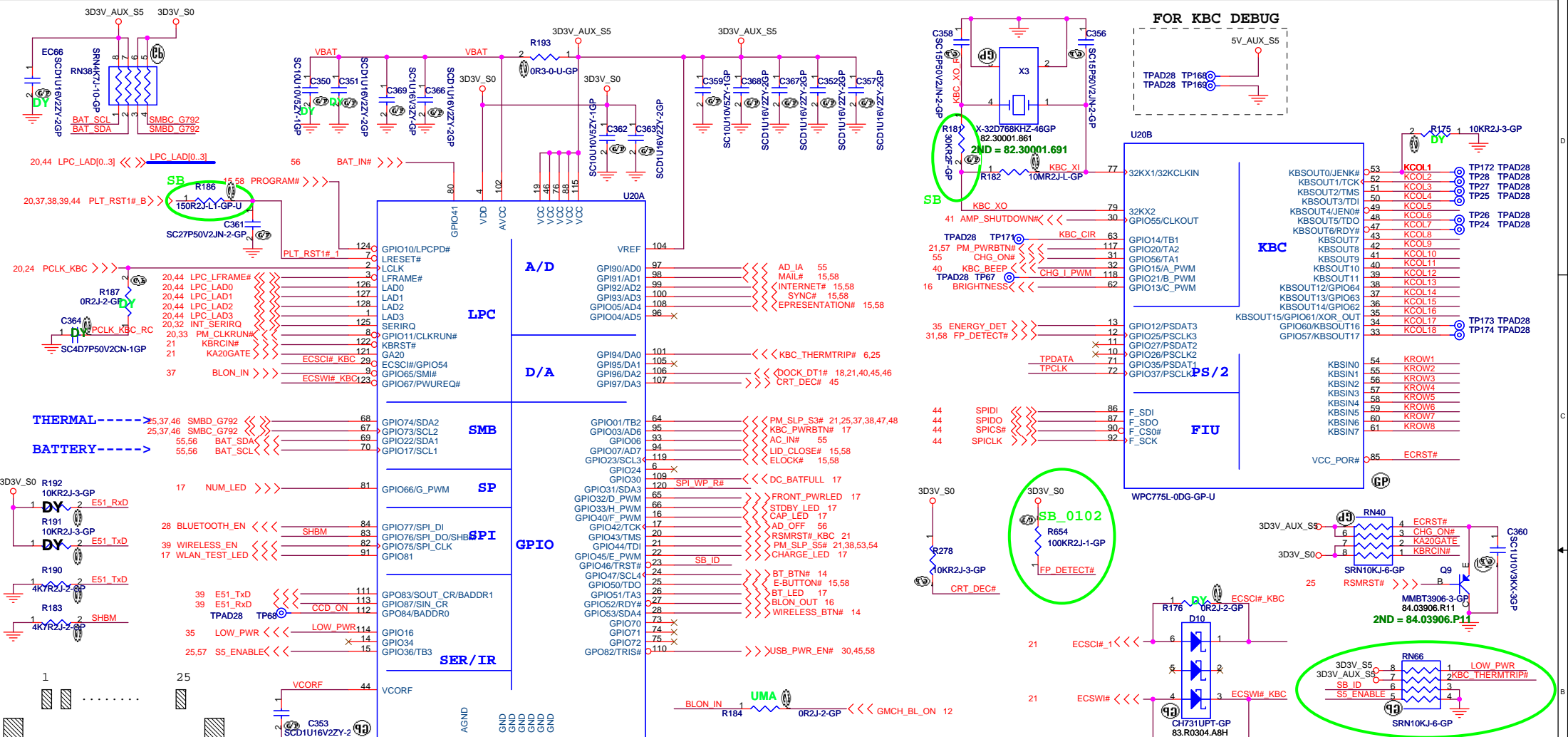


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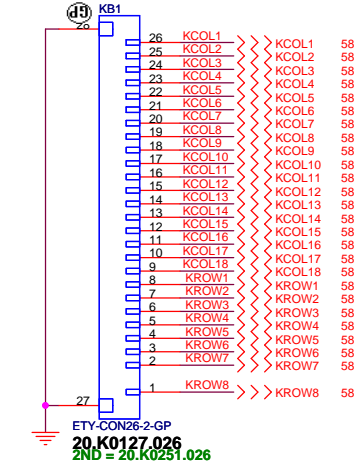
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Title		
<b>AUDIO AMP</b>		
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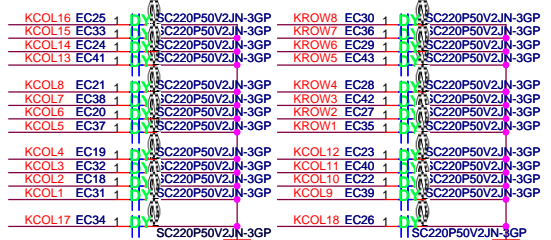


CHECK KB SPEC. AND PIN DEFINE

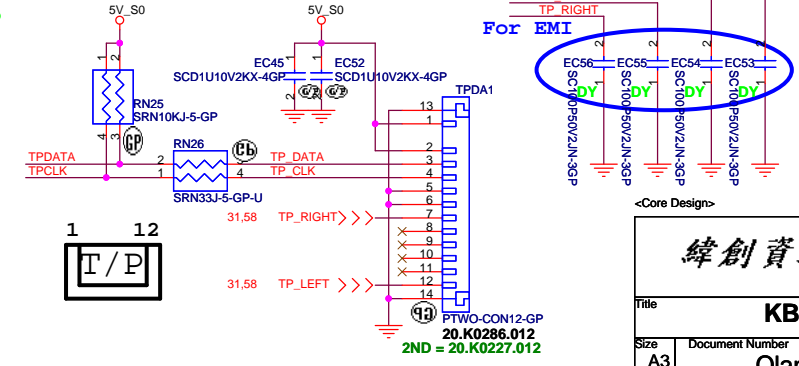


### Internal Keyboard Connector

EMI Bypass cap.



### TOUCH PAD



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**KBC WPC775**

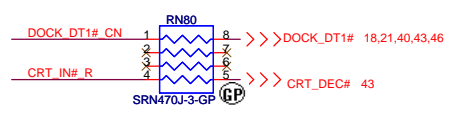
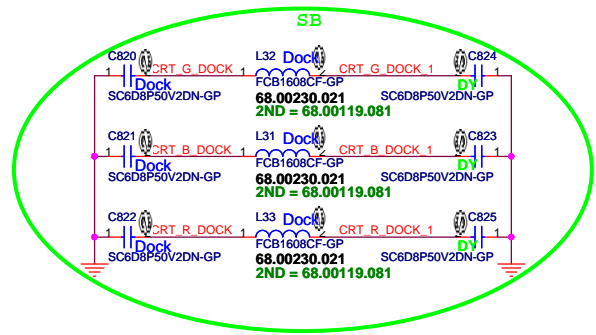
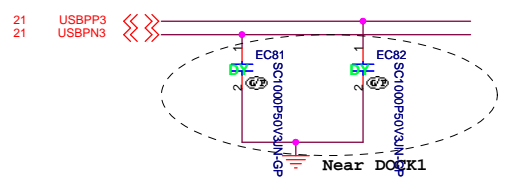
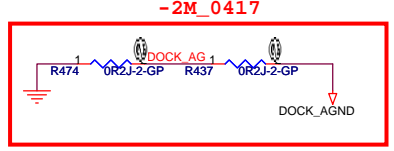
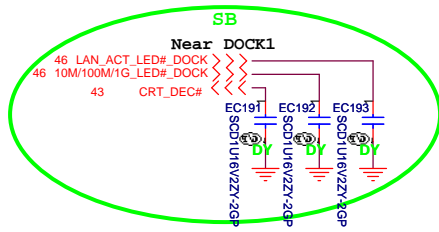
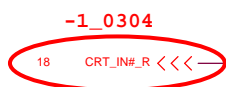
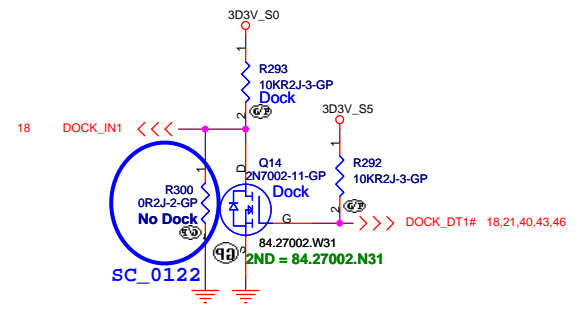
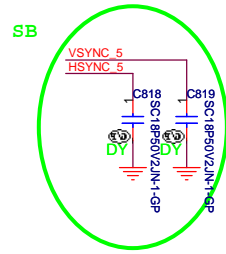
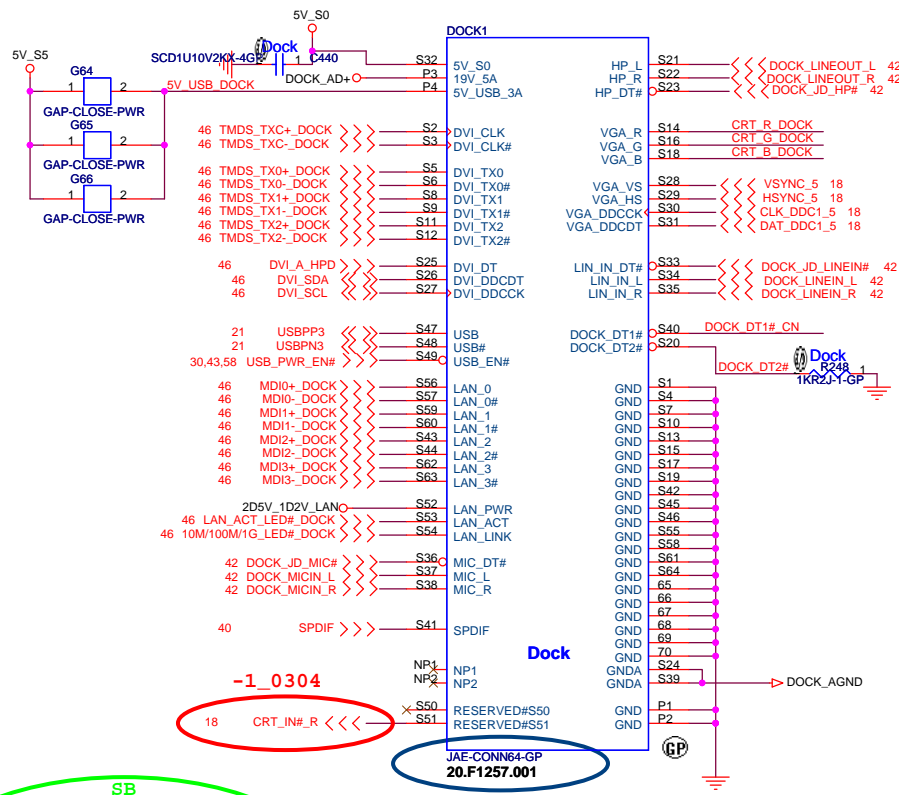
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Size: **A3** Document Number: **Olan** Rev: **-1**

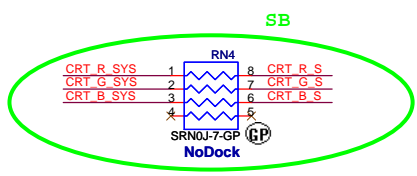
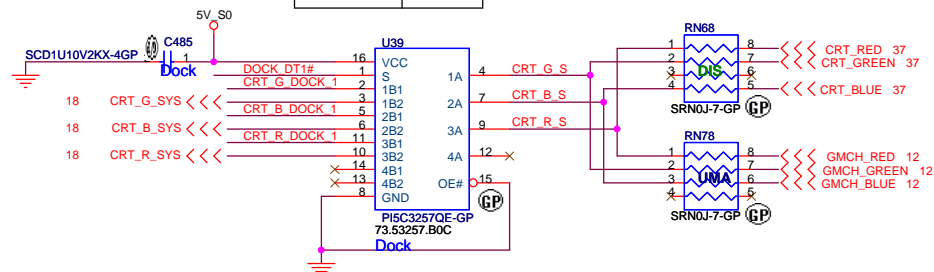
Date: **Friday, April 18, 2008** Sheet: **43** of **58**







Function	CRT
SYSTEM	H
DOCK	L



<Core Design>

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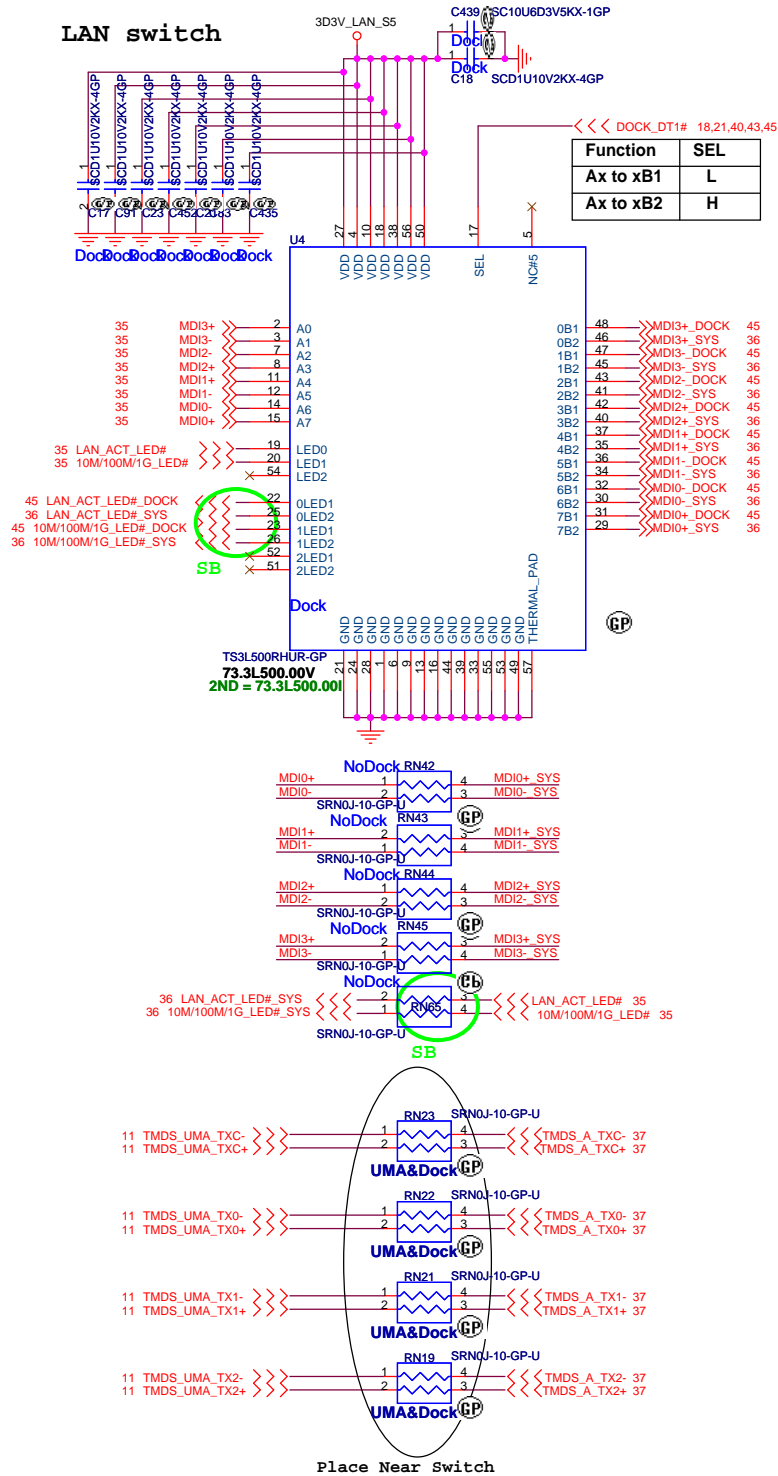
Title

**EASY PORT4**

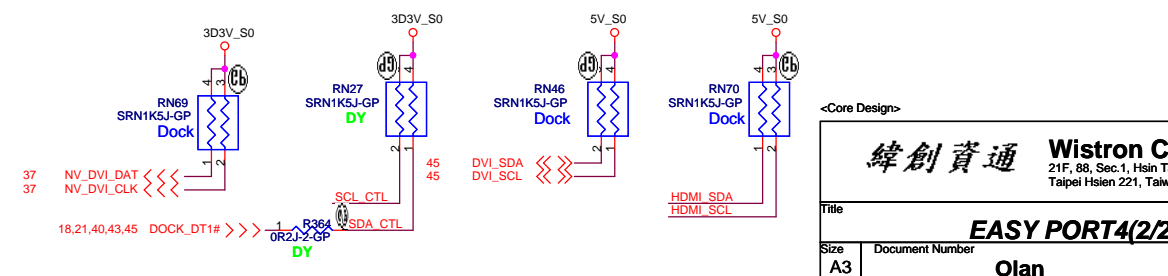
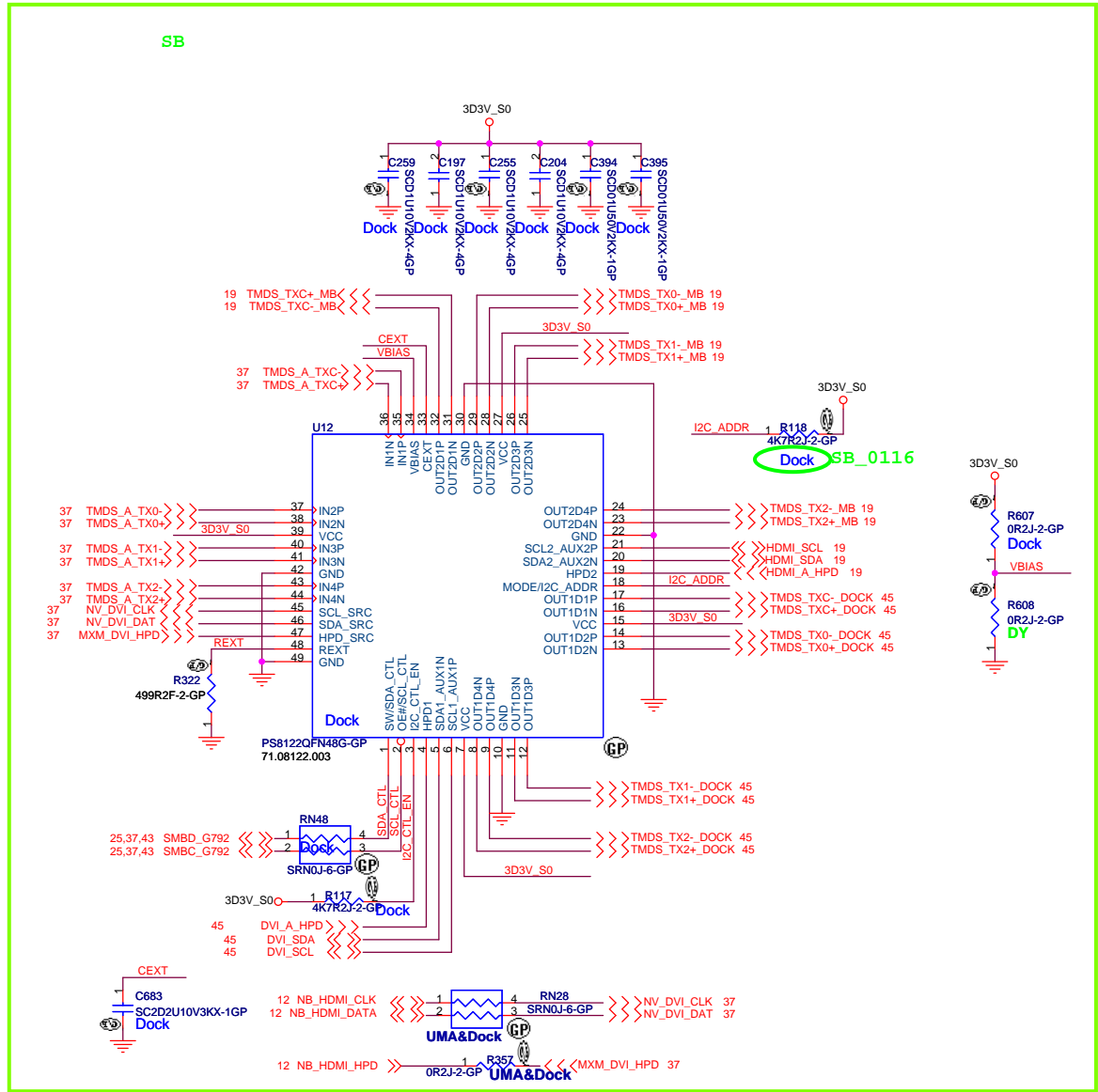
Size A3 Document Number Olan Rev -1

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**LAN switch**



**SB**



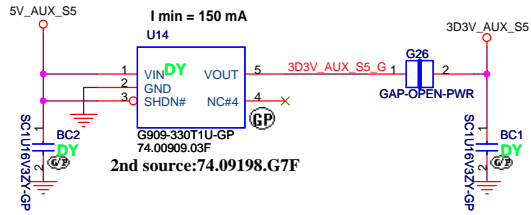
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**EASY PORT4(2/2)**

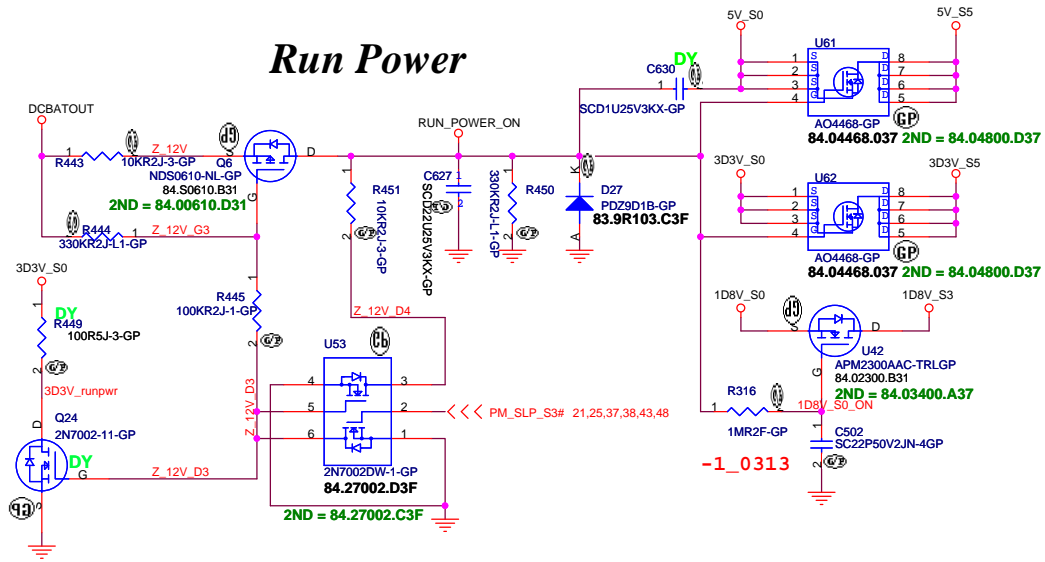
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# Aux Power 3D3V\_AUX\_S5

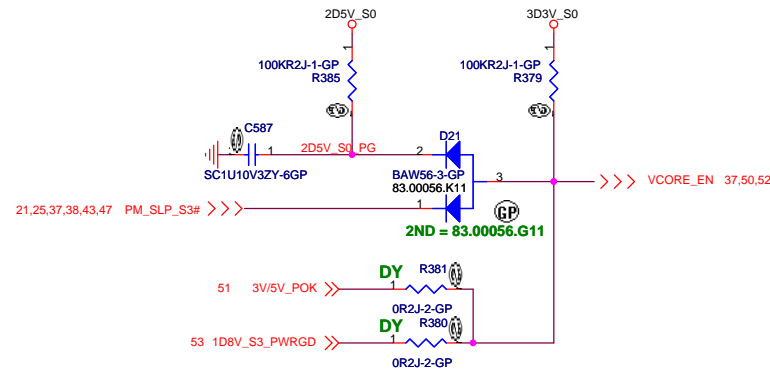


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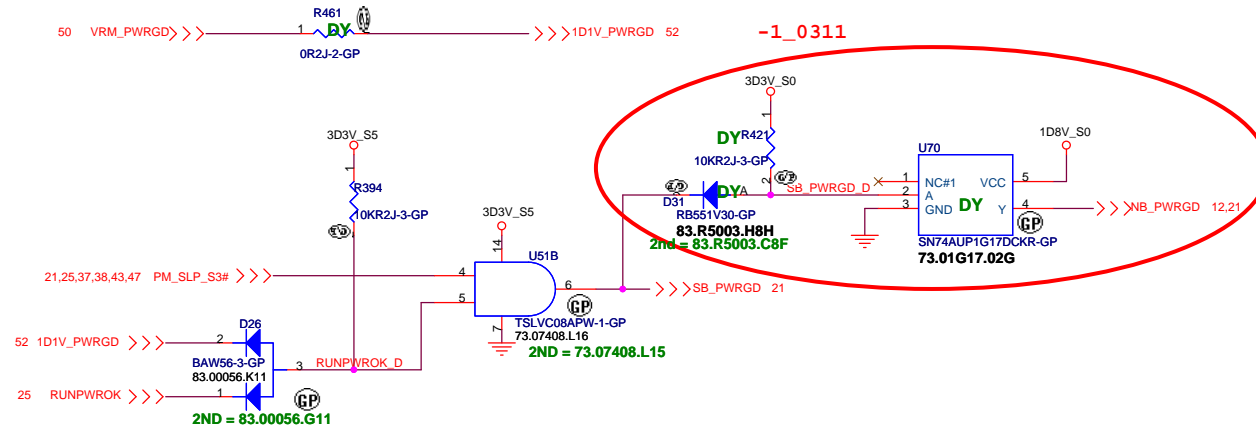


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<b>Title RUN POWER and 3D3V_AUX_S5</b>	
Size <b>A3</b>	Document Number <b>Olan</b>
Date: <b>Friday, April 18, 2008</b>	Rev <b>-1</b>
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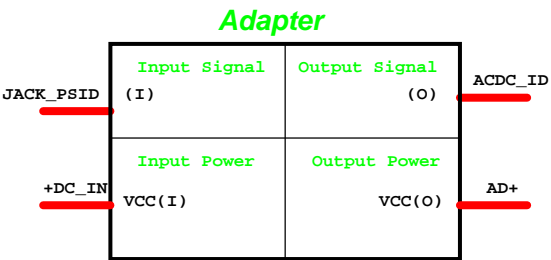


P/H @ 1D8V\_S3 PAGE

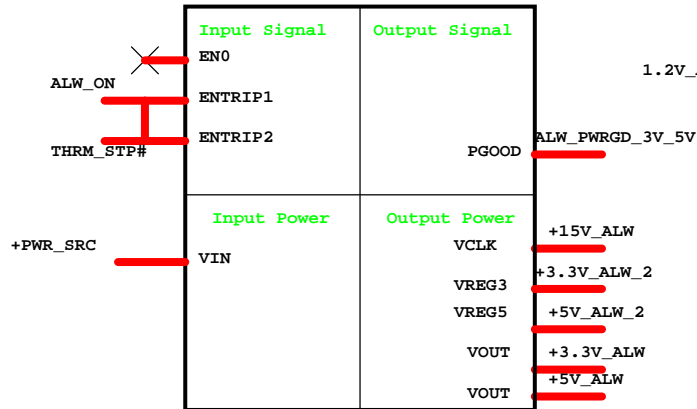


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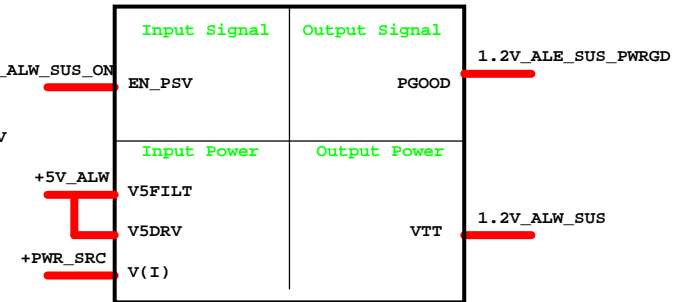
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Title		
<b>POWER ON LOGIC</b>		
Size	Document Number	Rev
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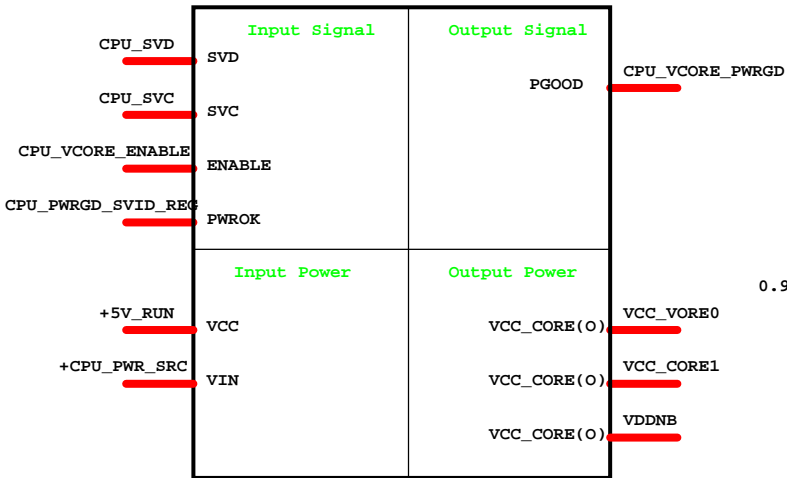
### SN0608098



### DCDC 1D2V(TPS5117)

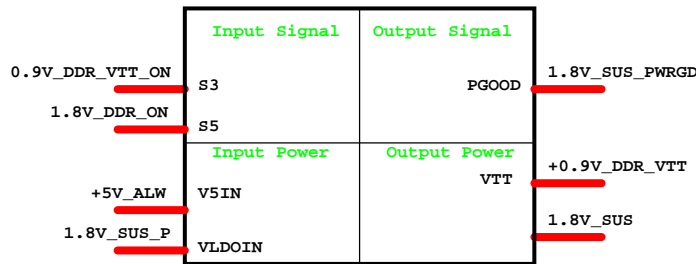


### CPU\_CORE ISL6265HRTZ

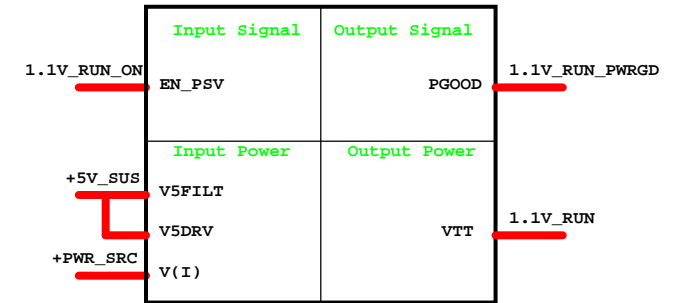


	S3	S5	VDDQ	VTTREF	VTT
S0	1	1	1	1	1
S3					
S4	0	0	0	0	0
S5					

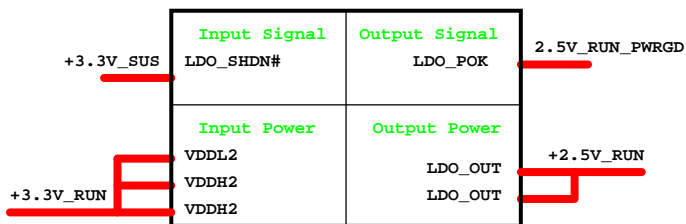
### 1D8V/0D9V(TPS5116)



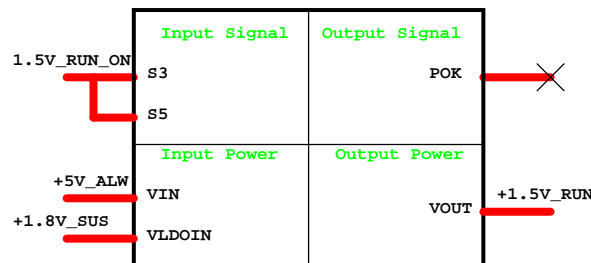
### 1D1V(TPS5117)



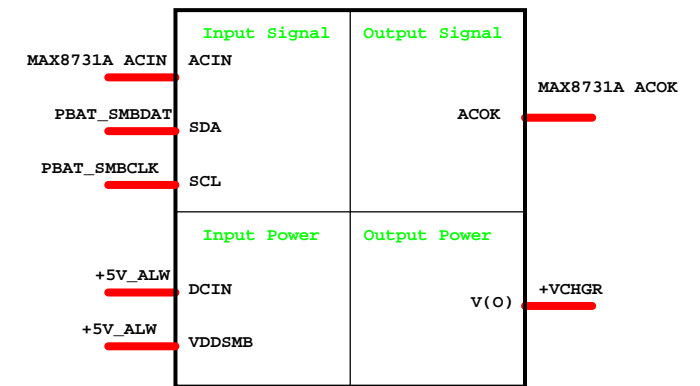
### 2.5V LDO EMC4002



### 1.5V LDO



### CHARGER BQ24745



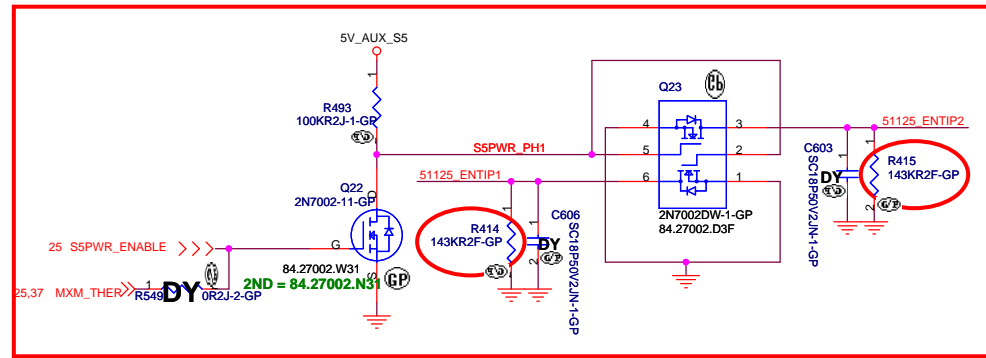
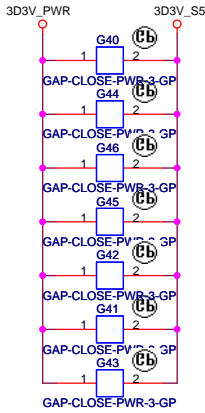
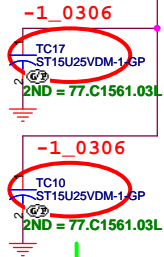
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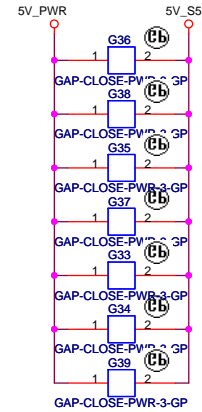


2080307\_Modify by

Brian  
ACOUSTIC NIOSE

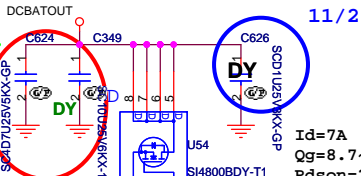


SB\_0102



2080307\_Modify by  
Brian  
ACOUSTIC NIOSE

Design Current = 6A  
Max Current = 7A  
OCP min = 10A  
  
Cyntec 7\*7\*3  
DCR=30mohm, Irating=6A  
Isat=13.5A



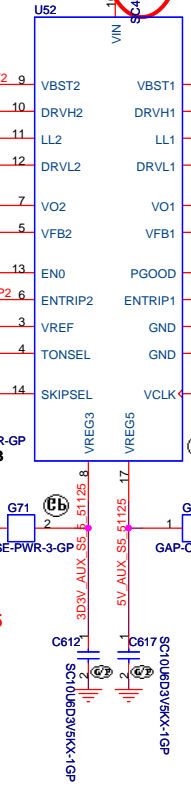
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Brian  
ACOUSTIC NIOSE

Id=7A  
Qg=8.7~13nC  
Rdson=23~30mohm

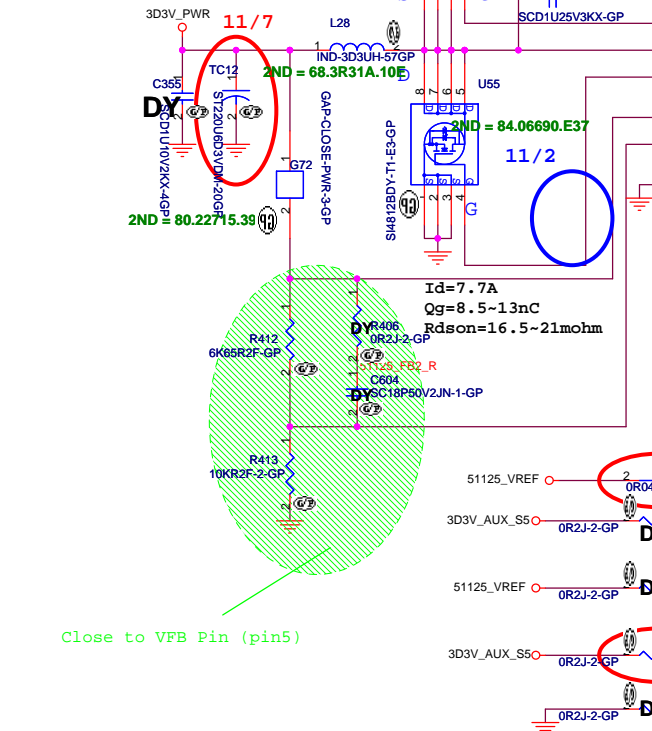
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Brian  
ACOUSTIC NIOSE

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Rdson=23~30mohm

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Max Current = 7A  
OCP min = 10A



2080114



Close to VFB Pin (pin5)

Id=7A  
Qg=8.7~13nC  
Rdson=23~30mohm

2ND = 84.08884.037

11/7

11/2

11/7

11/2

11/7

11/7

<Core Design>

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Title <b>DCDC 5V/3D3V (TPS51125)</b>		
Size A3	Document Number <b>Olan</b>	Rev <b>-1</b>
Date Friday, April 18, 2008	Sheet 51	of 58

20080307\_Modify by

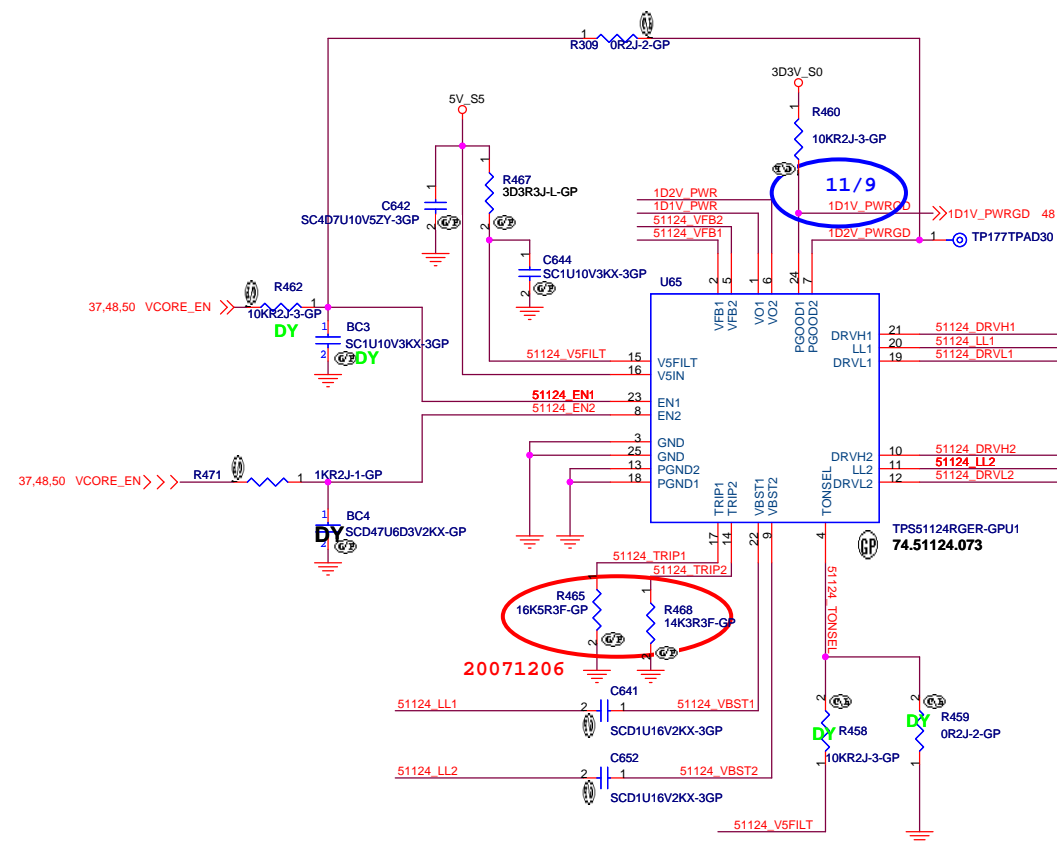
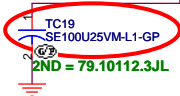
Brian  
ACOUSTIC NIOSE

$$V_{trip}(mV) = R_{trip}(Kohm) * 10(uA)$$

$$I_{ocp} = (V_{trip}/R_{dson}) + ((1/(2*L*f)) * ((V_{in}-V_{out}) * V_{out}) / V_{in})$$

I/P cap: 10U 25V K1206 X5R/ 78.10622.52L

-1\_0306



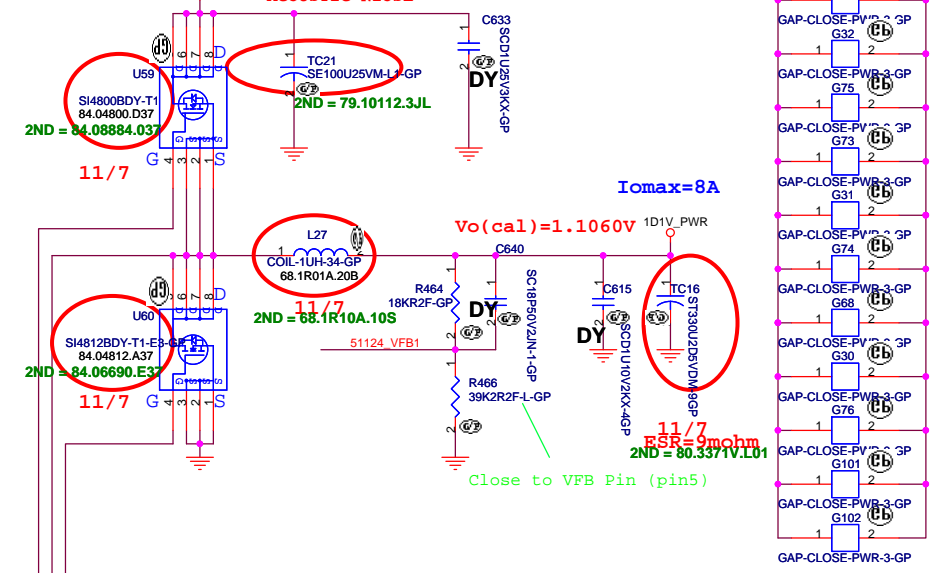
	GND	OPEN	V5FILT
TONSEL	240k/CH1 300k/CH2	300k/CH1 360k/CH2	360k/CH1 420k/CH2

$V_{out} = 0.758V * (R1+R2)/R2$  --> PWM mode

$V_{out} = 0.764V * (R1+R2)/R2$  --> Skip Mode

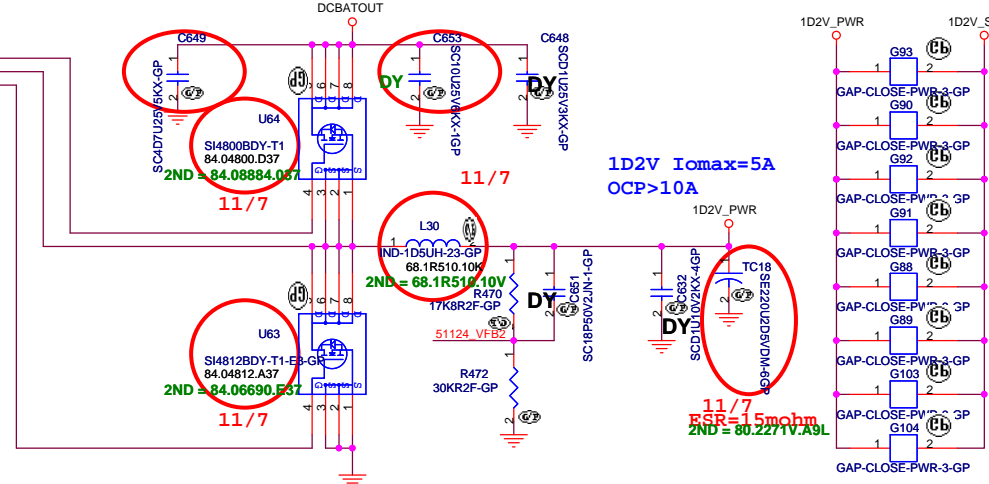
20080307\_Modify by

Brian  
ACOUSTIC NIOSE



20080307\_Modify by

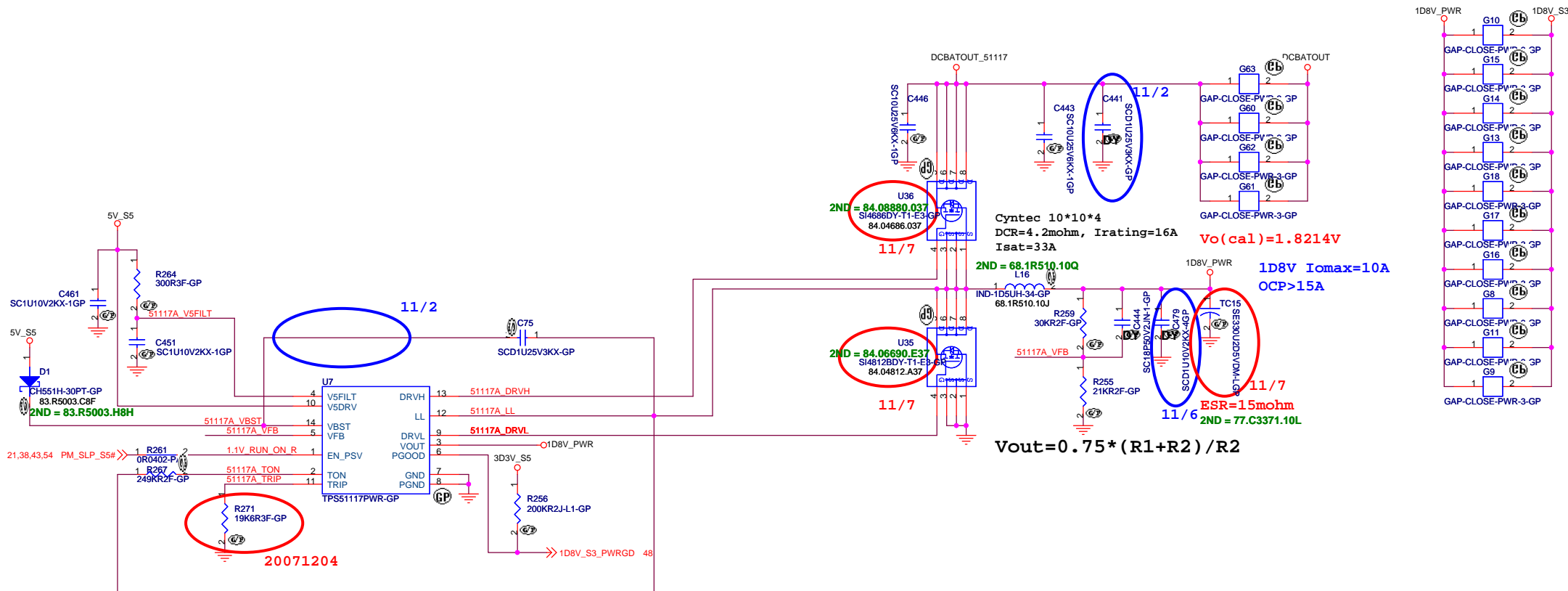
Brian  
ACOUSTIC NIOSE



<Core Design>

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Taipei Hsien 221, Taiwan, R.O.C.

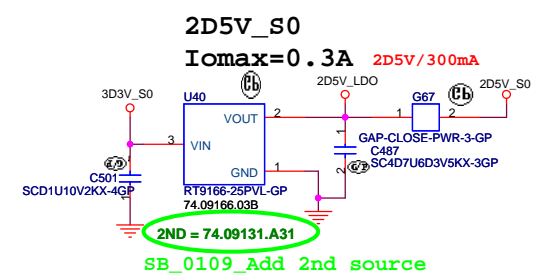
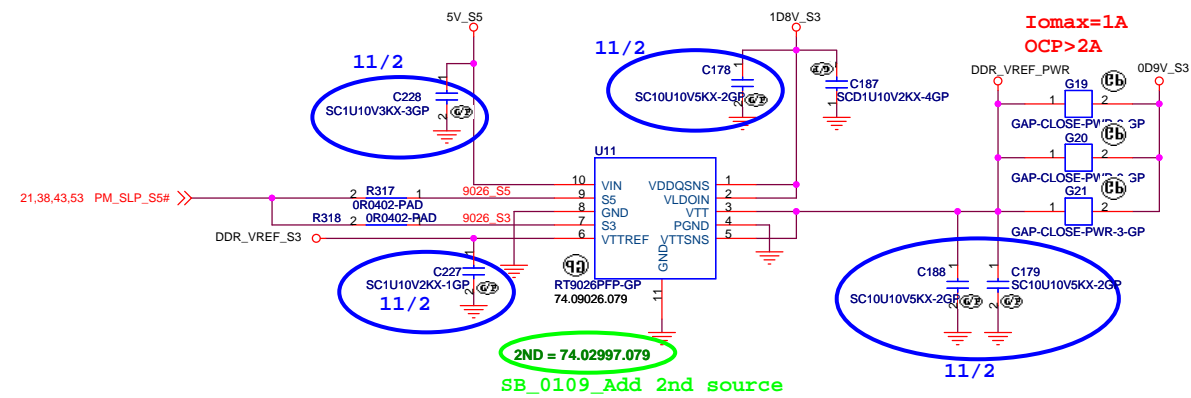
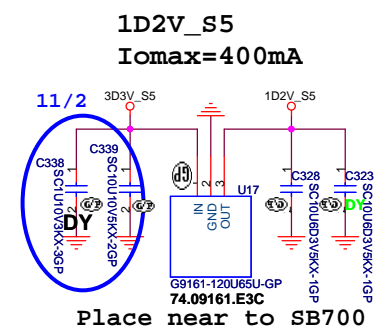
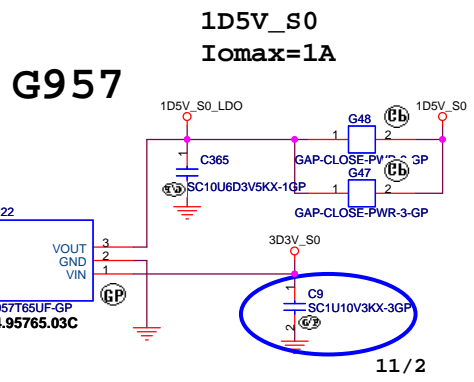
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Size	Document Number	Rev	
A3	Olan	-1	
Date:	Friday, April 18, 2008	Sheet	52 of 58



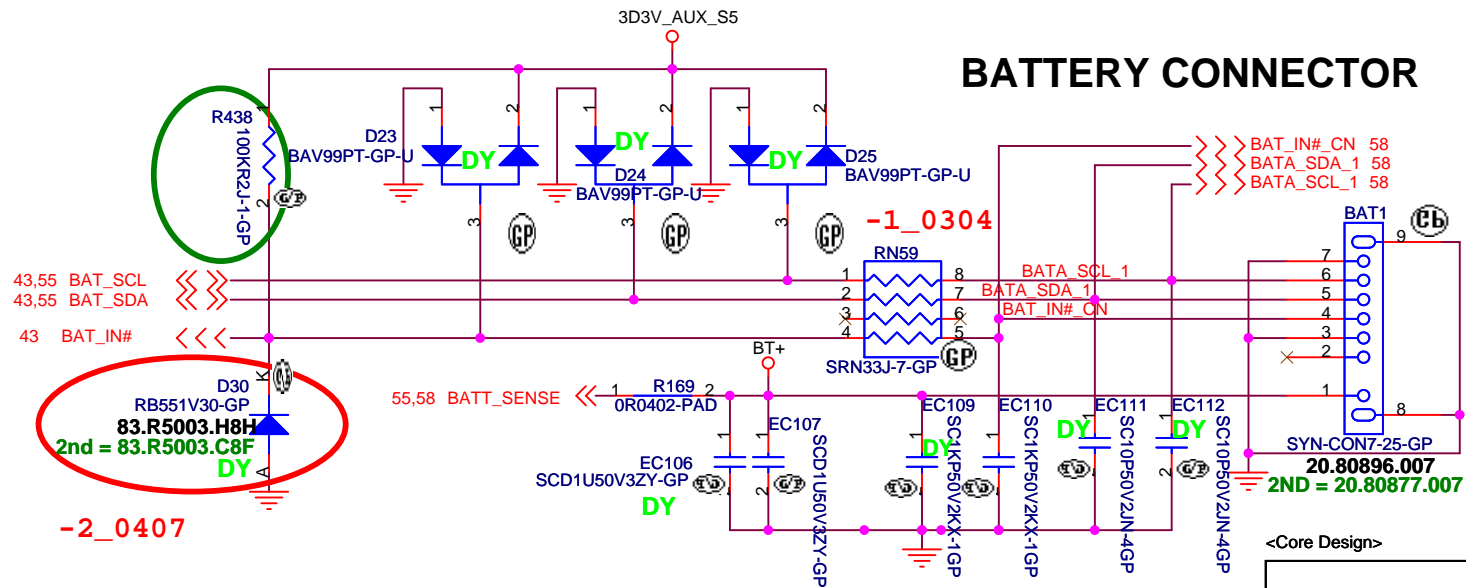
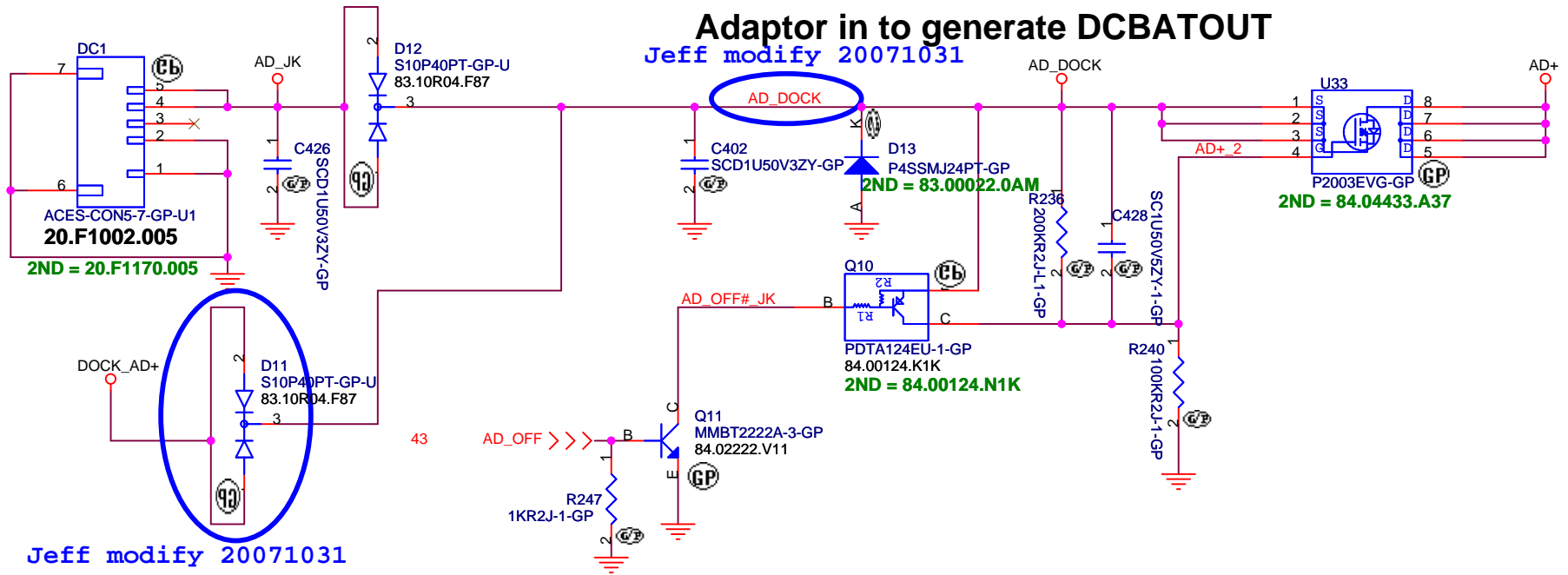
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 Taipei Hsien 221, Taiwan, R.O.C.

Title		
1D8V(TPS5117)		
Size	Document Number	Rev
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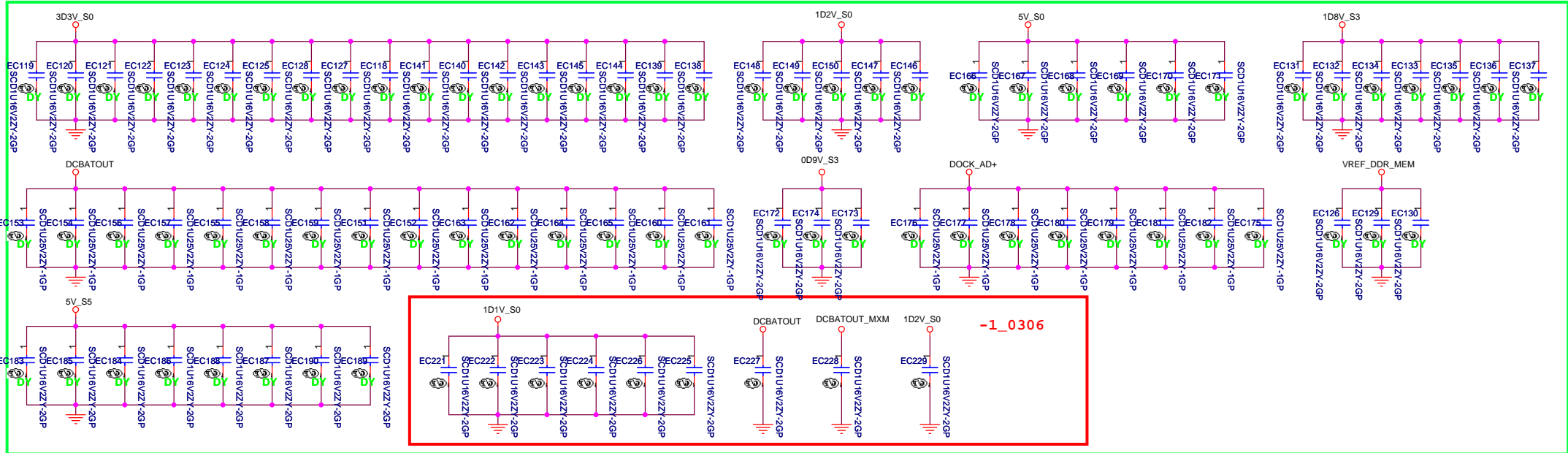
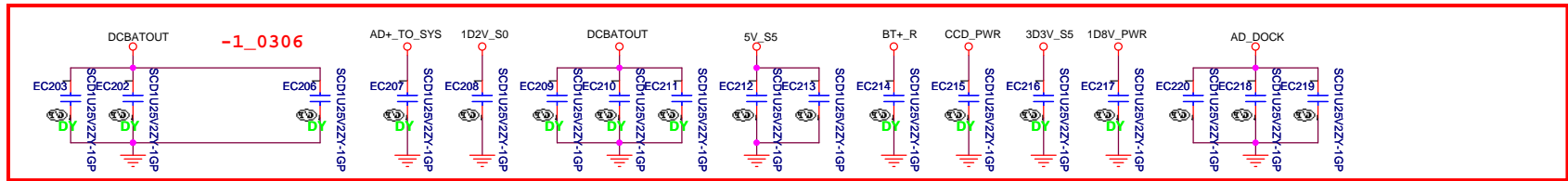
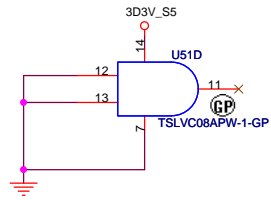




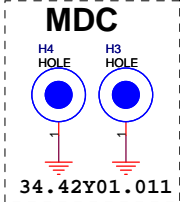


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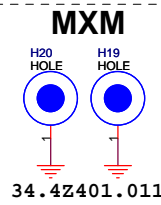
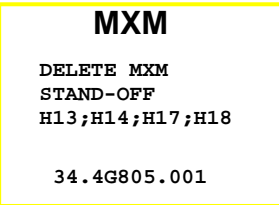
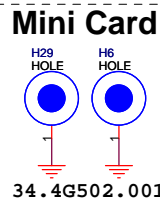
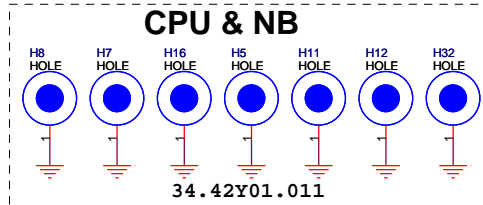


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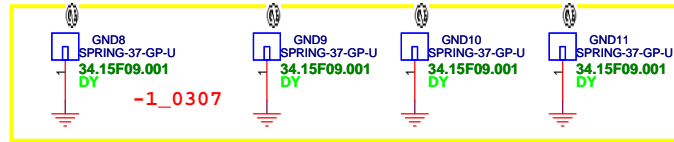


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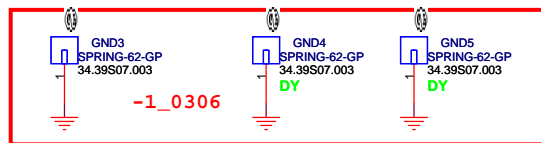
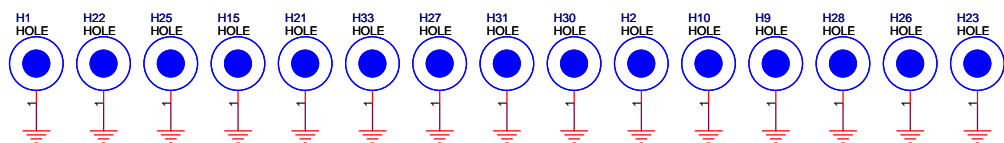
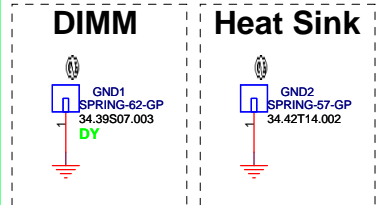
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**SPRING ON BOTTOM**



**Check test point**

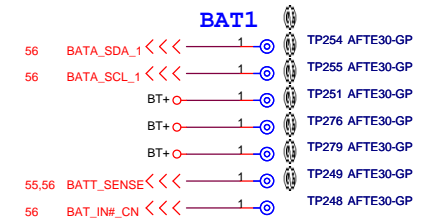
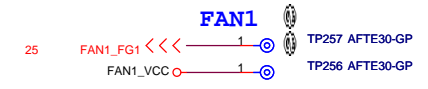
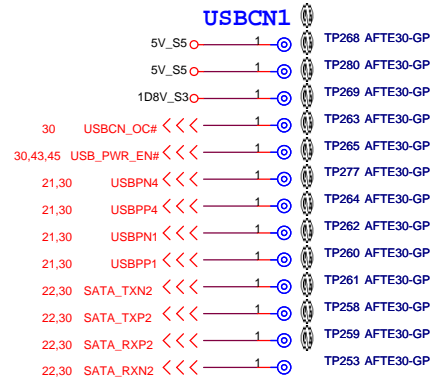
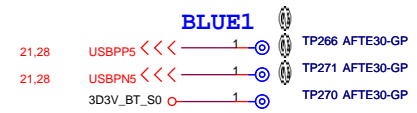
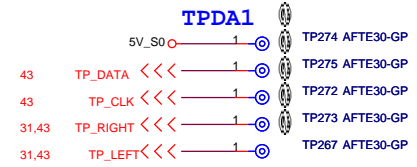
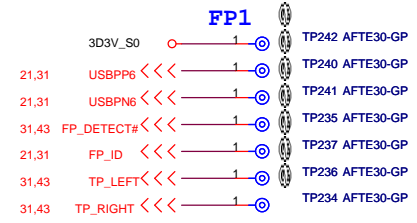
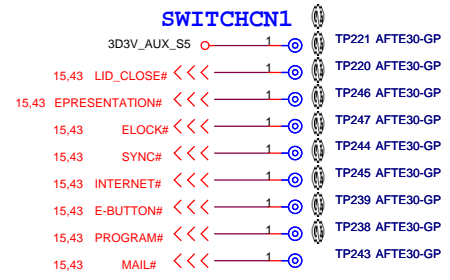
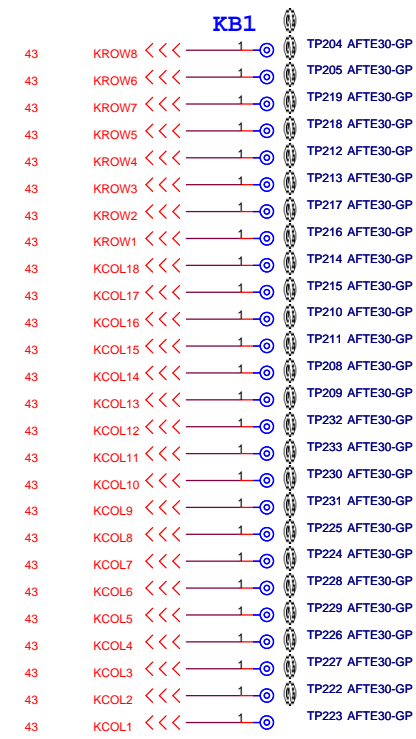
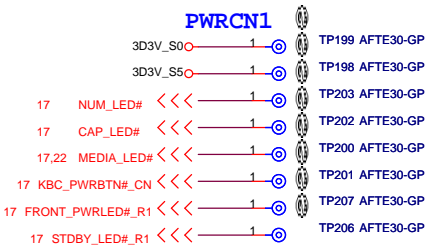
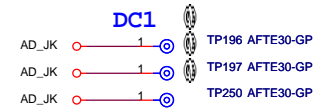
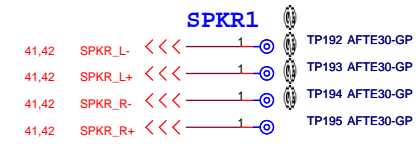
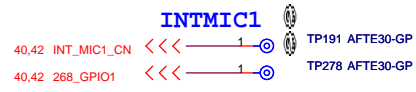
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- 3D3V\_AUX\_S5 TP4 TPAD30
- 3D3V\_S5 TP183 TPAD30
- 5V\_S5 TP186 TPAD30
- 21.43 PM\_PWRBTN# TP185 TPAD30
- 6.20 CPU\_PWRGD TP184 TPAD30
- 25.43 SS\_ENABLE TP181 TPAD30
- 6.20 CPU\_LDT\_RST# TP182 TPAD30

Test Point放在Dimm Door打開可量測處

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Title: **AFTE TP**

Size: A3 Document Number: **Olan** Rev: -2

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